

Prof: Abhishek Srivastava , CVEST

23 lectures

- 30 hours

Grading :

Assignment (3/4) : 10 %

Course Project : 20 %.

Quiz : 10 % + 10 %.

Midsem : 20 %.

Endsem : 30 %.

IEEE Journals — Solid State Society

JSSC (Journal Solid State Circuits)

ISSCC (Peak Journal)

Conferences: ISCAS, VLSID, VLSI Symposium

TWLSI, TCAS-II, MWSCAS, NEWCAS

VLSI Design

Verilog Textbooks: Brown's, J.Bhaskar,
Samir Patnikan .

Assignment Deadline: 6pm

VLSI Design

→ Topics:-

1) Intro to VLSI Design

2) CMOS Inverter

3) Multi-stage logic Design and Optimization

4) Other logic styles

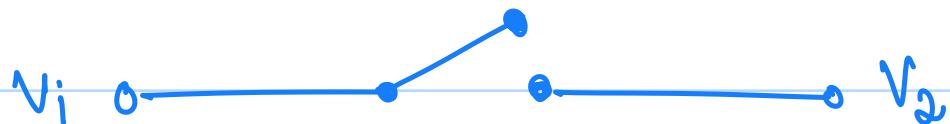
5) Intro. to HDL System Design.

• SCL - Semiconductor Complex Limited. Only fabrication facility in India. Can do upto 180 nm CMOS. Located in Mohali.
↳ Considered a very old technology.

• We will be using 180 nm technology in this course, since it is now open-source.

→ High impedance state :-

• When a node is not connected to any well defined voltage, it is said to be existing in a high impedance state.

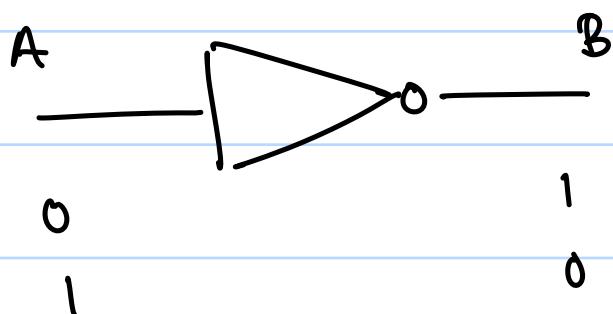


V_2 is in a high impedance state.

(Refer Weste & Harris MOS T Physics for
today's lecture)

5/8/25

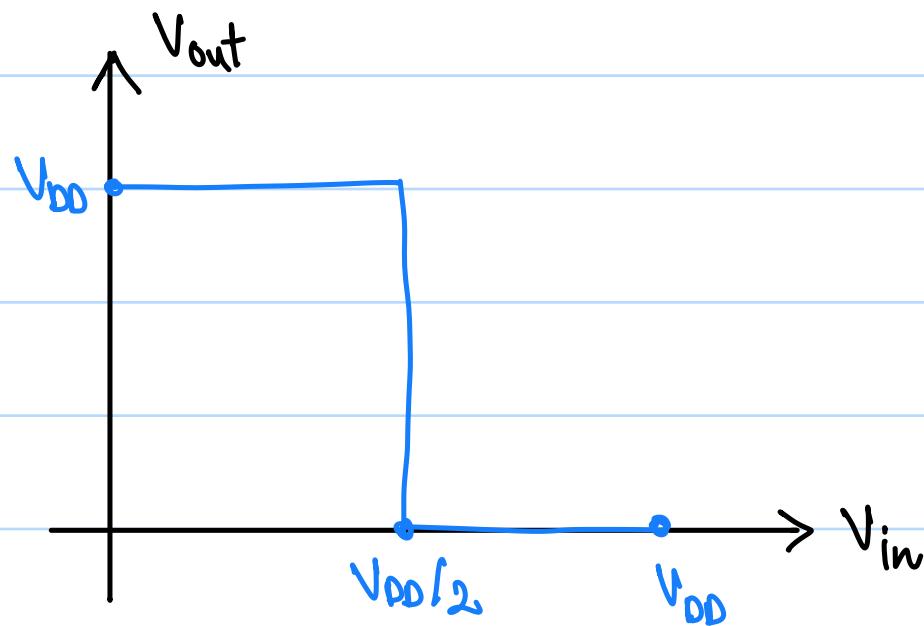
→ Inverter :-



A	B
0	1
1	0

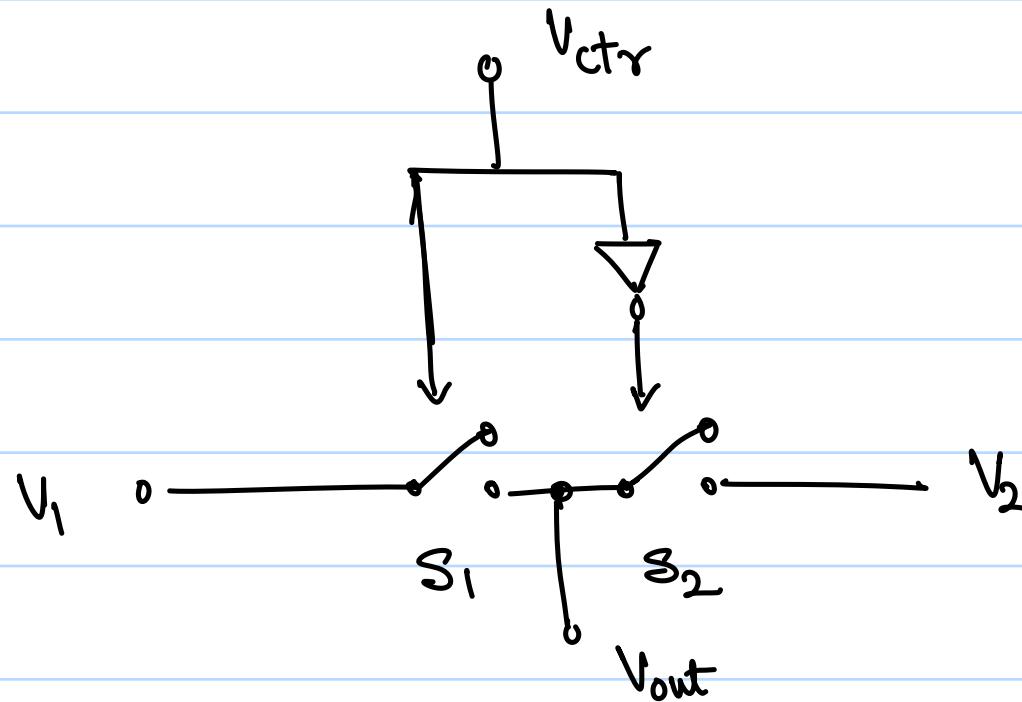
- 1 and 0 correspond to 2 different voltage levels.

• Ideally,



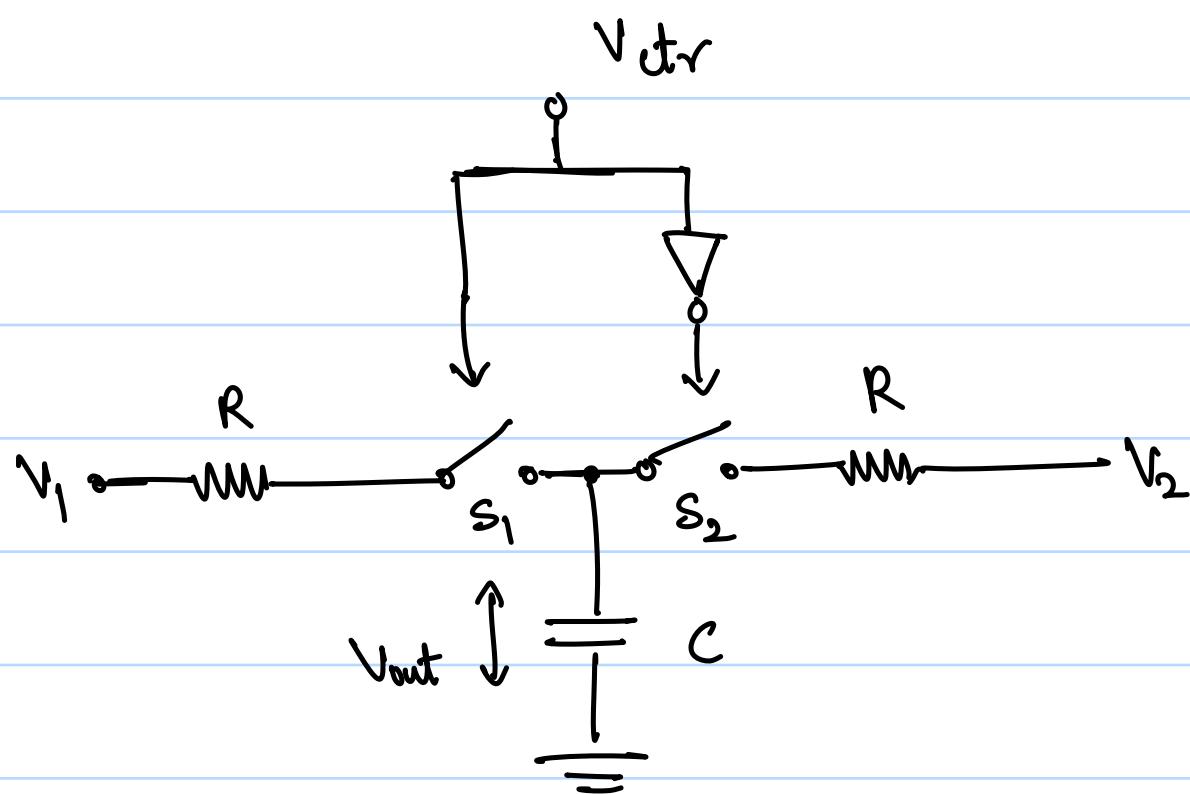
The above plot is termed as a VTC plot (Voltage Transfer Characteristics).

1)

Truth Table:

V_{ctr}	V_{out}
0	V_2
1	V_1

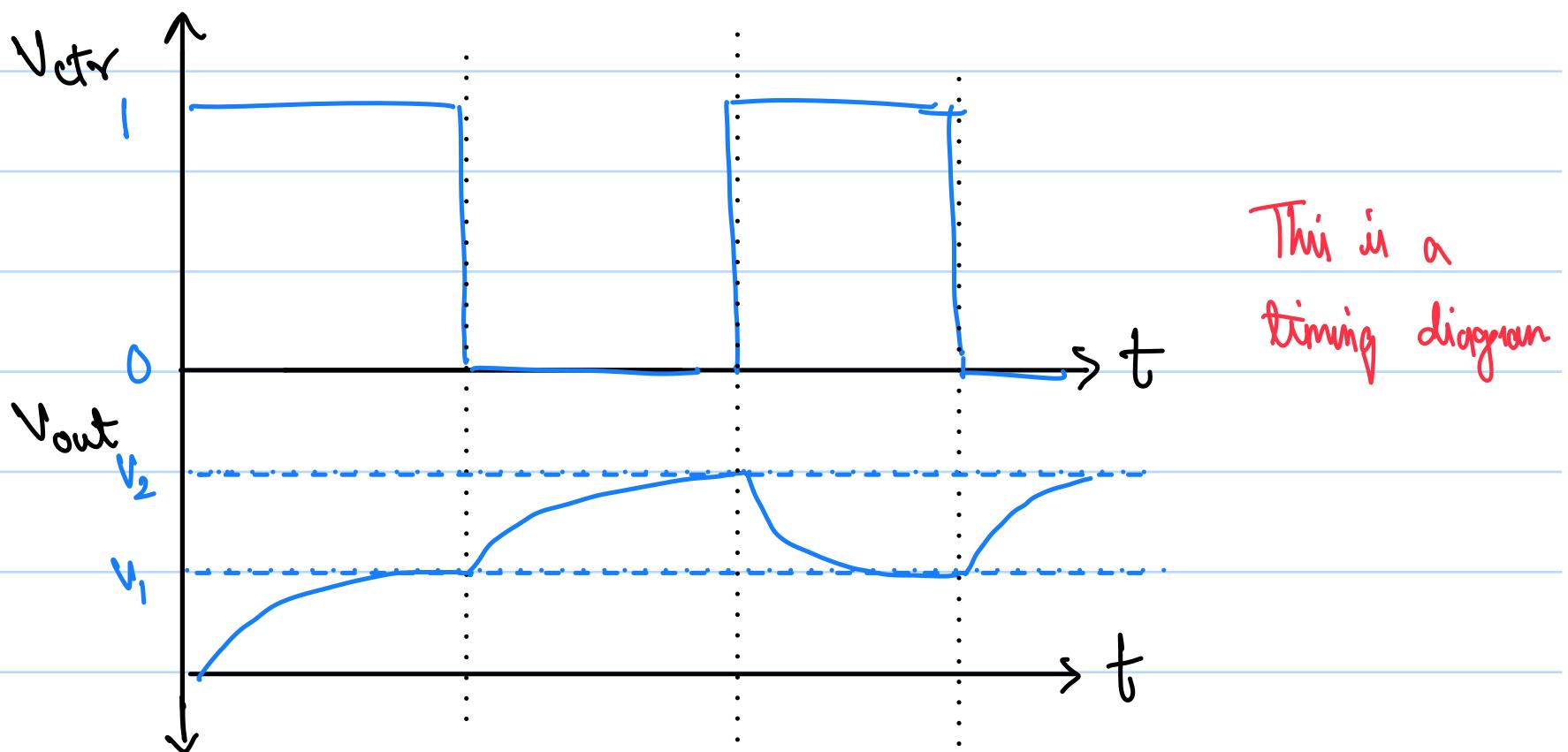
2)



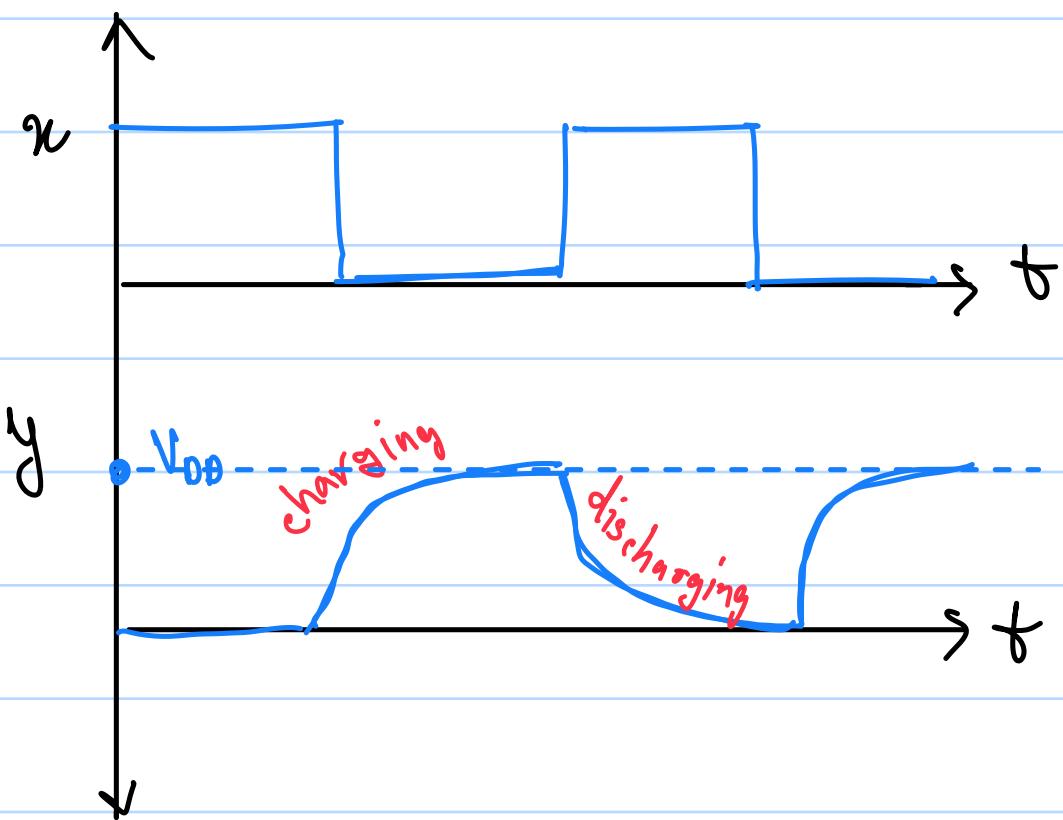
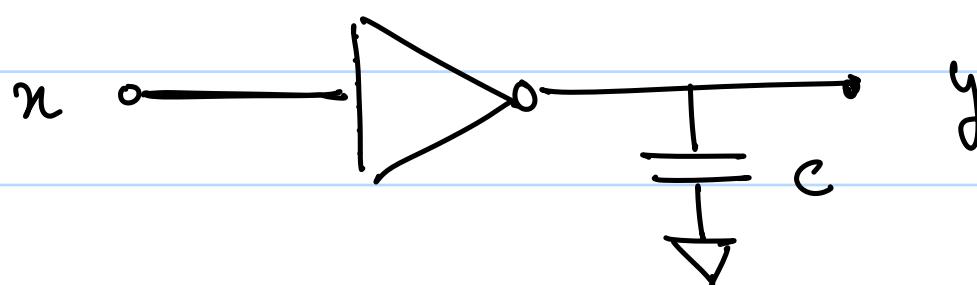
Here, $V_{out} = \begin{cases} V_2(1 - e^{-t/RC}), & V_{ctr} = 0 \\ V_1(1 - e^{-t/RC}), & V_{ctr} = 1 \end{cases}$

If there is no resistance involved, the current through the capacitor will be a Dirac impulse, infinite for an infinitesimal time.

($i = C \frac{dV}{dt}$, dt is very small)

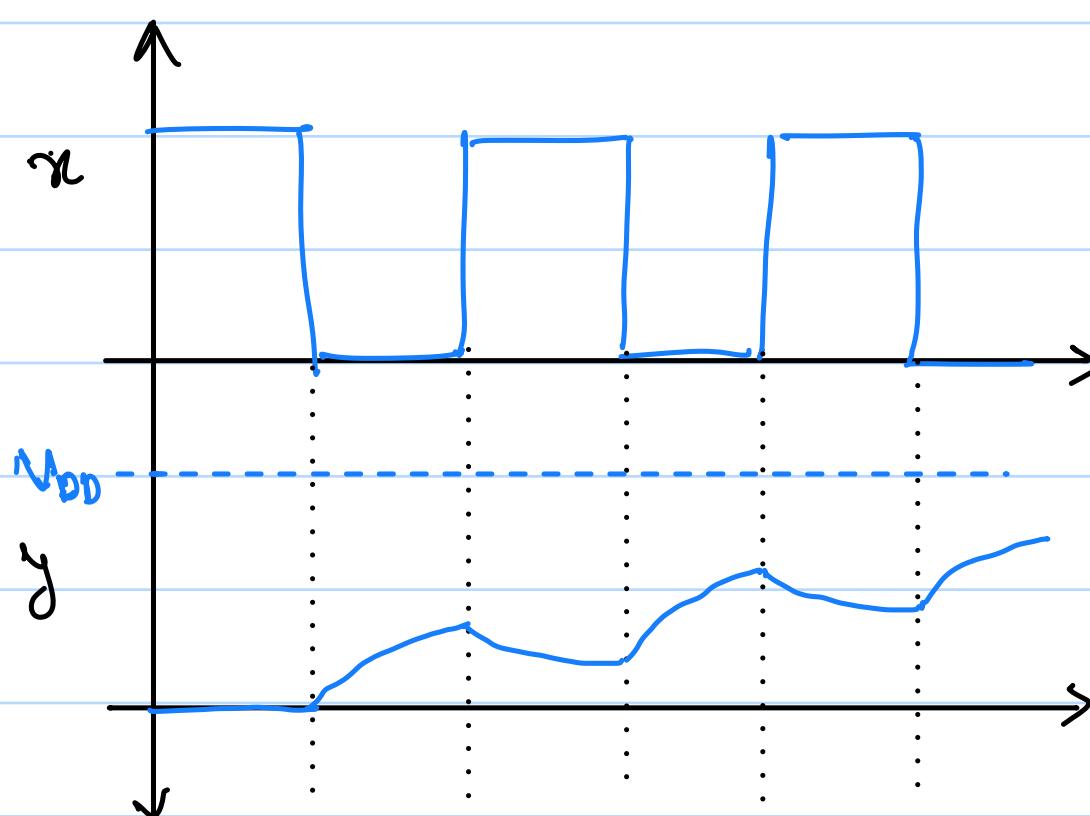


3)



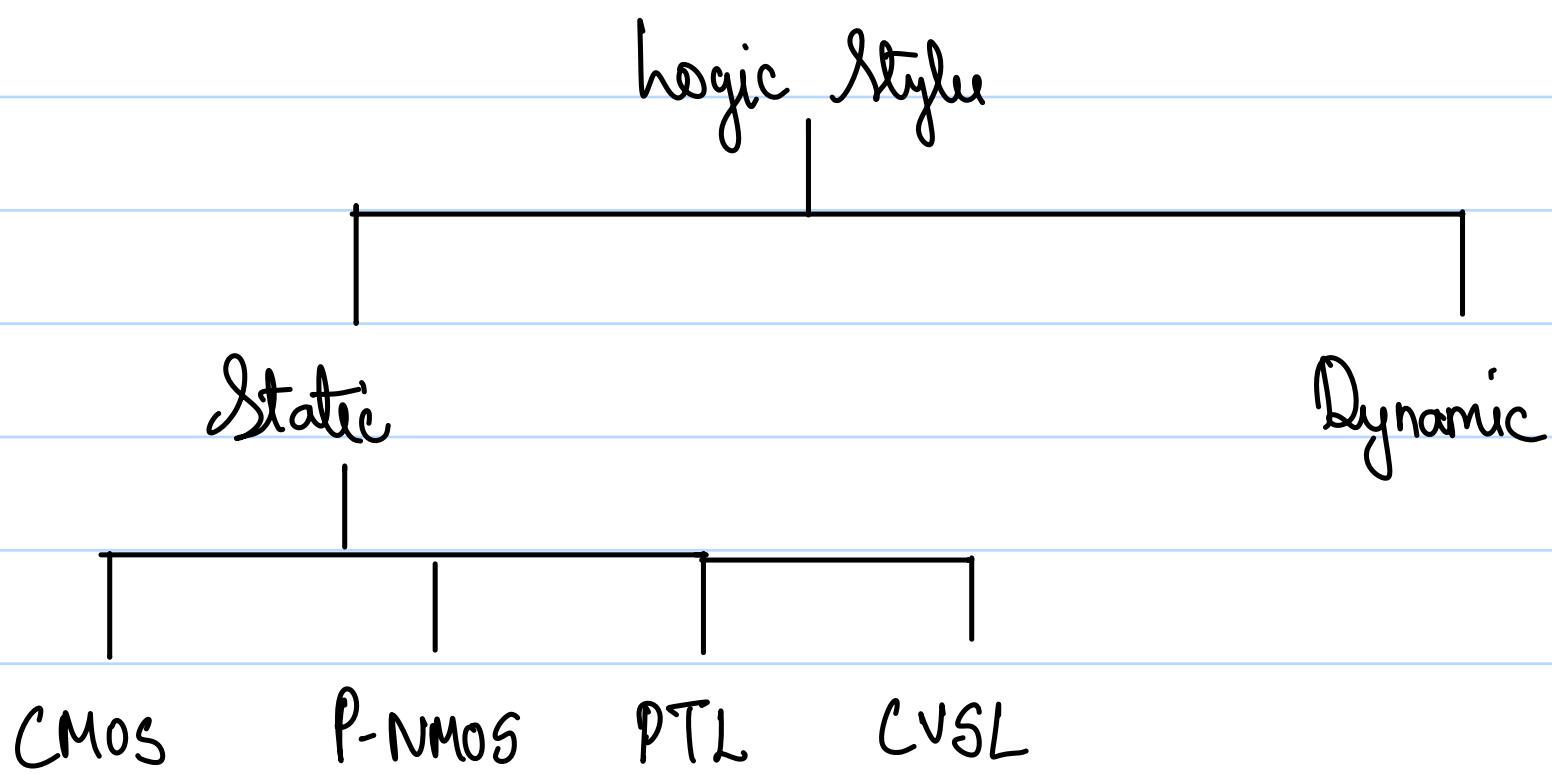
- The charging and discharging speeds of the capacitor are dependent on the RC / time constants of the circuit.

If RC is very large,



The capacitor is not fast enough to reach V_{DD} and zero, so information is lost.

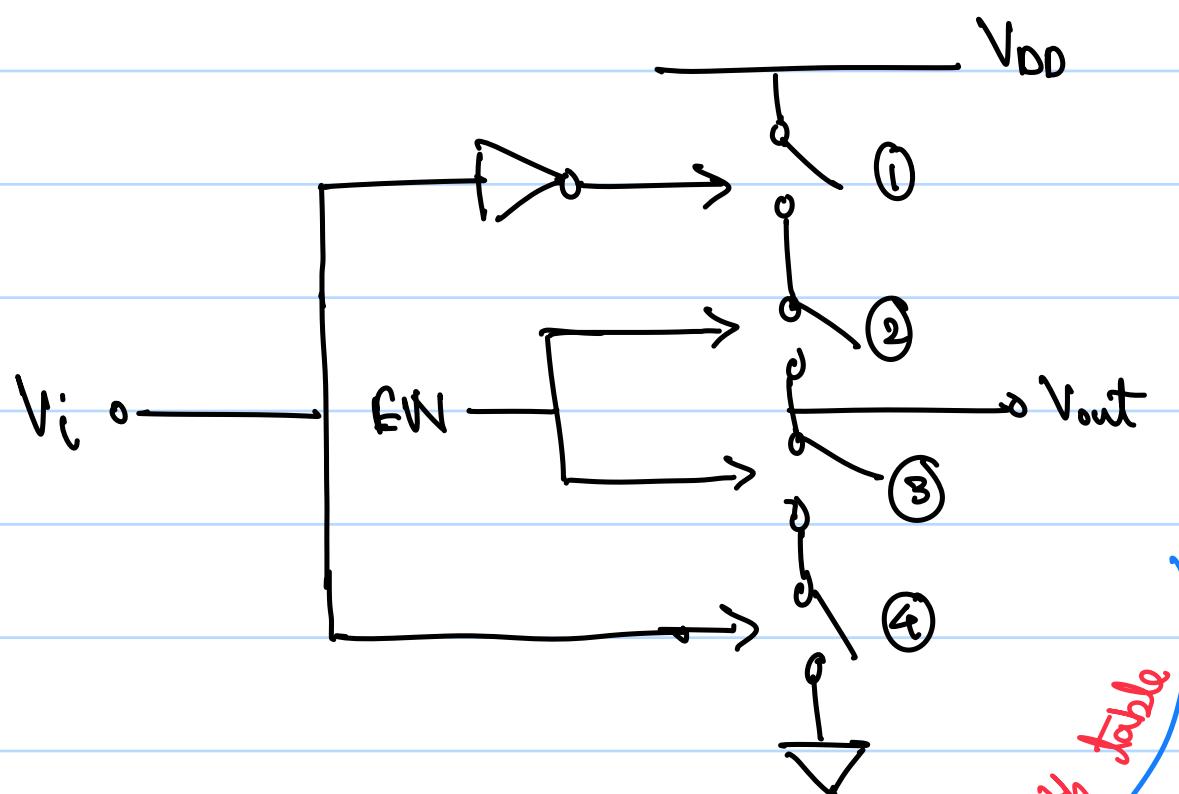
- Because of this, the RC parameters of the circuit must be fast enough to handle the input speed/frequency.



Circuit Design

Combinational Sequential Memory

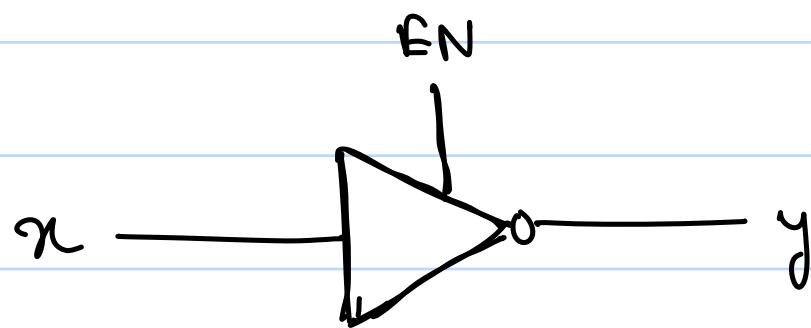
4)



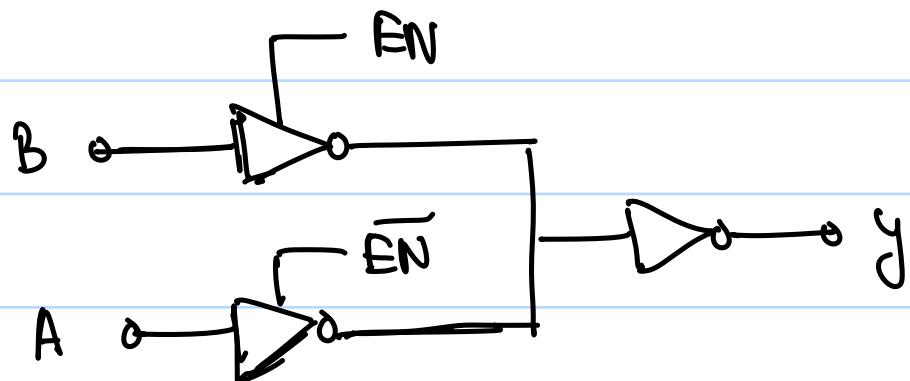
truth table

EN	V _i	V _o
0	0	Z
0	1	Z
1	0	V _{DD}
1	1	0

The above device acts like an inverter if $EN = 1$. This is the design of a tri-state inverter.



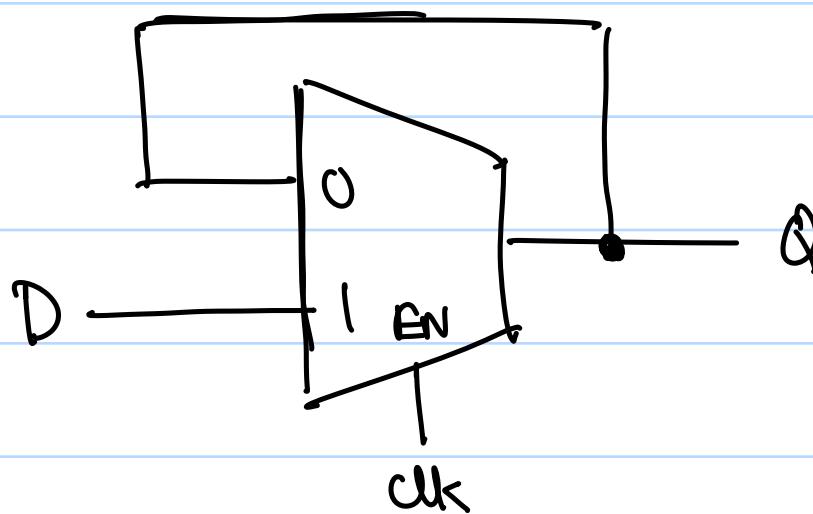
5)



Truth Table:

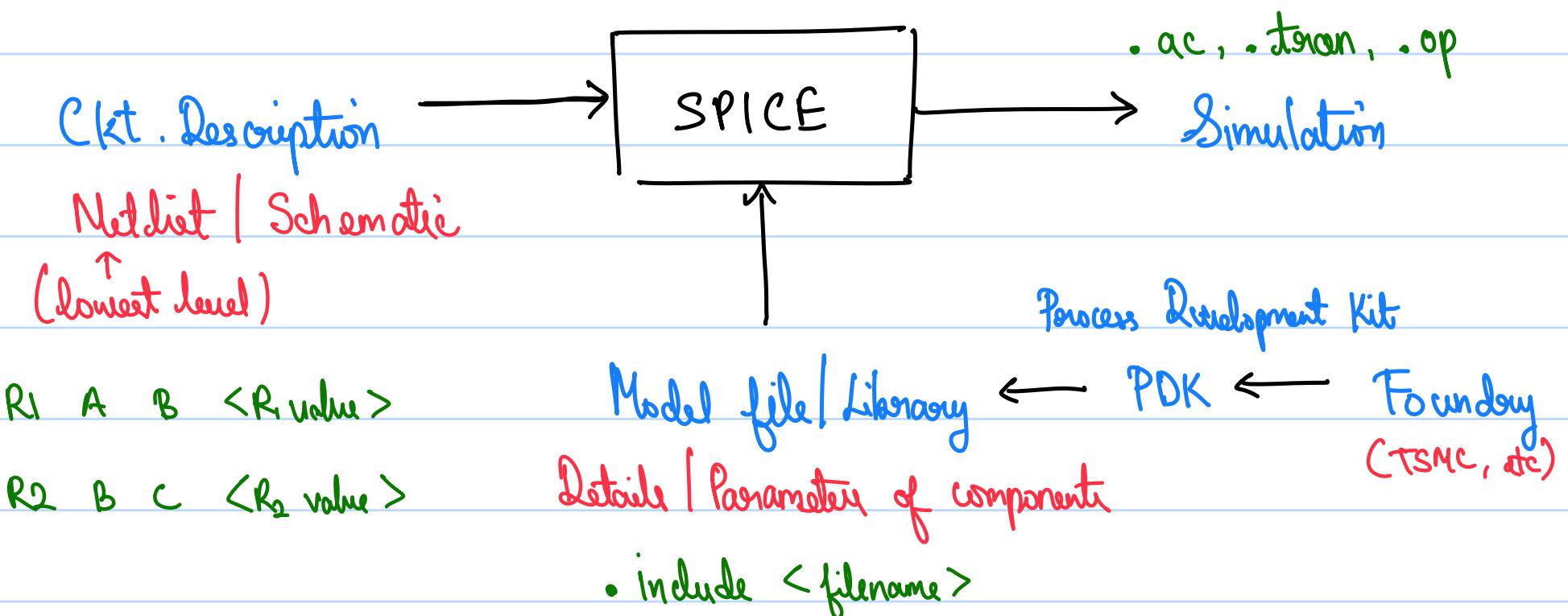
EN	Y
0	A
1	B

- Due to the high impedance, the output of one tri-state inverter will not be affected by the other, since one output is always z .
- The above device will act as a 2×1 MUX, which can be used to design devices like gates and latches.



Level Triggered D-Latch

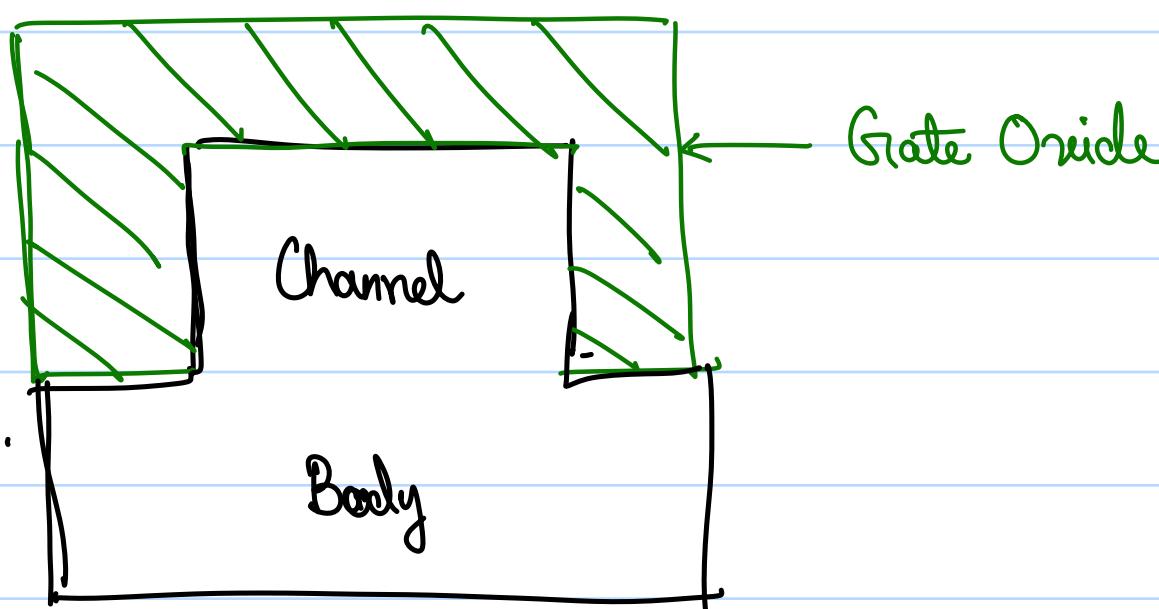
→ SPICE :-



→ Technology Node:

- To make a semiconductor chipset on a substrate, we use a "stencil" of the circuit layout.
- In the chipset, there are multiple metal layers on top of the substrate, to provide the interconnection between the MOSFETs.
- Within the MOSFETs, there are multiple dimensions that vary between them, depending on the usage of that MOSFET.
- The minimum of those dimensions, ie, minimum feature length among the MOSFETs is deemed as the "technology node" of that MOSFET. Usually minimum channel length.
- 3nm (N3) node - Retail products released
- 2nm (N2) node - Will release early next year.

- < 22nm - FinFETs are used instead of MOSFETs.



View of FinFET through Source/Drain

In FinFETs, the oxide wraps around the channel, enabling better inversion at a lower gate potential, better than MOSFETs.

- A14 - 1.4nm node } In development.
- A7 - 0.7nm node }

- 180nm is still widely used, in devices that do not require extremely high competition.

- Lower transistor size \Rightarrow lower cost per transistor.

- Clock Speed:

- Recently the clock speed of processes has saturated.

- Since the packing density has increased by a lot, the heat and leakage of the transistors have increased by a lot.

- These factors made it difficult for clock speed to improve as fast as the technology node.

→ Shannon's Expansion :-

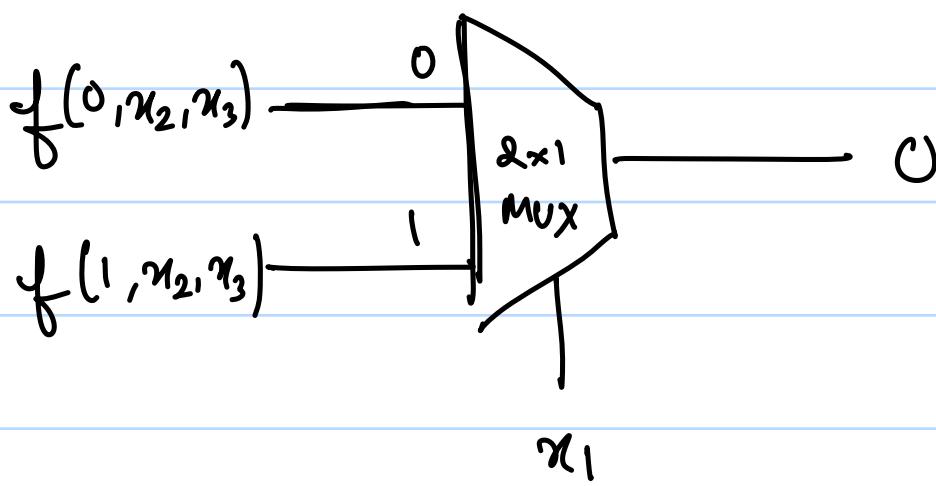
- For any function $f(x_1, x_2, x_3 \dots x_n)$,

$$f(x_1, x_2, x_3 \dots x_n) = x_1 f(1, x_2, x_3 \dots x_n) + \bar{x}_1 f(0, x_2, x_3 \dots x_n)$$

Example: Expand $f(x_1, x_2, x_3) = \bar{x}_1 \bar{x}_3 + x_1 x_2 + x_1 x_3$. w.r.t x_1

$$\Rightarrow f(x_1, x_2, x_3) = x_1 (x_2 + x_3) + \bar{x}_1 (\bar{x}_3)$$

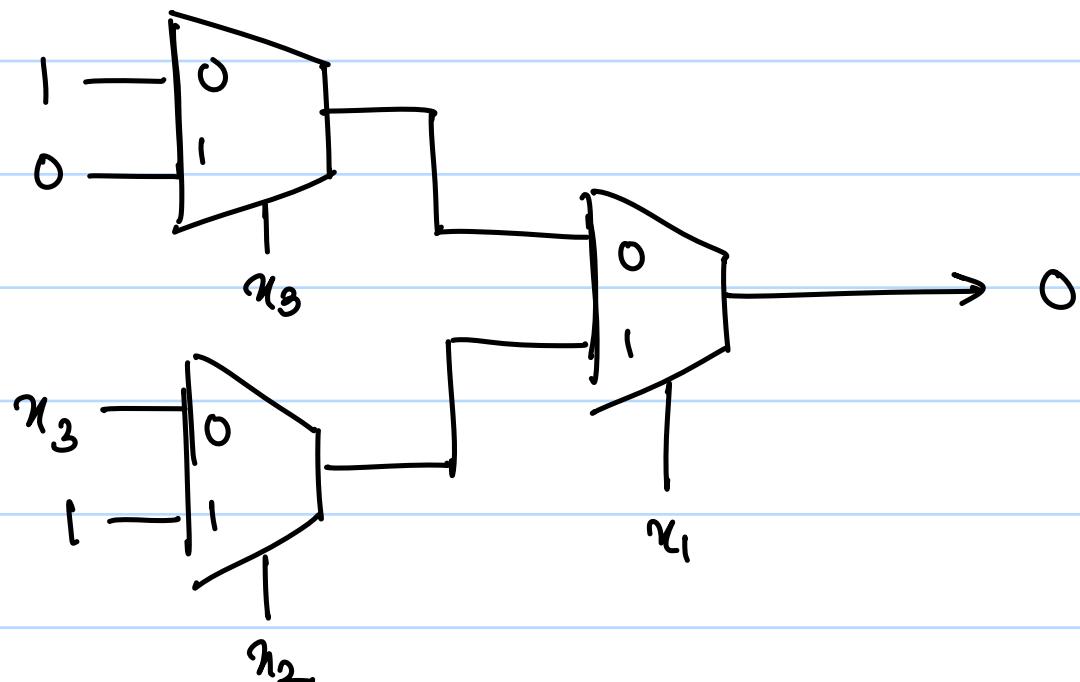
- If we expand the function in this way, we can use a 2×1 MUX to implement the function, using x_1 as the selection variable.



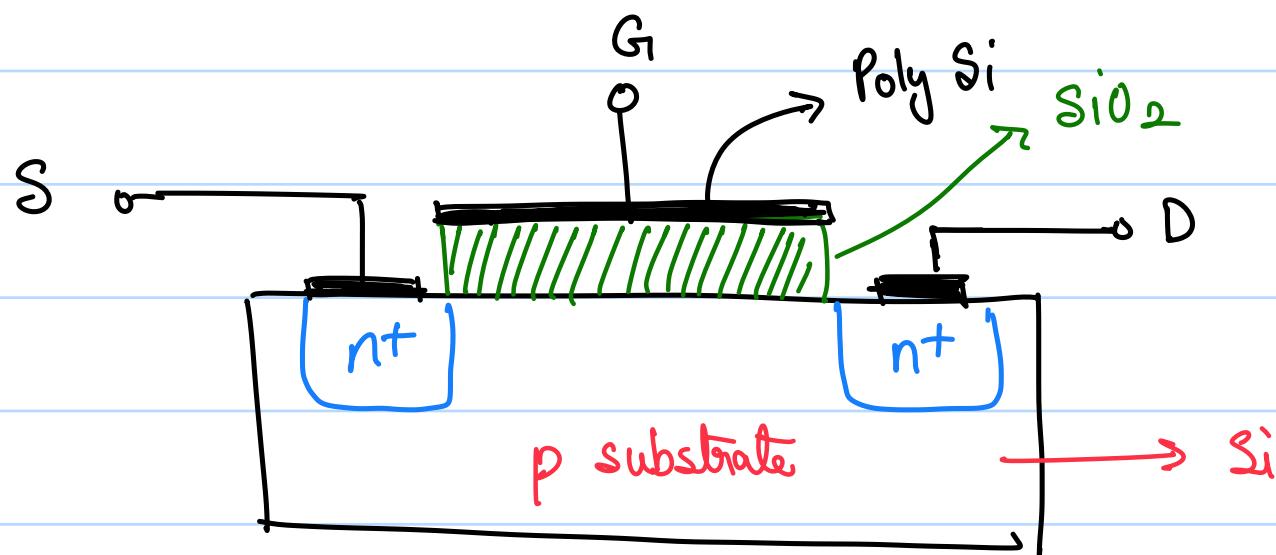
Example: Express the prev. function only using 2x1 MUXes.

$$\begin{aligned} f(x_1, x_2, x_3) &= \bar{x}_1 \bar{x}_3 + x_1 x_2 + x_1 x_3 \\ &= x_1 (x_2 + x_3) + \bar{x}_1 (\bar{x}_3) \end{aligned}$$

$$\begin{aligned} f(x_2, x_3) &= x_2 + x_3 \\ &= x_2(1) + \bar{x}_2(x_3) \end{aligned}$$



→ MOSFETs :-

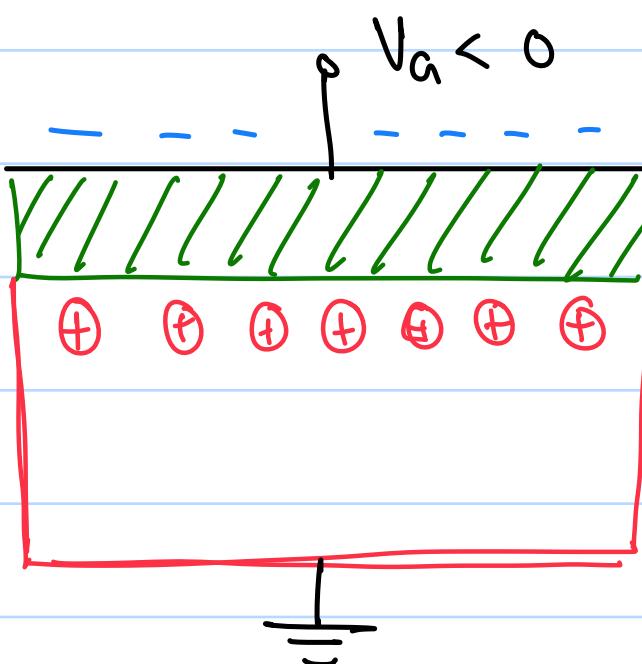


NMOS Structure

- Poly silicon is used in the gate terminal to simplify the manufacturing process, since silicon is the major element of a MOSFET.

- Let S and D be grounded and ,

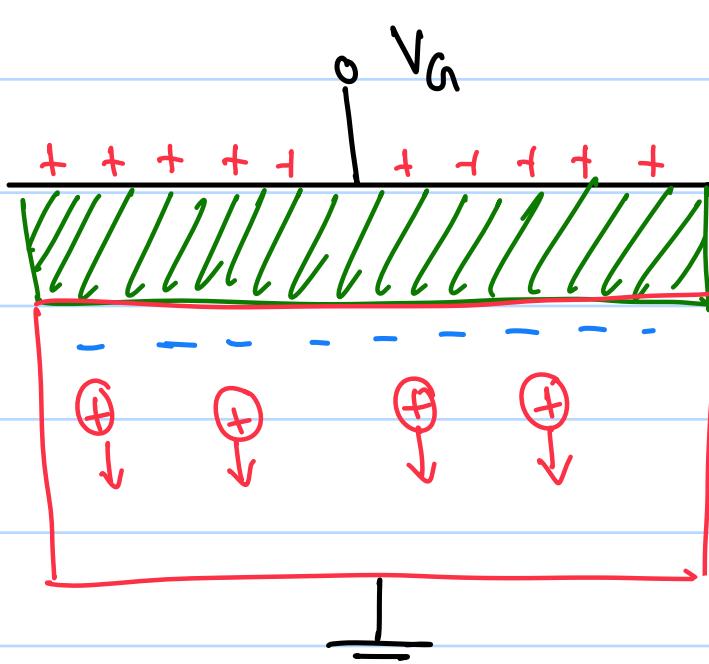
1) $V_G < 0$



holes are attracted towards the gate

- This is accumulation mode of operation .

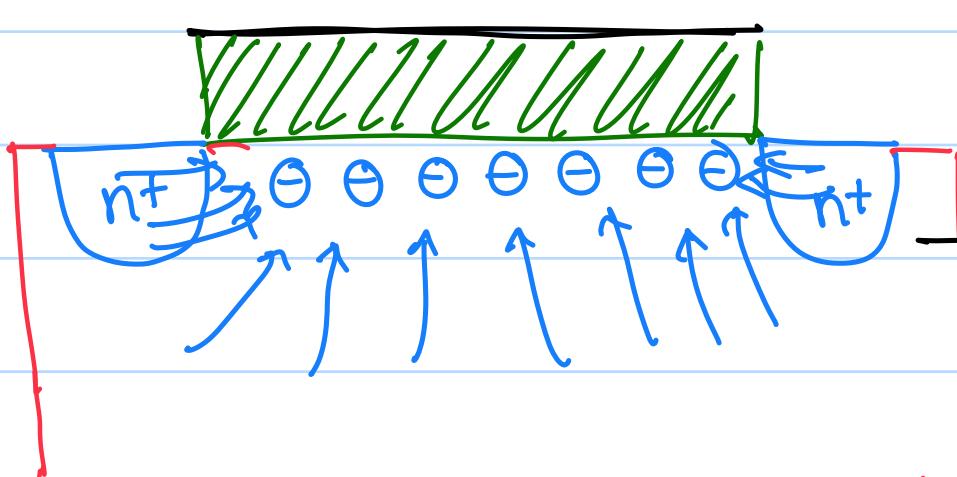
2) $V_G > 0$



holes go away from gate, leaving -ve charge .

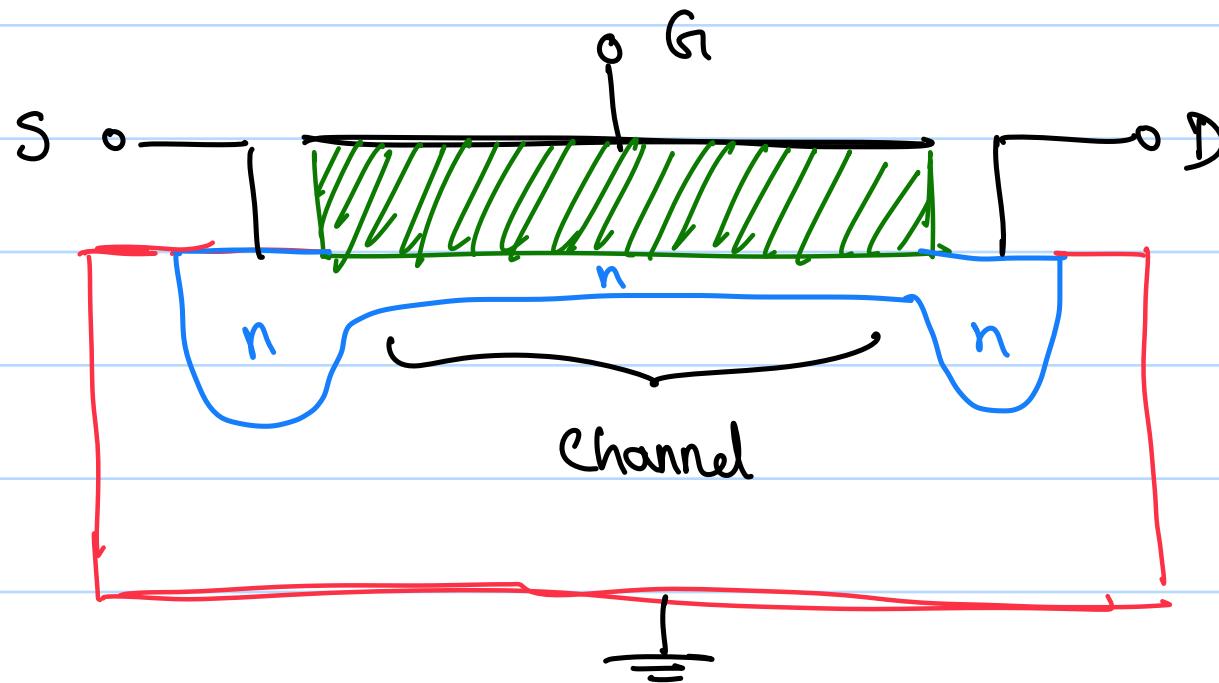
- This is depletion mode of operation .

3) $V_G \gg 0$



electrons are attracted from the substrate and (majorly) from S and D

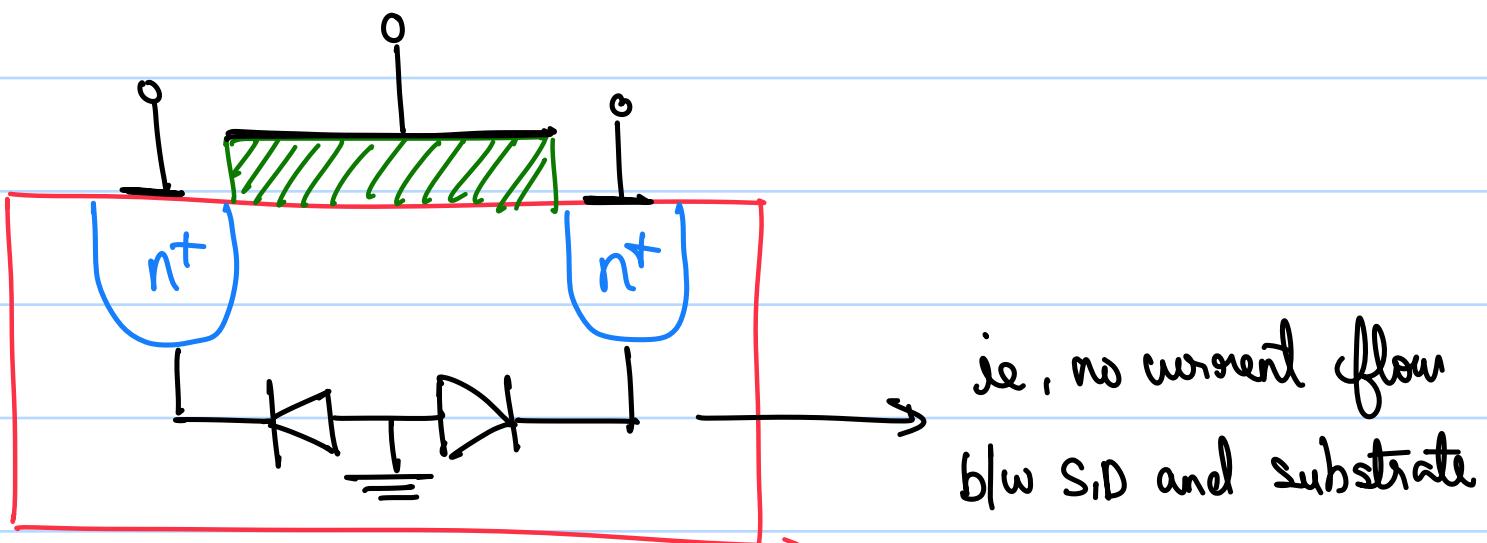
- The surface of the p-substrate becomes dominated by electrons, ie, becomes n-type.



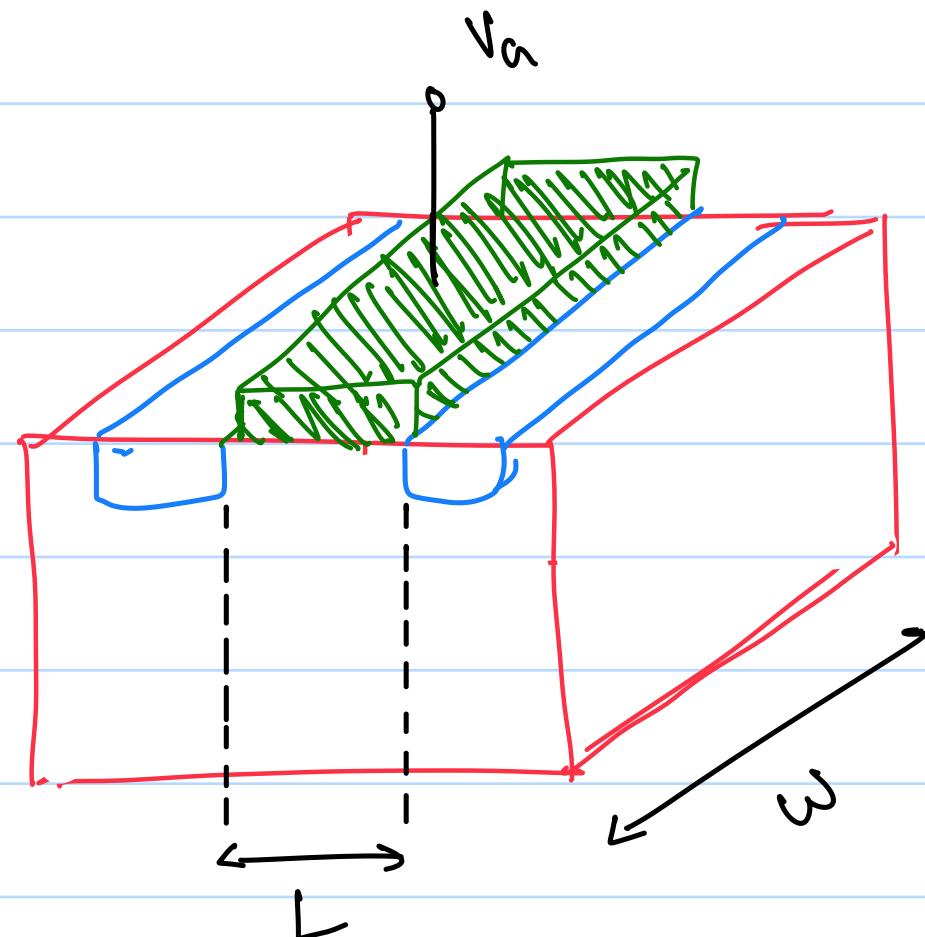
- This is inversion mode of operation.

- If n_e at surface $< N_A$ (hole conc. of substrate), it is weak inversion / subthreshold mode.

- If n_e at surface $\geq N_A$, it is strong inversion. The min. gate voltage to attain strong inversion is V_{TH} (threshold voltage)

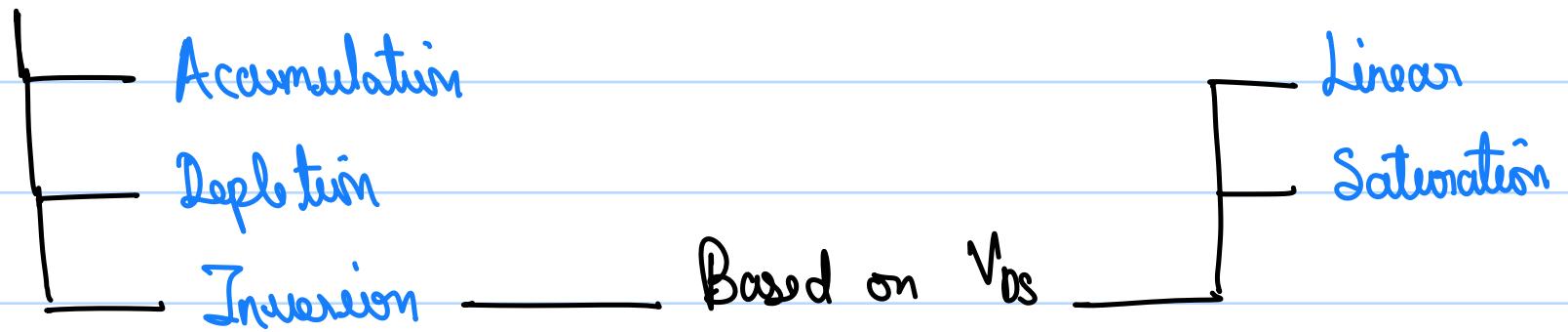


• 3D View:-



Since the n-channel is not perfectly conductive, it has some resistance to it, depending on the dimensions L and w.

Based on V_{AS}



1) $V_{AS} \leq 0 \Rightarrow I_D = 0 + V_{DS}$. Accumulation mode has zero channel.

2) $0 < V_{AS} < V_{TH} \Rightarrow I_D \approx I_{D0} e^{\frac{V_{AS}-V_{TH}}{nVt}}$. V_t - thermal voltage.

Subthreshold conduction.

3) $V_{AS} > V_{TH}$ & $V_{DS} < V_{AS} - V_{TH} = V_{ov}$. (Overshoot voltage)

$$I_D = \frac{1}{2} \mu_n C_o \frac{w}{L} \left(2V_{ov}V_{DS} - \frac{V_{DS}^2}{2} \right) \rightarrow \text{Linear Mode of Opn.}$$

If $V_{DS} \ll V_{OV}$,

$$I_D = \left(\mu_n C_o x \frac{W}{L} V_{OV} \right) V_{DS}$$

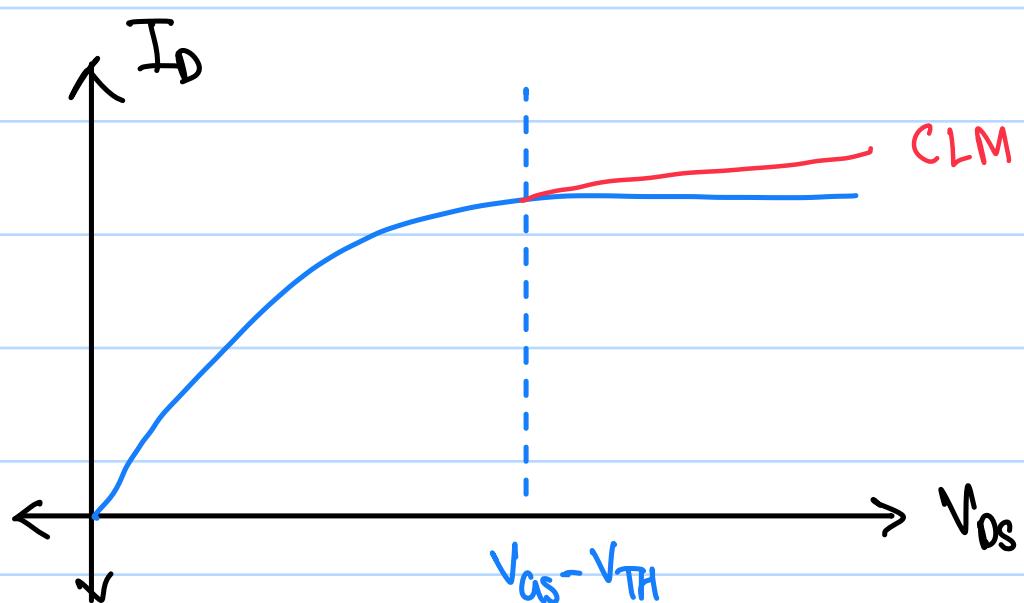
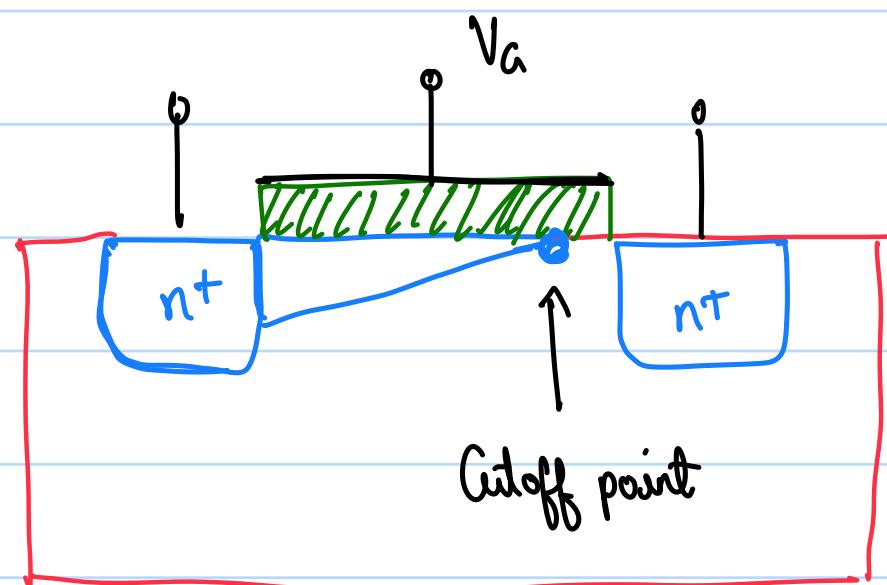
$$\Rightarrow R = \frac{1}{\mu_n C_o x \frac{W}{L} V_{OV}}$$

4) $V_{GS} > V_{TH}$, $V_{DS} \geq V_{GS} - V_{TH}$

$$\Rightarrow V_{GS} - V_{DS} \leq V_{TH}$$

$$\Rightarrow \underline{V_{DS} \leq V_{TH}}$$

Since $V_{DS} \leq V_{TH}$, the channel will cease to exist near the drain, since potential at the point will be lesser than threshold.



Beyond the cutoff point, the charge density is very low (depletion mode). Let linear charge density there be Q_d . $Q_d \approx 0$.

$$dQ = Q_d \cdot dx$$

$$\frac{dQ}{dt} = Q_d \frac{dx}{dt}$$

$$= I = Q_d V_d$$

$$= V_d = \frac{I}{Q_d} \Rightarrow \lim_{Q_d \rightarrow 0} \frac{I}{Q_d}$$

$\therefore V_d \rightarrow \infty$ for finite I .

\therefore The electrons are swept almost instantaneously across the cutoff point into the drain.

$$I_{DS} = \begin{cases} \mu n C_o \frac{W}{L} (2(V_{GS} - V_{TH})V_{DS} - \frac{V_{DS}^2}{2}), & V_{GS} > V_{TH}, V_{DS} < V_{ov} \\ \frac{1}{2} \mu n C_o \frac{W}{L} (V_{GS} - V_{TH})^2, & V_{GS} > V_{TH}, V_{DS} > V_{ov} \\ 0, & V_{GS} \ll V_{TH} \\ I_{DSS} e^{\frac{V_{GS}-V_T}{nVt}} [1 - e^{\frac{V_{DS}}{4}}], & V_{GS} < V_{TH} \end{cases}$$

(Subthreshold leakage)

• PMOS:

$$I_{SD_{PSI}} = \frac{1}{2} \mu p C_o \frac{W}{L} [V_{SA} - |V_T|]^2$$

$$V_{SA} \geq |V_T| \quad \&$$

$$V_{SD} \geq V_{SA} - |V_T|$$

$$I_{SD\text{plin}} = \mu_p C_{ox} \frac{W}{L} \left[(V_{SD} - |V_T|) V_{SD} - \frac{V_{SD}^2}{2} \right]$$

• Second-Order Effects :-

1) Channel Length Modulation :-

Since the cutoff point moves further towards the source, as V_{DS} increases, I_D actually increases with V_{DS} even during saturation.

$$I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2 (1 + \lambda V_{DS})$$

λ CLM Parameter

$$\lambda V_{DS} = \frac{\Delta L}{L}$$

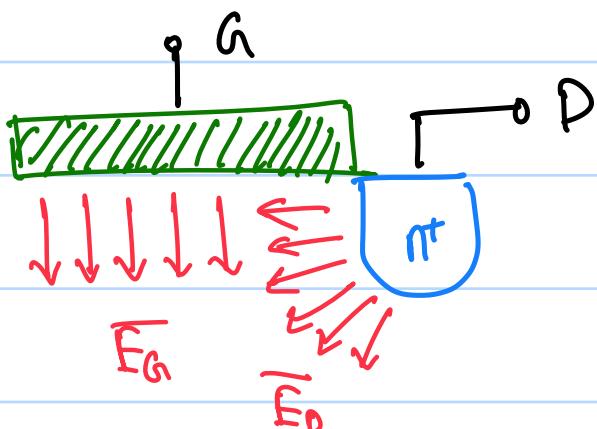
2) Body Biasing :-

If V_{BS} is increased, the threshold voltage of the MOSFET is decreased.

$$V_{TH} = V_{TH0} + \sqrt{2\psi_s + V_{SB}} - \sqrt{2\psi_s}$$

3) Drain Induced Barrier Lowering :-

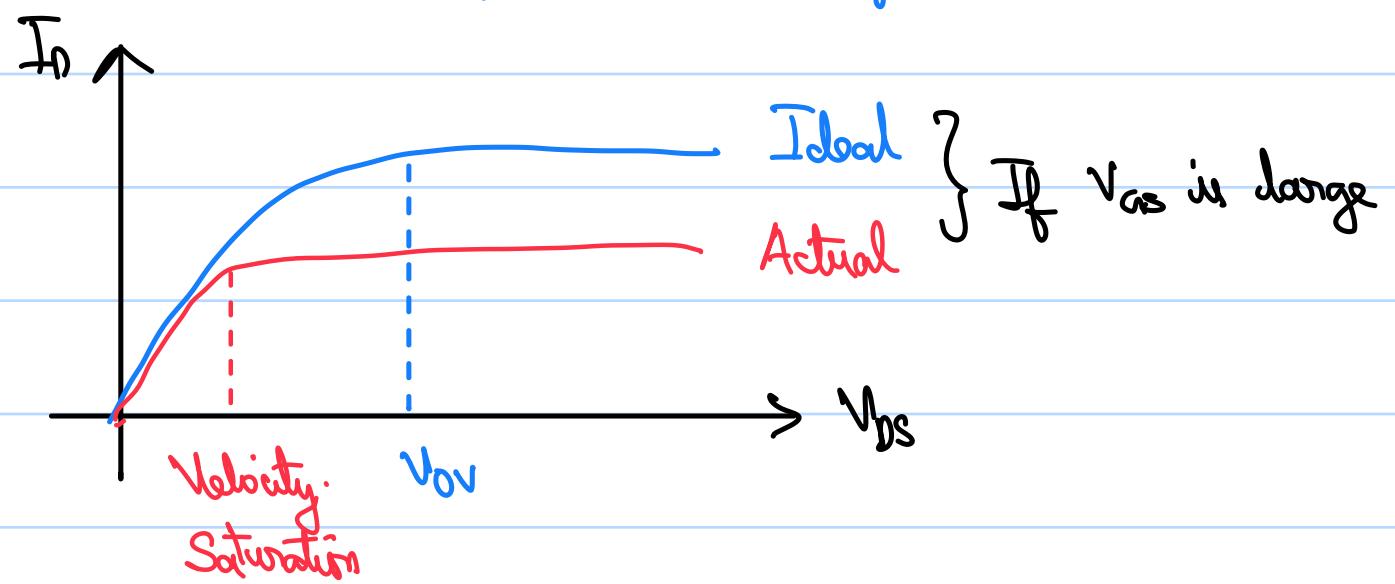
In short channel MOSFETs, the drain voltage will aid in the inversion of the channel.



Because of this aid, the threshold voltage of the MOSFET will be lower.

4) Velocity Saturation :-

For each channel, there is a certain V_d at which mobility degradation occurs due to scattering of the charge carriers. Prominent if V_{as} is large.

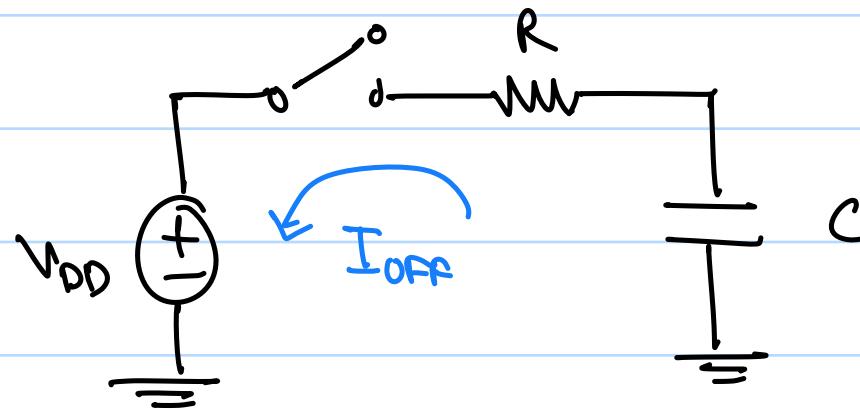


If V_{as} is low, overdrive voltage is attained before velocity saturation, so the effect is not visible.

• Switch I_{ON}, I_{OFF} :-

- I_{ON} : Current through the switch when it is in the ON position.
- I_{OFF} : Current through the switch when it is in the OFF position.
- Ideally I_{OFF} should be zero, but it is non-zero due to effects like leakage.

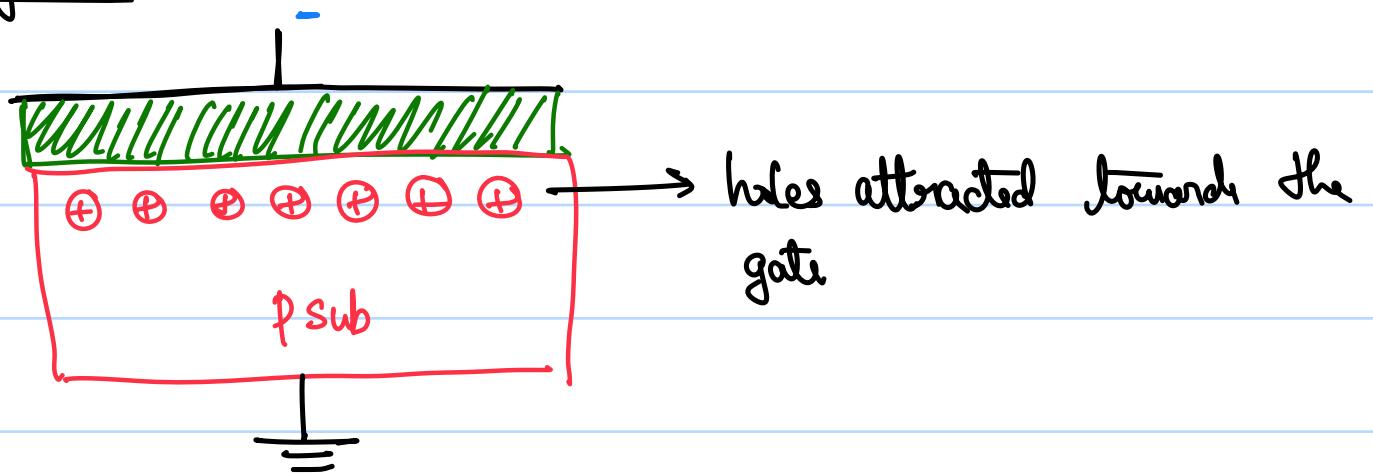
- t_{hold} : Time taken for a capacitor to discharge in an RC circuit when the switch is OFF.



$$\text{For a good circuit, } t_{\text{hold}} \geq \frac{1}{2} \frac{C V_{DD}}{I_{\text{off}}}$$

- o MOS Capacitor:

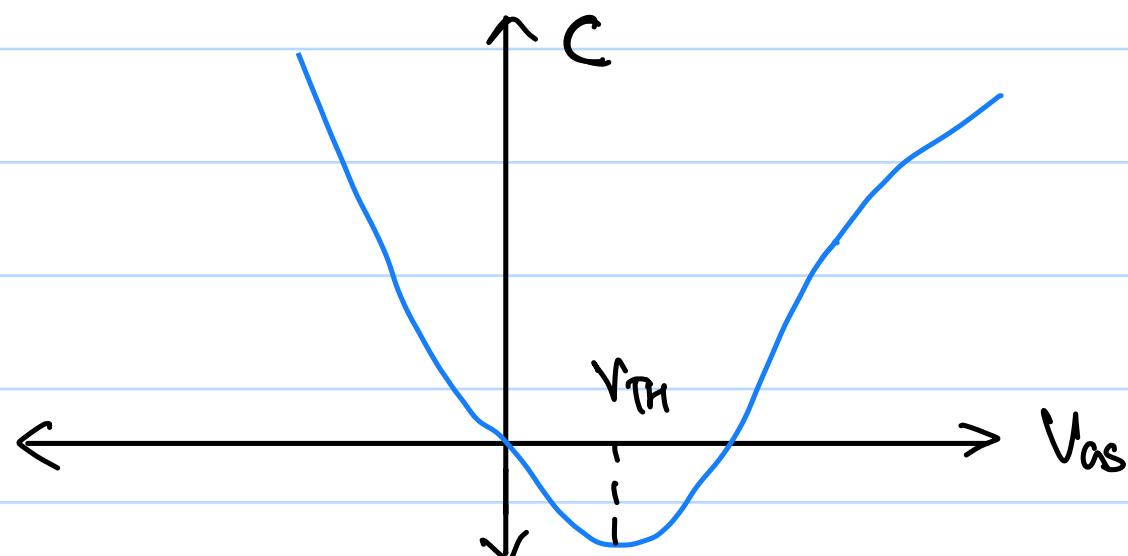
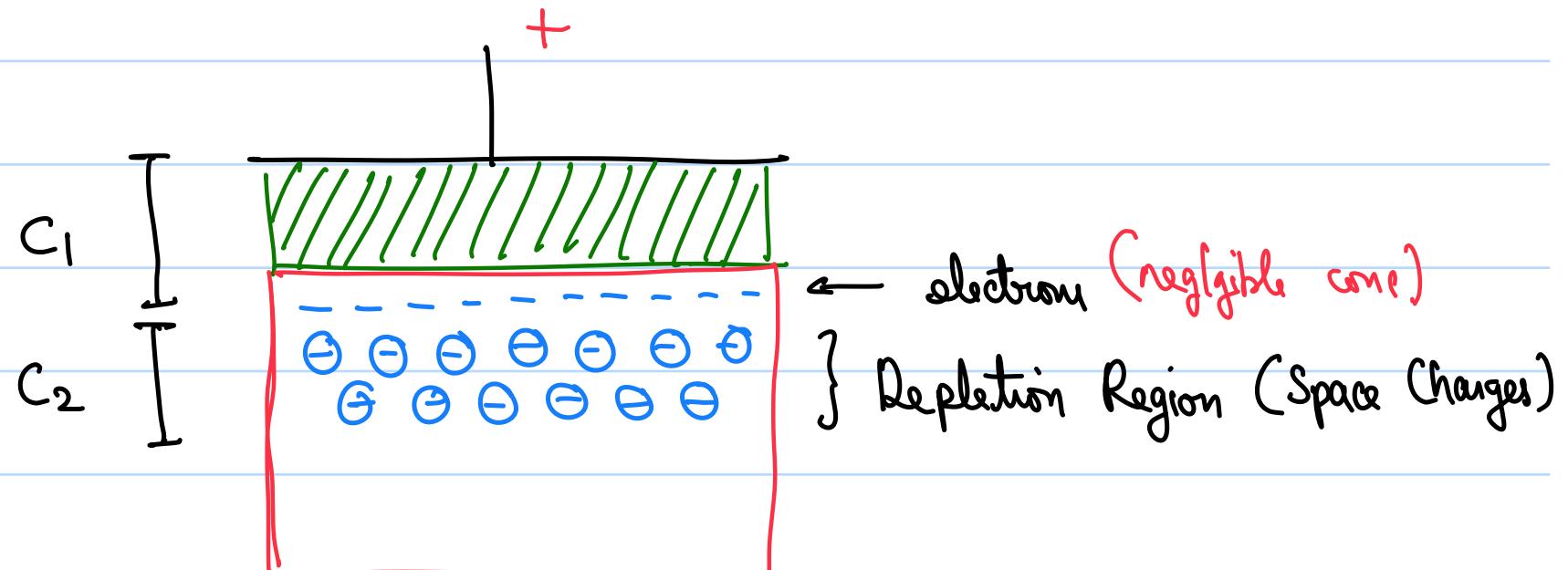
- i) Accumulation Region:-



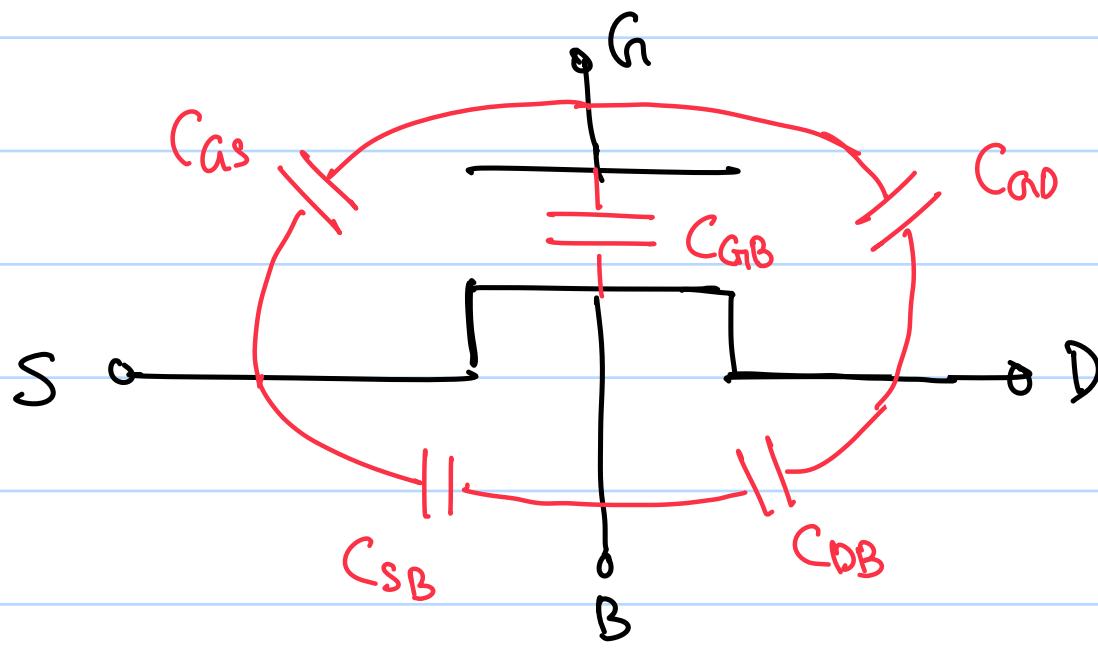
The capacitor acts like a normal parallel plate capacitor.

$$C = \frac{\epsilon A}{d} = \frac{\epsilon W L}{t_{ox}}$$

2) Depletion and Inversion :-



• Capacitance in the Modes of Operation :-



1) In Cutoff: $C_{GS} = C_{GD} = wC_{ov} \rightarrow$ Overlap Capacitance

$$C_{ov} = WL C_{ox}$$

2) In Linear :- $C_{GD} = C_{GS} = \frac{WLCon}{2}$

$$C_{GD_{ov}} = C_{GS_{ov}} = WLCon$$

3) In Saturation :- $C_{GS} = WLCon + \frac{2}{3}WLCon$

5) Mobility Degradation :-

The mobility of the channel depends on the electric field inside the channel as follows,

$$\mu \propto E^0 \text{ for } E < 10^3 \text{ V/cm}$$

$$\mu \propto \frac{1}{\sqrt{E}} \text{ for } E \approx 10^3 - 10^4 \text{ V/cm}$$

$$\mu \propto \frac{1}{E} \text{ for } E > 10^4 \text{ V/cm}$$

Note: Short Channel MOSFETs are those MOSFETs whose channel length is of the same magnitude as the dimensions of the source / drain depletion regions.

6) Tunneling :

Tunneling is the conduction of current through the gate terminal. Significant in short channel MOSFETs.

→ Parametric Extraction :-

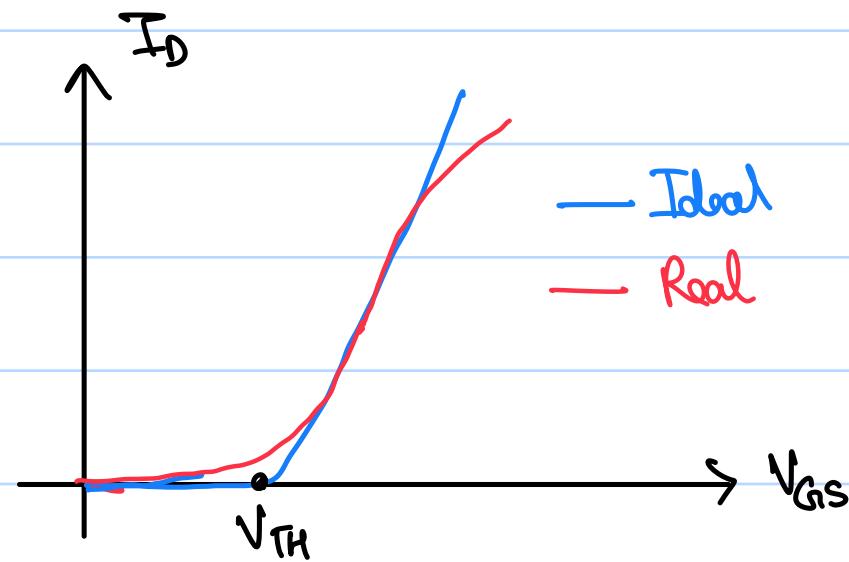
- $V_{GS} \geq V_T$ and $V_{DS} \ll (V_{GS} - V_T)$ [Deep Trickle]

$$\Rightarrow I_D = \mu_n C_o \frac{w}{L} (V_{GS} - V_{TH}) V_{DS}$$

is of the form $y = m(x - x_0)$ [I_D v/ V_{GS} sweep]

x_0 is the x intercept of the line

$\therefore V_{TH}$ is the x intercept of the above line



We take the point of maximum slope to construct the line equation, to avoid mobility reducing second order effects.

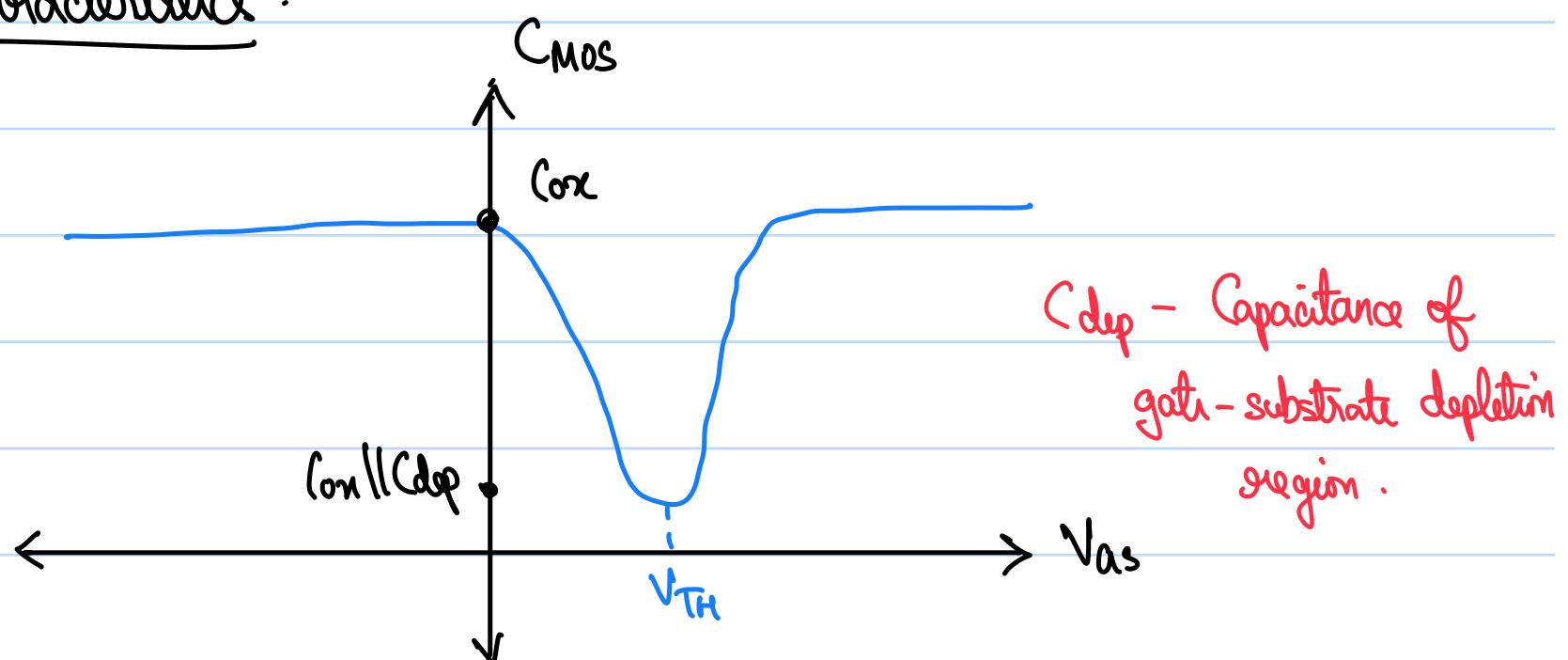
$$\mu = \frac{\mu_0}{1 + \Theta(V_{GS} - V_{TH})}$$

If $V_{GS} \approx V_{TH}$

$$\mu = \frac{\mu_0}{1 + \Theta(V_{GS} - V_{TH})} \approx \underline{\underline{\mu_0}} \quad [\text{Maximum value}]$$

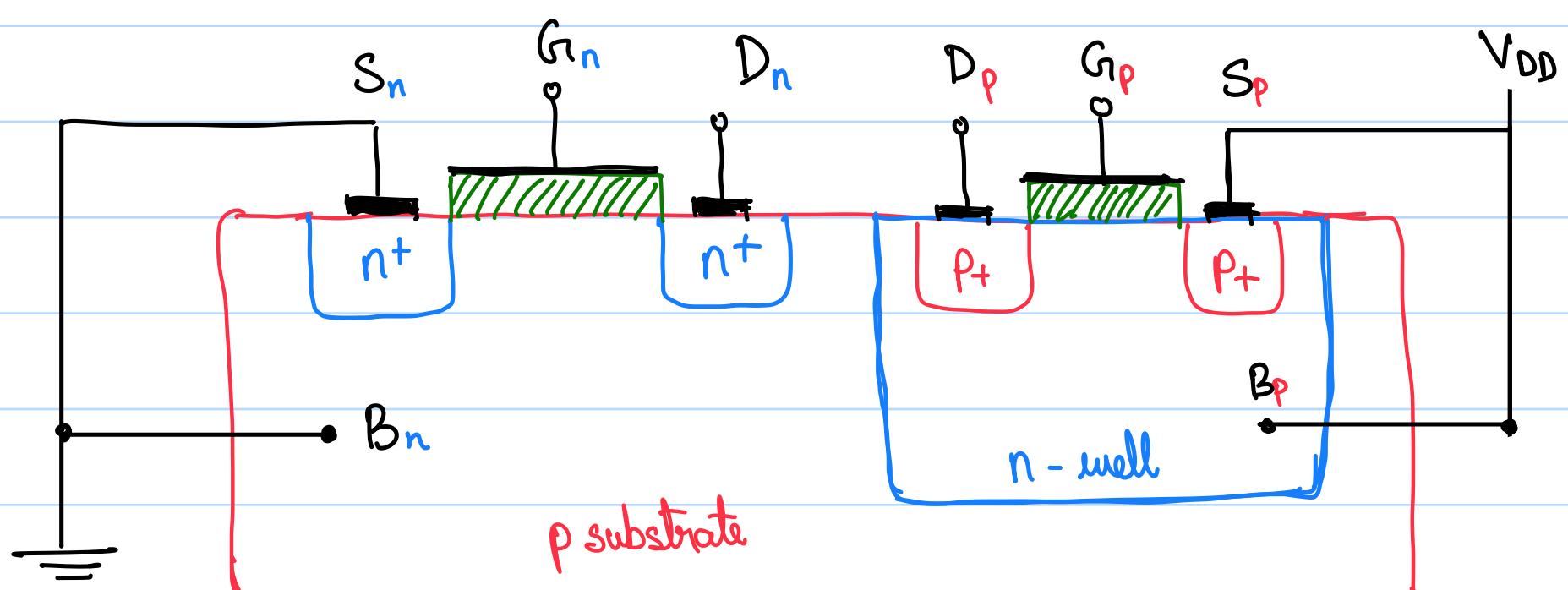
The effect of all the second order effects is modelled using Θ . So when $V_{GS} \approx V_{TH}$, ie at max mobility, Θ 's effect is low.

- C-V Characteristics :-



- CMOS Static Logic Devices :-

- CMOS - Complementary MOS (Combination of PMOS and NMOS)



CMOS Structure

(Well settled)

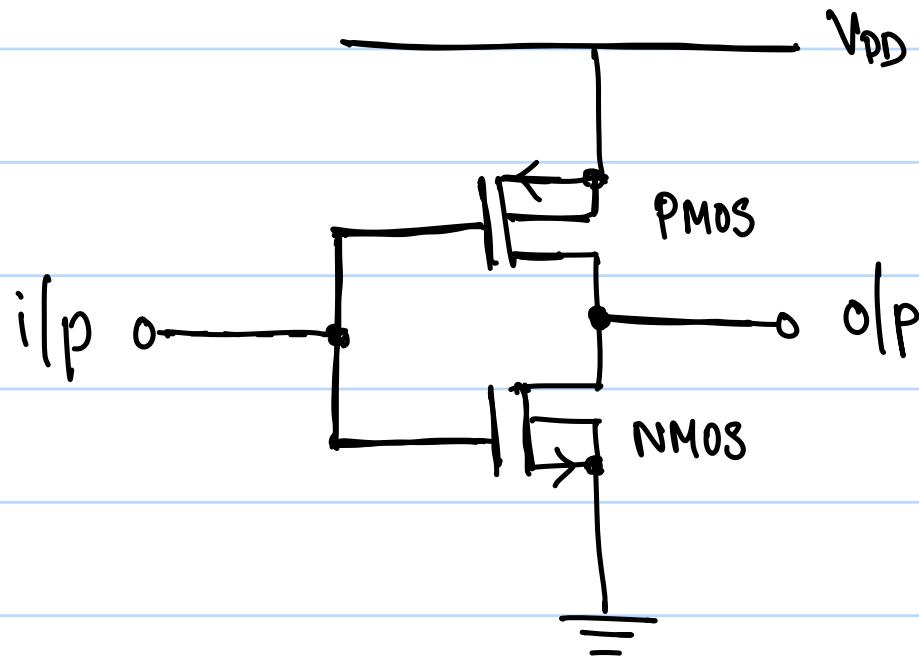
- Static - Well defined op states : Either 0 (gnd) or 1 (V_{DD})

- CMOS Devices will have a Pull-up and Pull-down networks in each logic stage.

Pulls op and ip to 0,1 levels

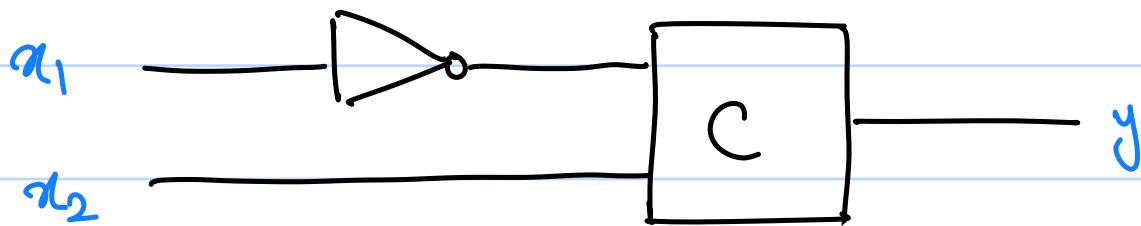
- Purpose of Logic Stage : To evaluate i/p and pull the o/p up or down to match V_{DD} or GND .
 - No static power consumption , ie , while i/p s are unchanged the power consumption is zero . Circuit still draws power when the i/p s are changed , ie , switching power is non-zero . (dynamic power)
 - CMOS Inverter :- (Rabaray's CMOS Design textbook & Weste)
- 1) Transfer Characteristic (VTC) (output vs input)
 - 2) Noise Margin
 - 3) Dynamic Characteristics (Rise/fall, time delay)
 - 4) Inverter Design Flow
 - 5) Efficacy
 - 6) Inverter in Other Logics

- Circuit:



- The design procedure of the inverter needs to consider things like time delay, load impedance, output load type, etc.

Example:

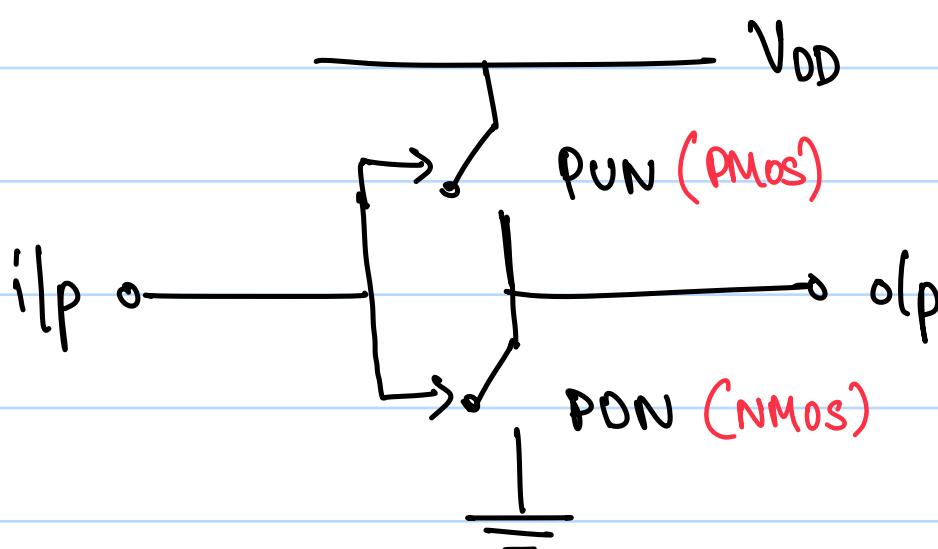


Since the inverter adds some delay, x_1 and x_2 will not reach C at the same time.

- Pull Up and Pull Down Network :-

- Pull Up : Pulls ilp to VDD

- Pull Down : Pulls ilp to GND



PUN and PDN are never on simultaneously.

- VTC of CMOS Inverter :-

- The VTC of a CMOS Inverter can be analyzed by plotting the different modes of the PMOS and NMOS.

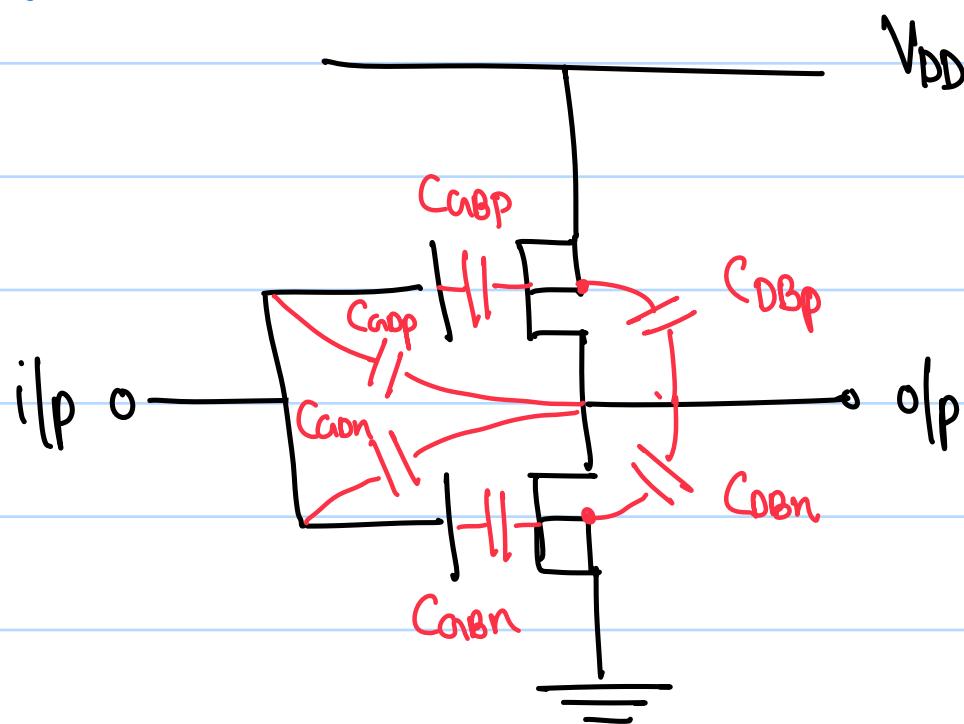
- On condition for M_n : $V_{GSn} = V_{ip} \geq V_{Tn}$
- " " " " M_p : $V_{GSp} = V_{DD} - V_{ip} \geq |V_{Tp}|$
 $= V_{ip} \leq V_{DD} - |V_{Tp}|$

Condition	M_n	M_p	o/p
$V_{ip} = 0$	OFF	ON	V_{DD}
$V_{ip} = V_{DD}$	ON	OFF	0

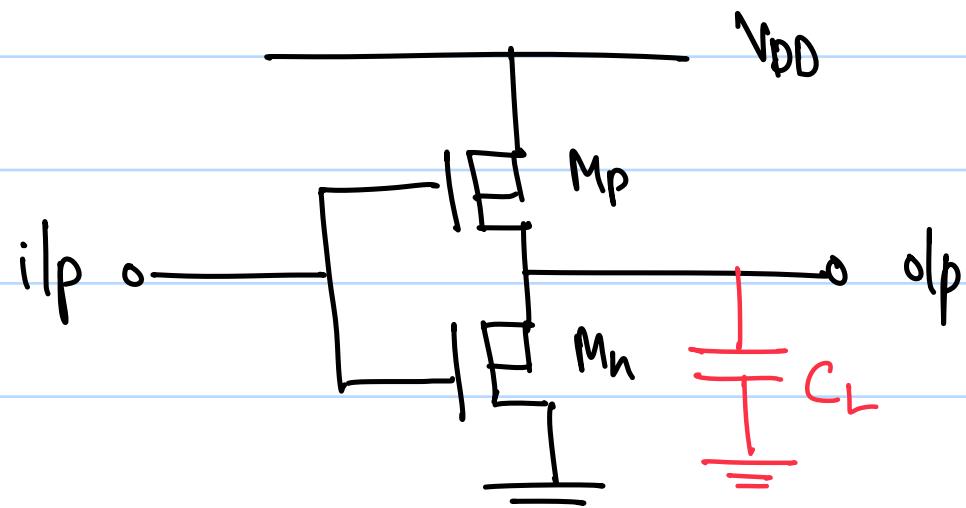
$V_{ip} \geq V_{Tn}$ $V_{ip} \leq V_{Tp} + V_{DD}$
 $(V_{Tp} \leq 0)$

} Inverter Behavior

- Modelling the capacitances in the inverter



Since at the settled state, the voltages are all constant, they can be considered as AC grounds. Therefore the total capacitive impedance can be modelled as a capacitive load.



$$M_n : V_{asn} = V_{tp}$$

$$V_{tp} \geq V_{tn}$$

$$V_{bsn} \approx V_{dd} \Rightarrow V_{bsn} \geq V_{asn} - V_{tn} \rightarrow M_n \text{ is in Saturation}$$

$$\text{Case 3: } V_{in} = V_{dd}/2 \longrightarrow V_{olp} \approx V_{dd}/2$$

$$M_n : V_{asn} = V_{dd}/2 \geq V_{tn} \quad [\text{Assn ②}]$$

$$V_{bsn} = V_{dd}/2$$

$$V_{dd}/2 \geq V_{dd}/2 - V_{tn} \longrightarrow M_n \text{ is in Saturation}$$

$$M_p : |V_{asp}| = |V_{dd}/2 - V_{dd}| = V_{dd}/2 > V_{tp}$$

$$|V_{asp}| = |V_{dd}/2 - V_{dd}| = V_{dd}/2$$

$$V_{dd}/2 > V_{dd}/2 - |V_{tp}| \Rightarrow |V_{asp}| \geq |V_{asp}| - |V_{tp}| \rightarrow M_p \text{ is in Saturation}$$

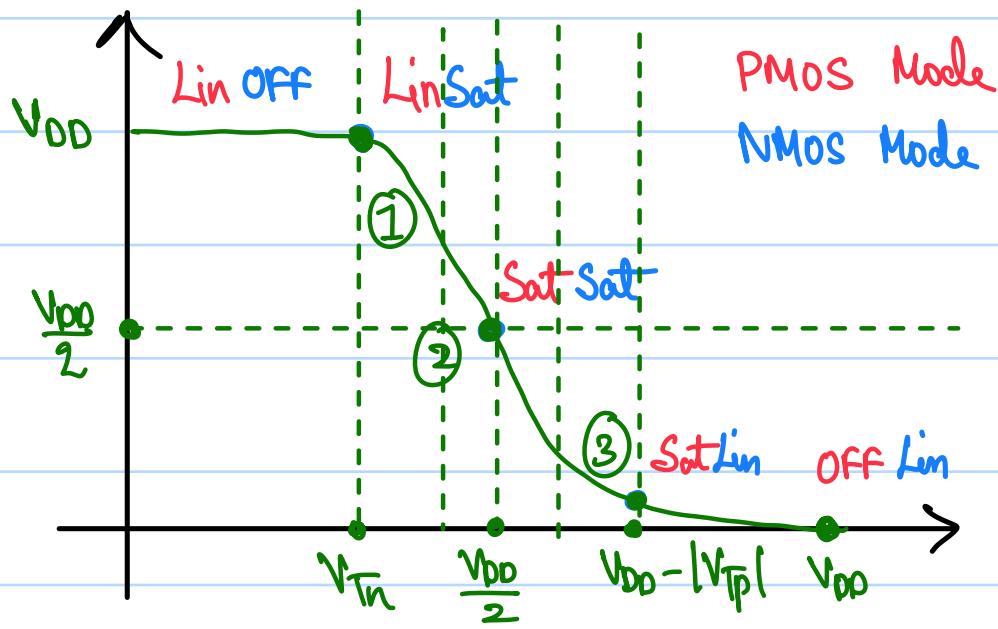
III proof can be stated for $V_{dd}/2 < V_{tp} < V_{dd} - |V_{tp}|$ and $V_{dd} - |V_{tp}| < V_{tp}$.

Once the voltages are settled

\therefore The VTC of the CMOS Inverter can be summarized as,

Condition	M _p	M _n	o/p
$0 \leq V_{in} \leq V_{tn}$	Lin	OFF	V _{dd}
$V_{tn} \leq V_{in} < V_{dd}/2$	Lin	Sat	$< V_{dd}$
$V_{in} = V_{dd}/2$	Sat		
$V_{dd}/2 < V_{in} < V_{dd} - V_{tp} $	Sat	Lin	$< V_{dd}/2$
$V_{dd} - V_{tp} < V_{in}$	OFF	Lin	0

This switching point is valid if $V_{tn} = |V_{tp}|$



Note: By KCL, currents through both the MOSFETs will always be equal in the 3 intermediate points (LinSat SatSat SatLin)

At ① (LinSat)

$$I_{Dp\text{ Lin}} = I_{Dn\text{ Sat}}$$

$$= K_p \left[(V_{DSp} - |V_{Tp}|) V_{SD} - \frac{V_{SD}^2}{2} \right] = \frac{1}{2} K_n (V_{DSn} - V_{Tn})^2$$

$$= K_p \left[(V_{DD} - V_{in} - |V_{Tp}|)(V_{DD} - V_{Dp}) - \frac{(V_{DD} - V_{Dp})^2}{2} \right] = \frac{K_n}{2} (V_{Dp} - V_{Tn})^2$$

On Solving, we will get, (Take $V_{DD} - V_{Dp} = y$, $V_{Dp} - V_{Tn} = x$ easy)
and $K_n = K_p$

$$V_{Dp} = (V_{Dp} + |V_{Tp}|) \pm \sqrt{(V_{DD} - V_{Tn} - |V_{Tp}|)(V_{DD} - 2V_{Dp} + V_{Tn} - |V_{Tp}|)}$$

Since $V_{Dp} \approx V_{DD}$ near ①,

$$V_{Dp} = (V_{Dp} + |V_{Tp}|) + \sqrt{(V_{DD} - V_{Tn} - |V_{Tp}|)(V_{DD} - 2V_{Dp} + V_{Tn} - |V_{Tp}|)}$$

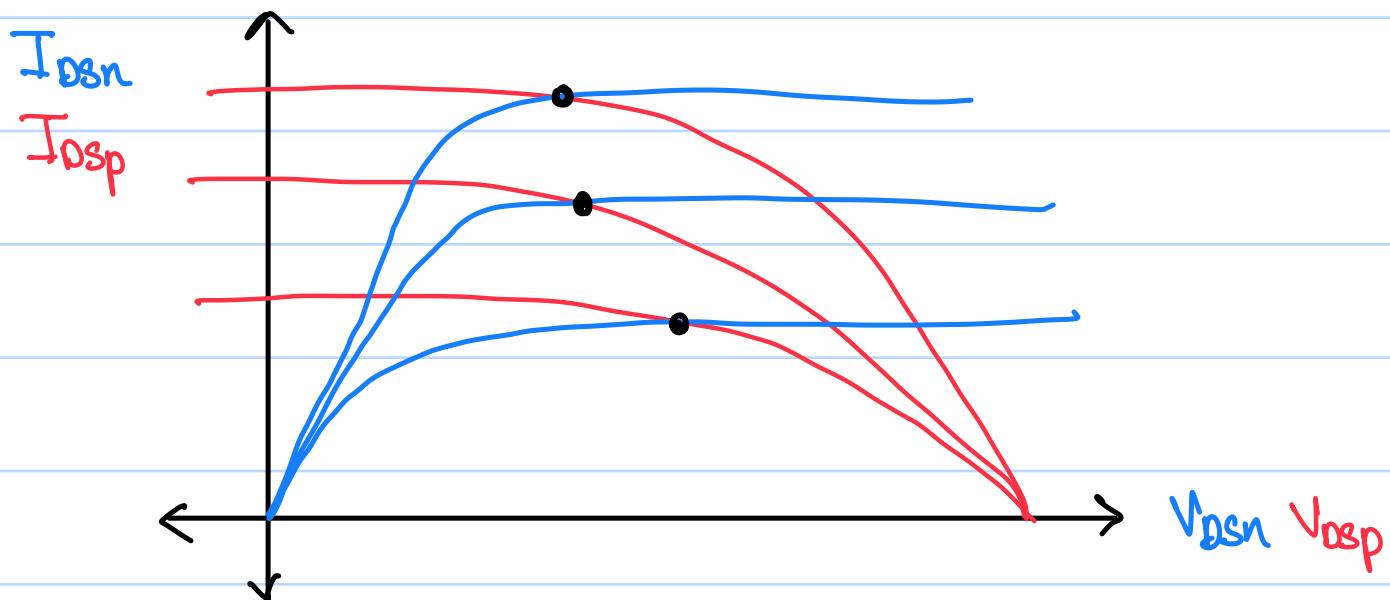
$$\text{Condition : } V_{DD} \geq V_{Tn} + |V_{Tp}|, V_{Dp} \leq \frac{V_{DD} + V_{Tn} - |V_{Tp}|}{2}$$

Therefore, the operating requirements of a CMOS inverter are:

$$1) V_{DD} \geq V_{Tn} + |V_{Tp}| \quad 2) V_{ilp} \leq \frac{V_{DD} + V_{Tn} - |V_{Tp}|}{2} \approx \frac{V_{DD}}{2}$$

min. power supply max. ilp voltage

By we can calculate for all the other points, by equating PMOS current and NMOS current.



$V_{DD} \approx 1.8 \text{ V}$ for 180 nm technology node.

At ② (Sat Sat),

$$\begin{aligned} I_{Dsn\text{sat}} &= I_{Dsp\text{sat}} \\ &= K_n (V_{Dsn} - V_{Tn})^2 = K_p (V_{Dsp} - |V_{Tp}|^2)^2 \\ &= K_n (V_{ilp} - V_{Tn})^2 = K_p (V_{DD} - V_{ilp} - |V_{Tp}|^2)^2 \end{aligned}$$

$$\Rightarrow V_{ilp} = \frac{(V_{DD} + \sqrt{B} V_{Tn} - |V_{Tp}|^2)}{1 + \sqrt{B}}$$

$B = \frac{K_n}{K_p}$

$$V_{DSN} \geq V_{ASN} - V_{THN}$$

$$\Rightarrow V_{Olp} \geq V_{ILP} - V_{THN}$$

$$V_{SDP} \geq V_{ASD} - |V_{THP}|$$

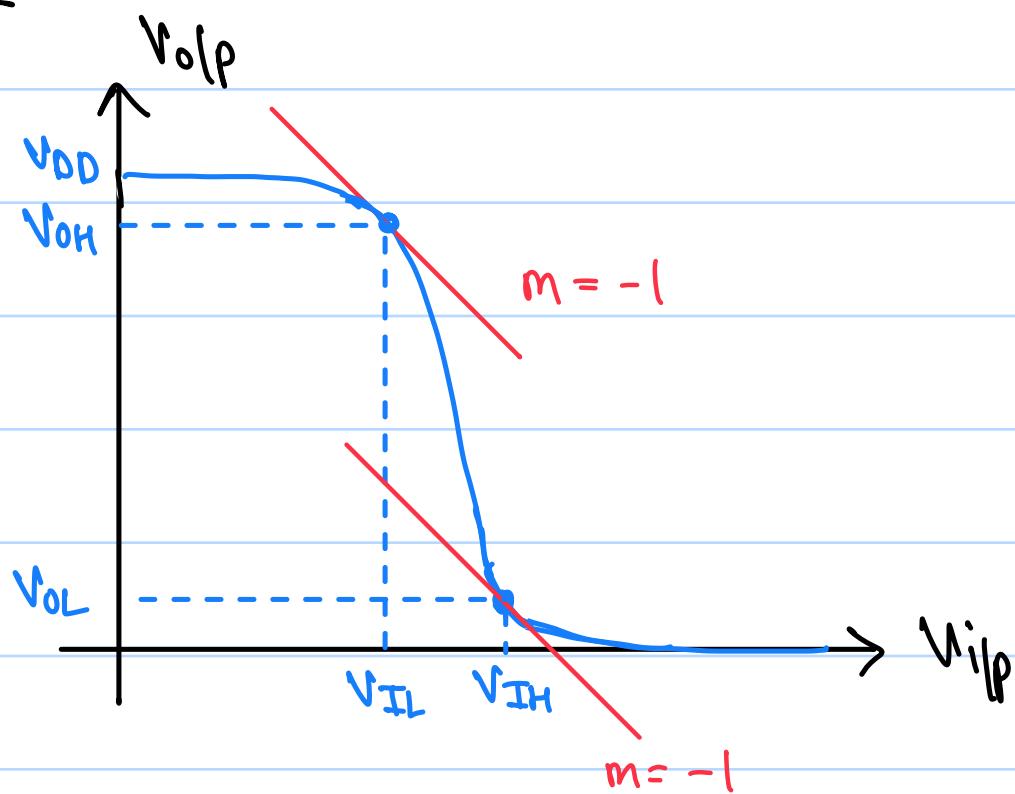
$$V_{DD} - V_{Olp} \geq V_{DD} - V_{ILP} - |V_{THP}|$$

$$\Rightarrow V_{Olp} \leq V_{ILP} + |V_{THP}|$$

$$\therefore V_{Olp} \in [V_{ILP} - V_{THP}, V_{ILP} + |V_{THP}|]$$

In this region, V_{Olp} vs V_{ILP} is approximately a straight line of very high slope. Therefore it shows amplifying action.

- Noise Margin :-



- To avoid the amplification behavior, we set

$$V_{out} \in [V_{OH}, V_{OD}] \longrightarrow \text{Logic 1}$$

$$V_{out} \in [0, V_{OL}] \longrightarrow \text{Logic 0}$$

$\Rightarrow V_{OH} = \text{Minimum o/p for o/p logic 1}$

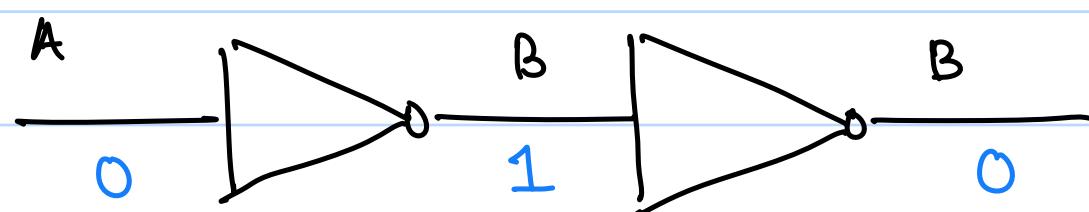
$V_{OL} = \text{Maximum o/p for o/p logic 0}$

$V_{IH} = \text{Minimum i/p for o/p logic 0}$

$V_{IL} = \text{Maximum i/p for o/p logic 1}$

- If $V_{i/p} \in (V_{IL}, V_{IH})$, the Inverter acts like an amplifier, which is unwanted since it **amplifies noise as well, creating undefined behavior.**

- If we have 2 inverters in series as,



$$V_A \in [0, V_{IL}] \quad V_B \in [V_{OH}, V_{OD}] \quad V_C \in [0, V_{OL}]$$

$$[V_{OH}, V_{OD}] \subseteq [V_{IH}, V_{OD}]$$

- From the VTC, we can say that $V_{OH} > V_{IH}$ and $V_{OL} < V_{IL}$. So, we define the noise margin of our inverter as,

$$NM_H = V_{OH} - V_{IH}$$

$$NM_L = V_{IL} - V_{OL}$$

- But since $V_{IH} < V_{OH}$, even if $V_B < V_{OH}$, as long as $V_B > V_{IH}$ the inverter C will output 0. Hence the noise margin NM_H . Similarly for V_B down, we have NM_L .

- Also if the 2 inverters are not the same, then it must be ensured that,

$$V_{OH1} > V_{IH2}$$

- The parameter extraction of V_{OH} , V_{OL} , V_{IH} , V_{IL} , can be done as follows,

For point (V_{IL}, V_{OH}) , Inv. is in region of LinSat

For point (V_{IH}, V_{OL}) , Inv. is in region of SatLin

We know the current equation at both these regions (or atleast how to derive them). The required points will have $\frac{dV_{Op}}{dV_{Ip}} = -1$

We will get,

$$V_{IL} = \frac{3V_{DD} + 5V_{Tn} - 8|V_{Tp}|}{8}$$

$$V_{OH} = \frac{7V_{DD} + V_{Tn} + |V_{Tp}|}{8}$$

$$V_{IH} = \frac{5V_{DD} + 3V_{Tn} - 5|V_{Tp}|}{8}$$

$$V_{OL} = \frac{V_{DD} - V_{Tn} + |V_{Tp}|}{8}$$

Assume

$$K_n = K_p$$

$$(or) \beta = 1$$

$$\Rightarrow NM_H = \frac{V_{DD} - V_{Th} + 3|V_{Tp}|}{4}$$

$$NM_L = \frac{V_{DD} + 3V_{Th} - |V_{Tp}|}{4}$$

if $V_{Th} = |V_{Tp}| = V_T$

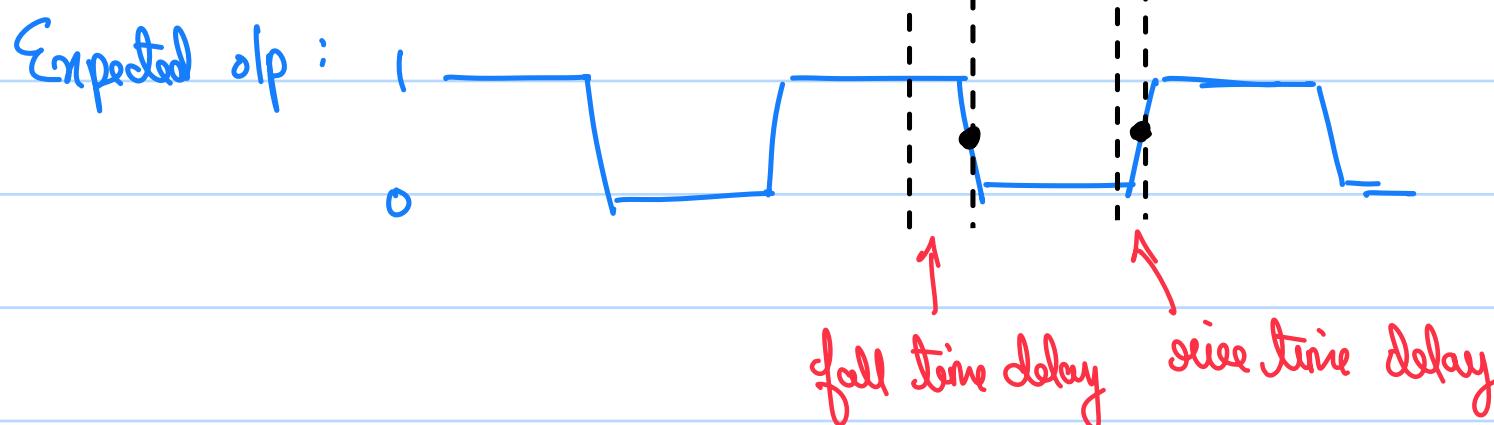
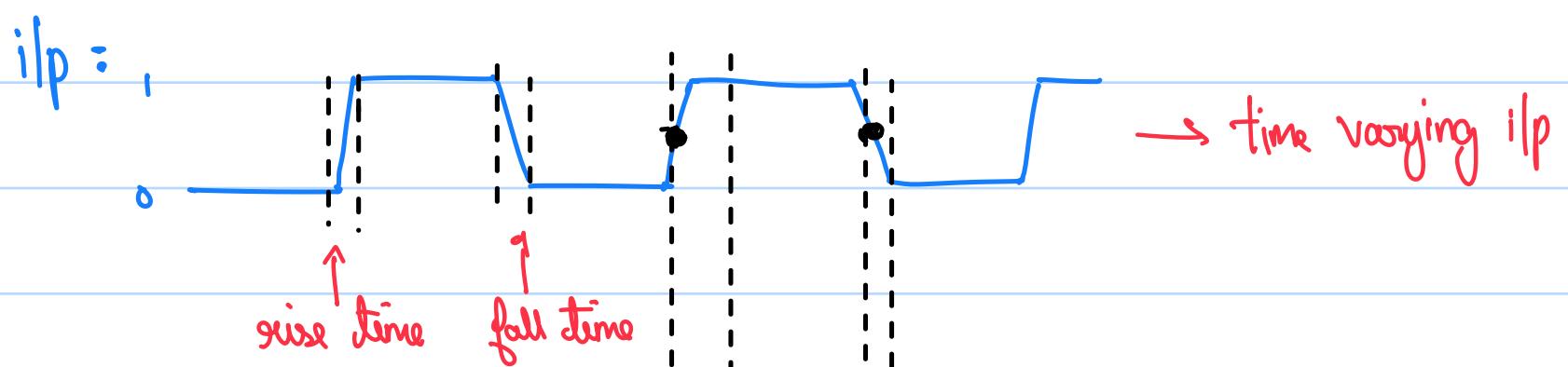
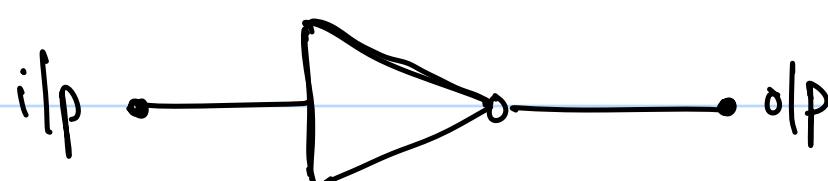
- From the NM_H/L equations we can see that increasing V_{DD} and V_{Th} will give us better noise margin.

Trade-offs :

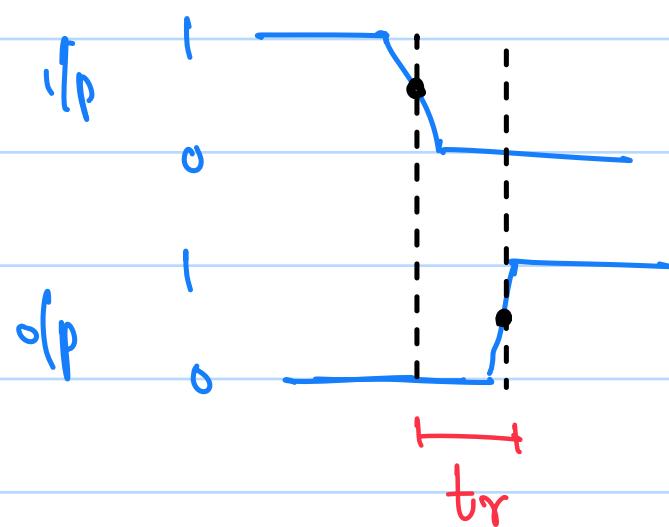
- $V_{DD} \uparrow$ increases power consumption
- $V_T \uparrow$ increases min. V_{DD} , lower current causing delays and lower speed.

Higher current charges the capacitances faster, reducing delay / increasing bandwidth

Dynamic Characteristics :-



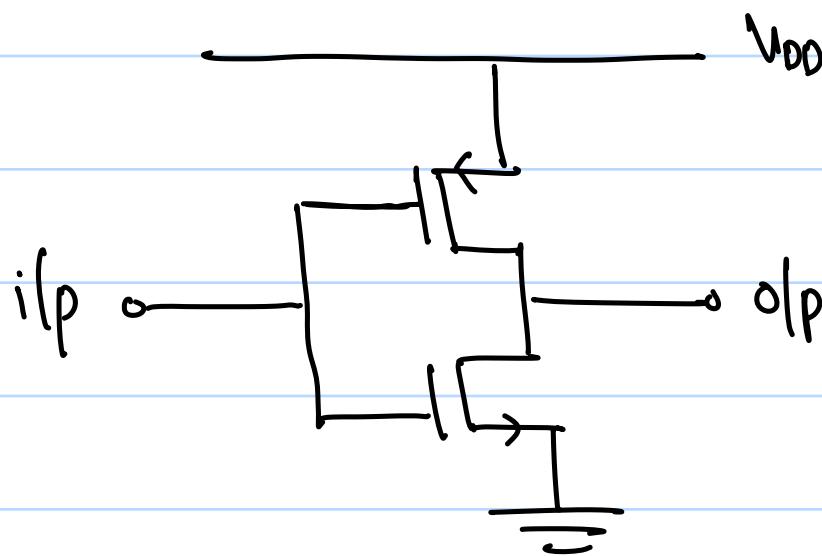
- The delay between the i/p and its respective o/p is due to the internal capacitances of the device and is unavoidable.
- Ideally, we want fall time delay and rise time delay to be the same, to get symmetric behavior.
- We assume that one of the MOSFETs is ON and the other is OFF always, to develop an intuition for the system.
- Rise Time Delay :-



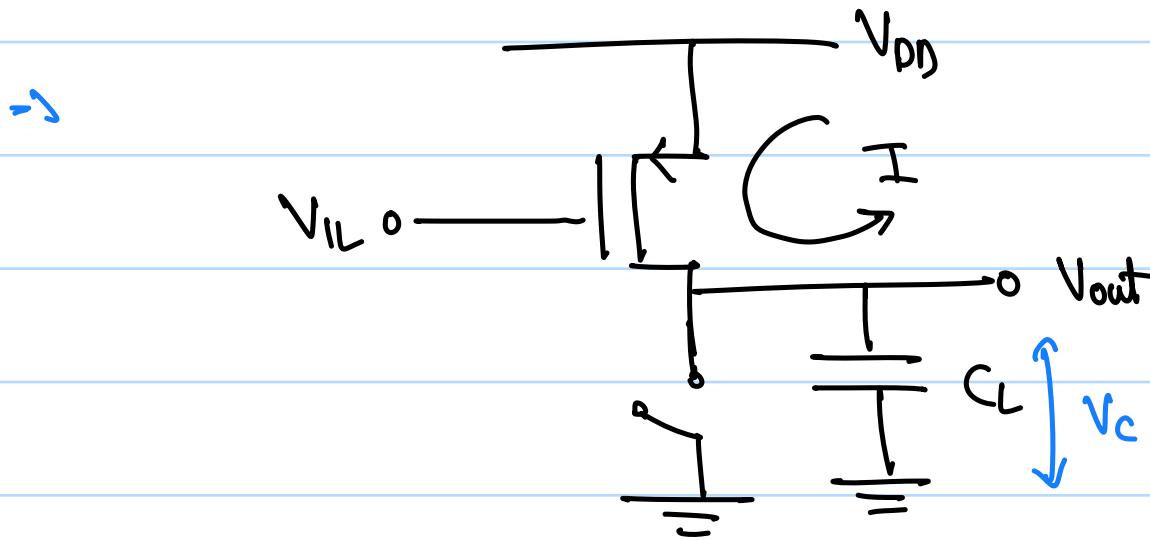
Assumptions:

$$V_{ilp} = V_{IL}$$

V_{olp} = Grows from 0 to V_{OH} .



~ In rise time, NMOS is OFF and PMOS is ON



$$I = I_{SD}, \Rightarrow I_{SD} = C \frac{dV_c}{dt}$$

$$\Rightarrow dt = \frac{C dV_c}{I_{SD}}$$

$$\Rightarrow t_r = \int_0^{V_{on}} \frac{C dV_c}{I_{SD}}$$

The mode of operation of the MOSFET,

$$V_{SDP} = V_{DD} - V_c$$

$$V_{on} = V_{SDP} - |V_{Tp}| = V_{DD} - V_{IL} - |V_{Tp}|$$

For linear,

$$V_{SDP} < V_{on}$$

$$\Rightarrow V_{DD} - V_c < V_{DD} - V_{IL} - |V_{Tp}|$$

$$\Rightarrow V_c > V_{IL} + |V_{Tp}|$$

\therefore For $V_c \in [0, V_{IL} + |V_{Tp}|]$, PMOS is in Saturation mode

For $V_c \in [V_{IL} + |V_{Tp}|, V_{on}]$, PMOS is in Linear mode

$$\rightarrow t_r = \int_0^{V_{IL} + |V_{Tp}|} \frac{dV_c}{I_{SO\text{ sat}}} + \int_0^{V_{IL} + |V_{Tp}|} \frac{dV_c}{I_{SO\text{ lin}}}$$

↑ constant current changing ↑ RC charging

$$I_{SPP} = \begin{cases} \frac{1}{2} K_p (V_{SDP} - |V_{Tp}|)^2, & \text{saturation} \\ K_p (V_{SDP} - |V_{Tp}|) V_{SDP} - \frac{V_{SDP}^2}{2}, & \text{linear} \end{cases}$$

Where,

$$V_{SDP} = V_{DD} - V_{IL}, \quad V_{SDP} = V_{DD} - V_C$$

On solving, we will get,

$$t_r = \frac{\alpha C [V_{IL} + |V_{Tp}|]}{K_p [V_{DD} - V_{IL} - |V_{Tp}|]^2} + \frac{C}{K_p [V_{DD} - V_{IL} - |V_{Tp}|]} \ln \left(\frac{V_{DD} + V_{OH} - 2V_{IL} - 2|V_{Tp}|}{V_{DD} - V_{OH}} \right)$$

↑ constant current charging time ↑ RC charging time

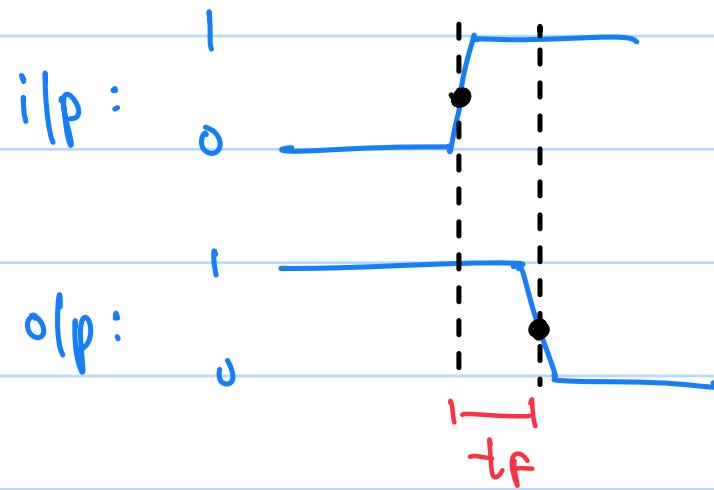
is the apparent
ON resistance of
the circuit

~ We can see that t_r is dependent on the ON resistance of the circuit

~ Also, the voltage terms resemble the Noise margin parameters of the inverter, i.e., for given Noise margin parameter,

$$\frac{K_p t_r}{C} \approx \text{const}$$

- Fall Time Delay :-

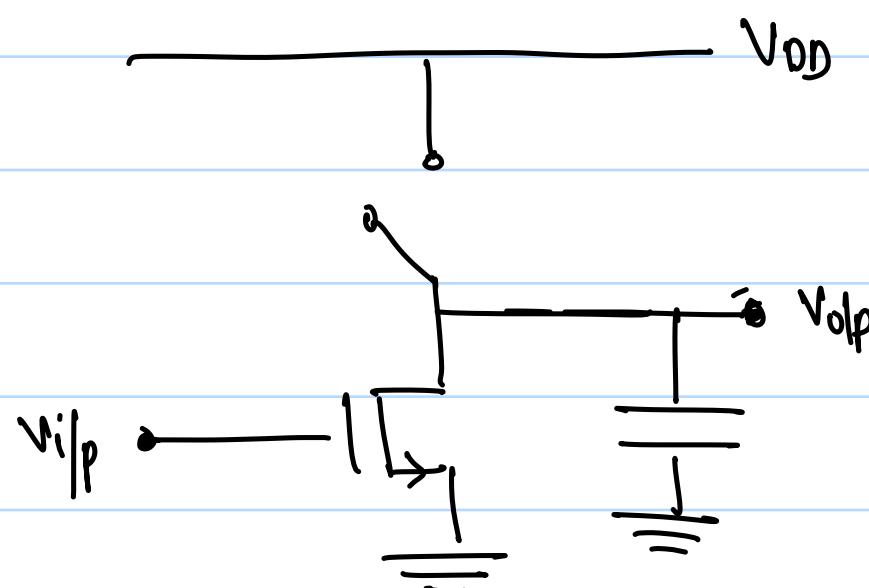


Assumptions :

$$V_{lp} = V_{IH}$$

V_{lp} = Falls from V_{DD} to V_{OL}

PMOS is OFF, NMOS is ON



$$I_{DS} = -C \frac{dV_C}{dt} \Rightarrow dt = -\frac{C dV_C}{I}$$

$$\Rightarrow t_f = -C \int_{V_{LP}}^{V_{OL}} \frac{dV_C}{I} = C \int_{V_{OL}}^{V_{DD}} \frac{dV_C}{I}$$

$$\Rightarrow t_f = \int_{V_{DD}}^{V_{IH} - V_{TN}} \frac{dV_C}{I_{DSsat}} - \int_{V_{IH} - V_{TN}}^{V_{OL}} \frac{dV_C}{I_{DSlin}}$$

$$\Rightarrow \frac{K_{n\text{tf}}}{c} = \frac{2(V_{DD} - V_{IH} + V_{Th})}{(V_{IH} - V_{Th})^2} + \frac{1}{V_{IH} - V_{Th}} \ln \left(\frac{2(V_{IH} - V_{Th}) - V_{OL}}{V_{OL}} \right)$$

$$\Rightarrow \frac{K_{n\text{tf}}}{c} = \text{const for a given NM}$$

- Delay: -

The total delay of the inverter is given by,

$$\tau = \frac{t_r + t_f}{2}$$

$$\Rightarrow \tau \propto \frac{c}{k_p + k_n}$$

~ We know,

$$C_{IN} = C_{asn} + C_{asp} + C_{aon} + C_{aop}$$

$$\approx w_n L_n C_{oxn} + w_p L_p C_{oxp} + C_{ovn} + C_{ovp}$$

$$+ w_n C_{ovn} + w_p C_{ovp}$$

Since $K_{p/n} \propto W$, we can say $C_{IN} \propto K_p / n$

$$\Rightarrow \tau \propto \frac{C_L}{C_{IN}}$$

~ Also, $C_L = C_{ext} + C_{self}$

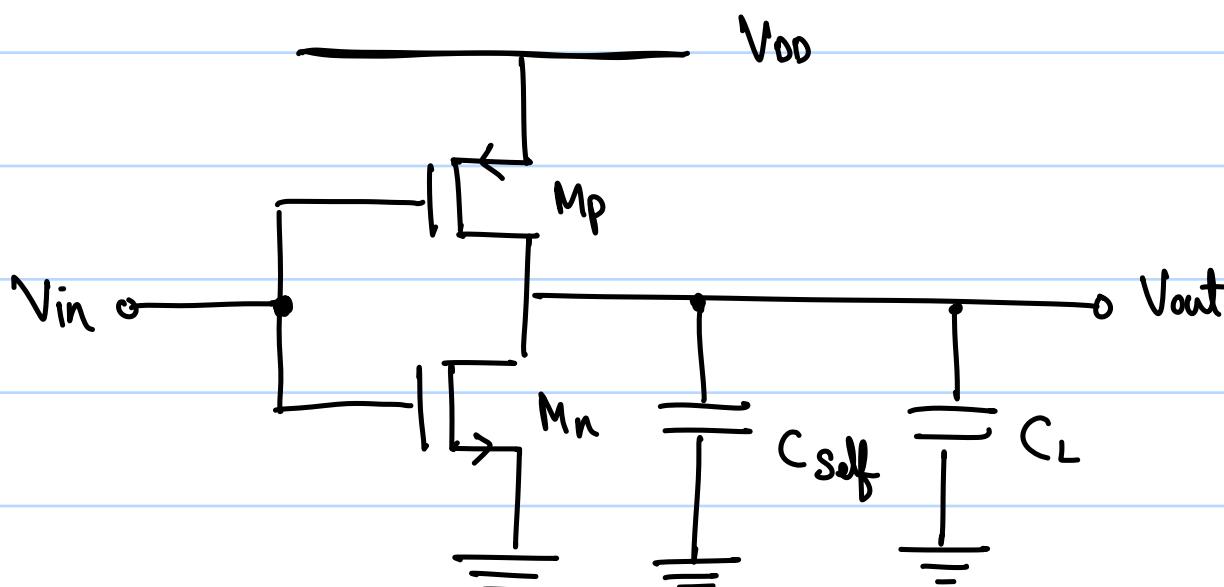
$$C_{self} = C_{DBn} + C_{DBp} + C_{aon} + C_{aop}$$

$$\Rightarrow C_{self} \propto K \Rightarrow C_{self} \propto C_{IN}$$

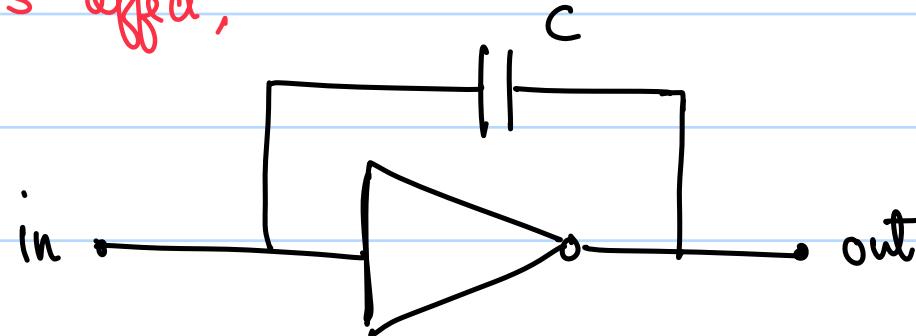
$$\Rightarrow T \propto \frac{C_{ext}}{C_{IN}} + \text{const}$$

~ Because of the constant in the equation, if we increase C_{IN} to a very large number, any further increase will be dominated by the constant.

~ Also, C_{IN} will act as C_{ext} for any logic circuit in the previous stage.



Note: Miller's effect,



This is high for
inv. in the Ampl.

$$C_{out} = C(1 + A) \quad A - \text{Gain mode}$$

+ Any DC potential acts like a ground for AC responses in capacitances.

$$\sim C_{self} = C_{Aop} + C_{GDN} + C_{DBn} + C_{DB}$$

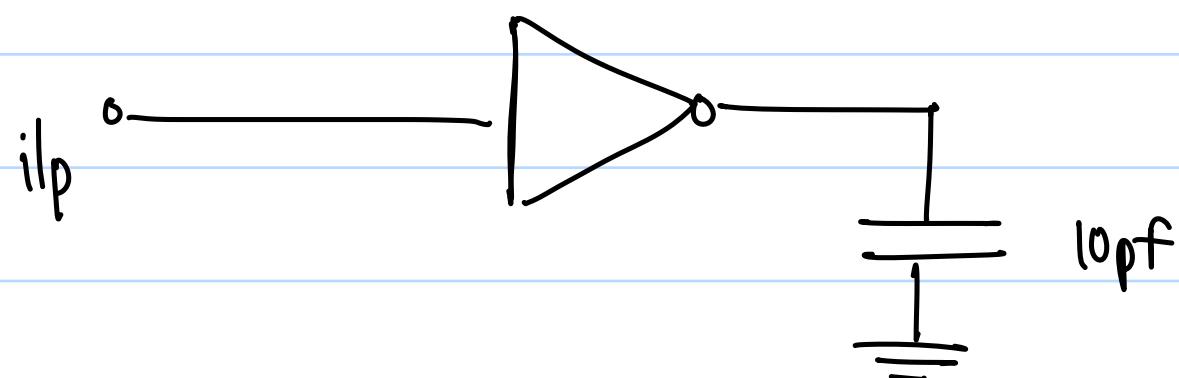
~ Define $\frac{C_{ext}}{C_{in}} = h$, since Delay = $\frac{C_{ext}}{C_{in}} + \text{const.}$

$$\Rightarrow \text{Delay} = (h + p)\tau \quad p - \text{Constant Term}$$

τ - Proprietary Const.

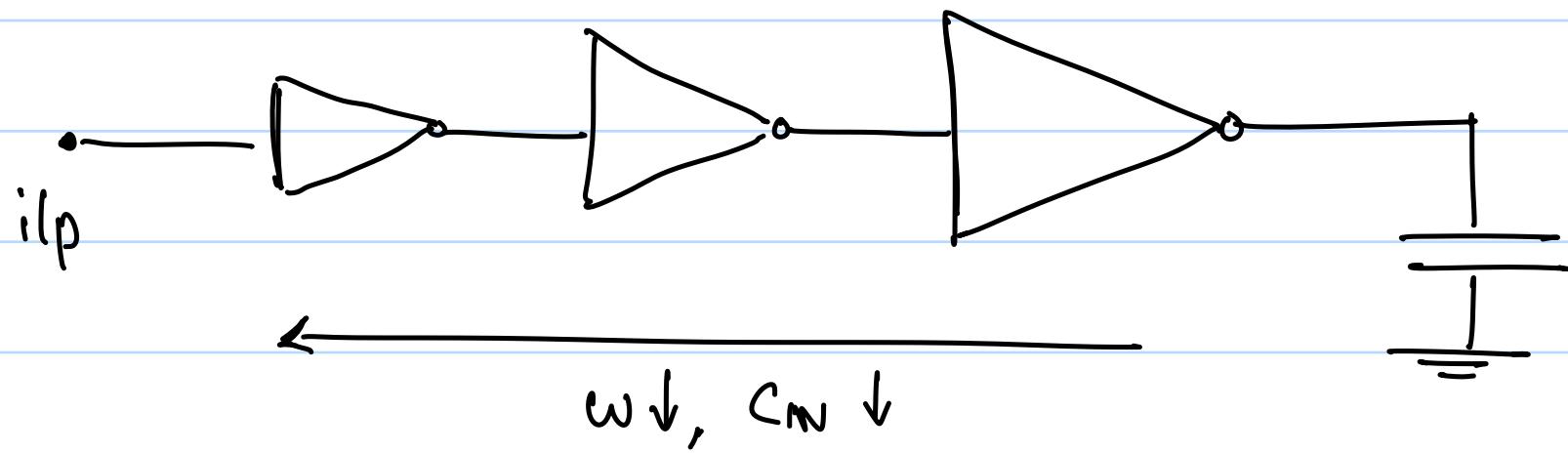
h - Electrical effort of the gate.

~ If we have a big capacitor on the output side.



Since a huge driving current is required to quickly charge the capacitor, the width of the inverter must be high, which increases C_{IN} .

If C_{IN} must be low, we can chain multiple inverters together.



Since $C_{IN} < C_{ext}$, smaller inverters are used to drive the

smaller i/p capacitance .

" If $K_n = K_p$, then $\frac{W_p}{W_n} = \frac{M_n}{M_p} \Rightarrow W_p = \frac{M_n}{M_p} W_n$

If we say an inverter has width W , we usually mean the width W_n . W_p is calculated by $\frac{M_n}{M_p} W_n$. ($\approx 2W_n$)

" Having such a chain of inverters will actually be faster than a single inverter, ie, the delay is lower.

Min. size transistor : $L = L_{min} = \text{Tech.node}$, $W = W_{min} > L_{min}$
 0.18μ , 0.27μ in 180nm TSMC.

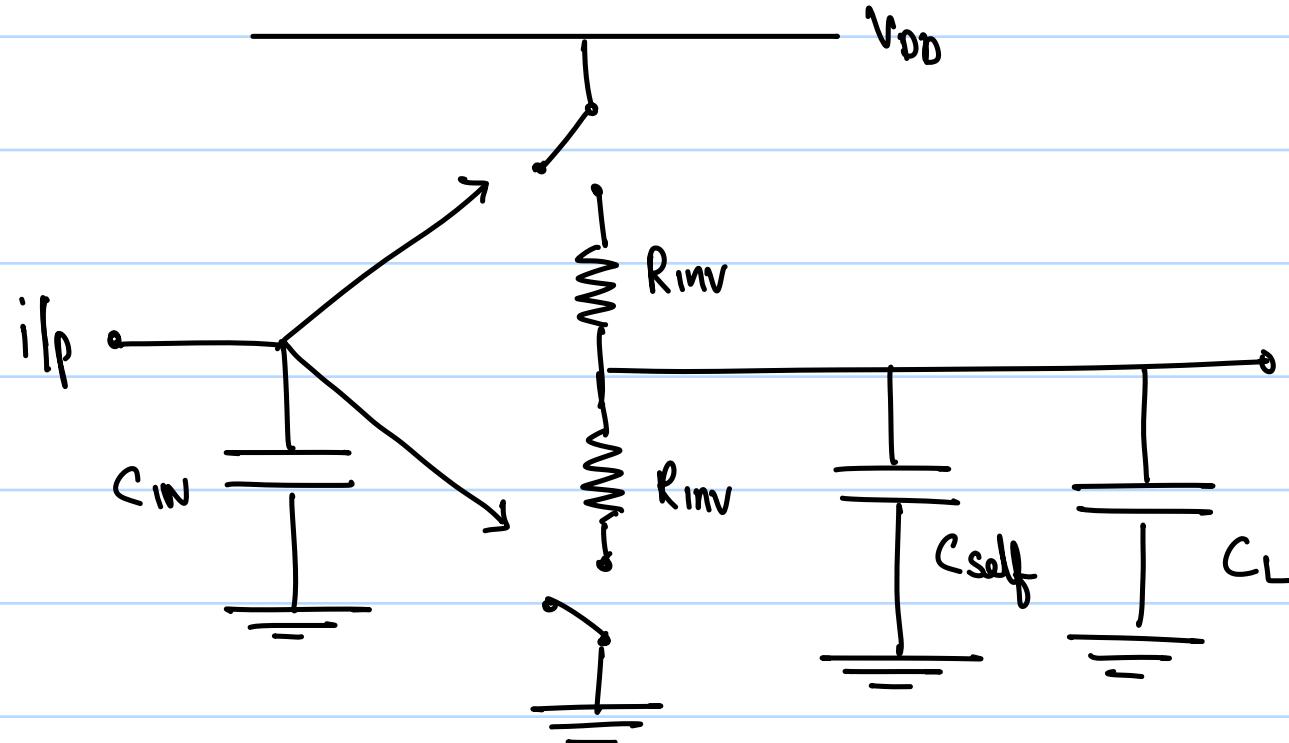
If we directly use a min. size transistor, the delay will be extremely high. (low W). But C_{IN} will be good.

So, using a series of inverters with increasing widths will be faster, since the smaller transistors drive a smaller capacitance, leading to smaller delays.

This is termed as the buffer chain / tapered buffer design .

- Buffer Chain Design :

~ Simplified Model of an Inverter,



Case 1: If $\rho = 0$ (ie $C_{self} = 0$), then $T_1 = R_{inv} C_L$

Case 2: $T_2 = R_{inv} (C_{self} + C_L) \rightarrow$ General Case

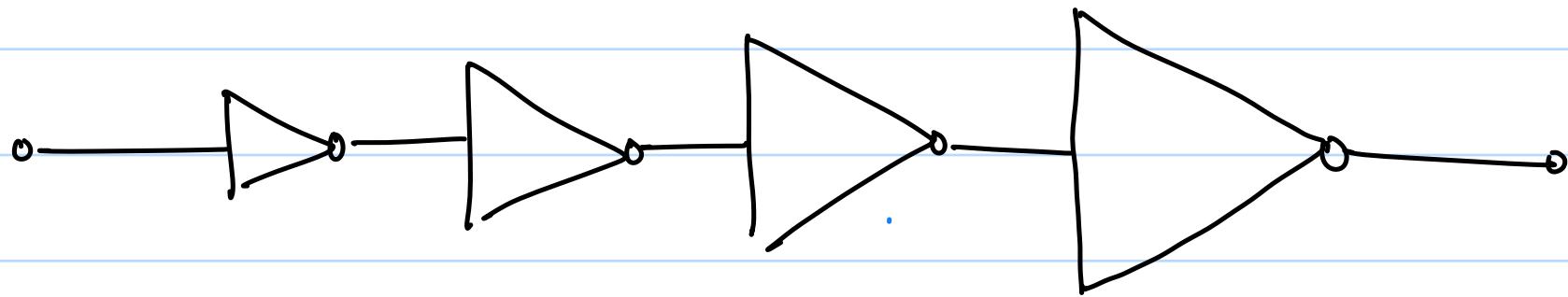
$$\frac{T_2}{T_1} = \frac{C_{self} + C_L}{C_L} = 1 + \frac{C_{self}}{C_L}$$

In buffer chain, $C_L = i_{ip}$ capacitance of next inverter. (C_{in-inv})

$$\Rightarrow \frac{T_2}{T_1} = 1 + \frac{C_{self}}{C_{in-inv}}$$

$$\Rightarrow T_2 = \left(1 + \frac{C_{self}}{C_{in-inv}}\right) T_1$$

So, given C_L and C_{in} limitations we can design a buffer chain for the lowest delay, through the following algorithm.



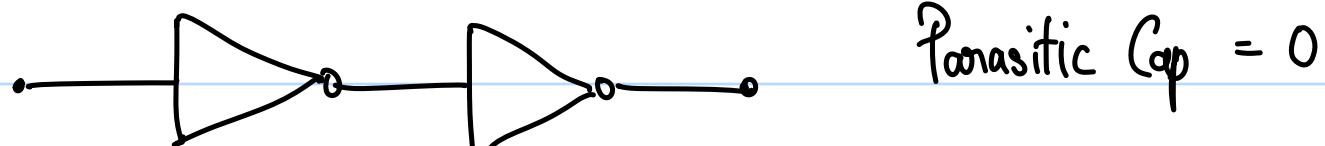
Total delay = \sum Delay in each inverter.

$$\text{Also, in } \tau_2 = \tau_1 \left(1 + \frac{C_{self}}{C_{in-inv}} \right)$$

Since $C_{self} \propto C_{in-inv}$, $\frac{C_{self}}{C_{in-inv}} = \text{const} = f$

$$\Rightarrow \tau_2 = \tau_1 (1 + p)$$

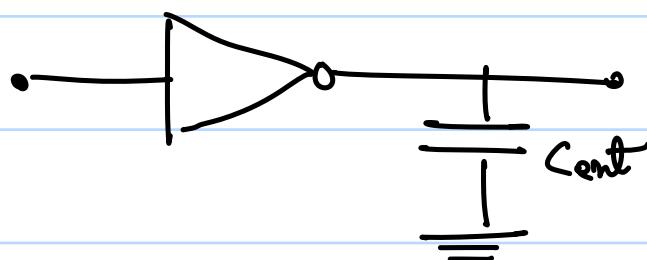
Case 1:



Parasitic Cap = 0

$$\tau = R_{inv} \cdot C_{in-inv}$$

Case 2:



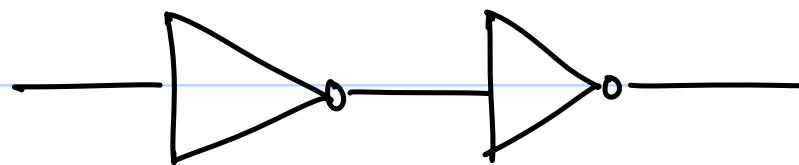
Parasitic $\neq 0$

$$D = R_{inv} (C_{ext} + C_{self})$$

$$\frac{D}{\tau} = \frac{C_{out} + C_{self}}{C_{in-inv}}$$

$$\Rightarrow D = \tau \left(\frac{C_{out}}{C_{in-inv}} + p \right)$$

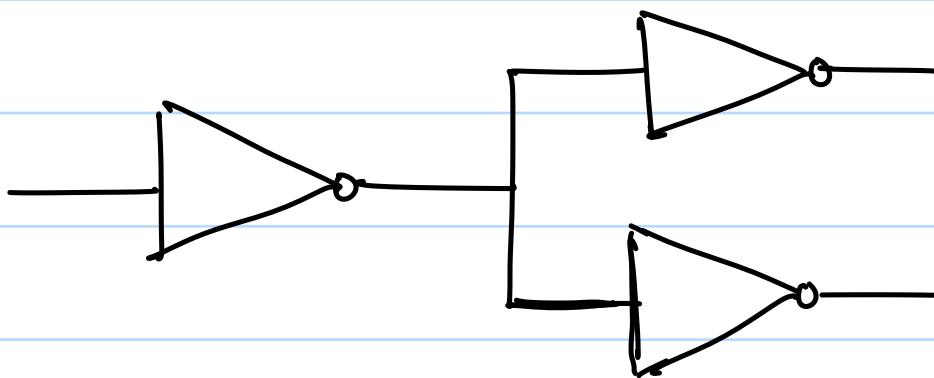
Using this formula, if the inverter is driving 1 other inverter,



$$C_{out} = C_{in-inv}$$

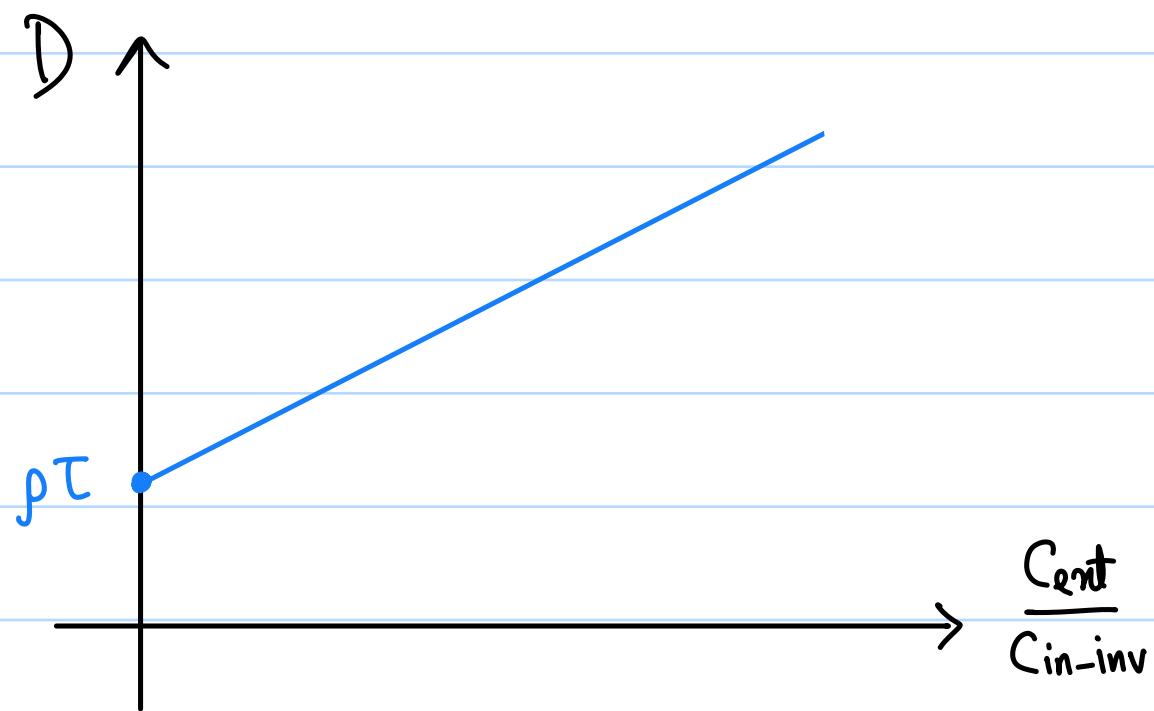
$$\Rightarrow D_1 = \tau(1+p)$$

If the inverter is driving 2 other inverters in parallel,

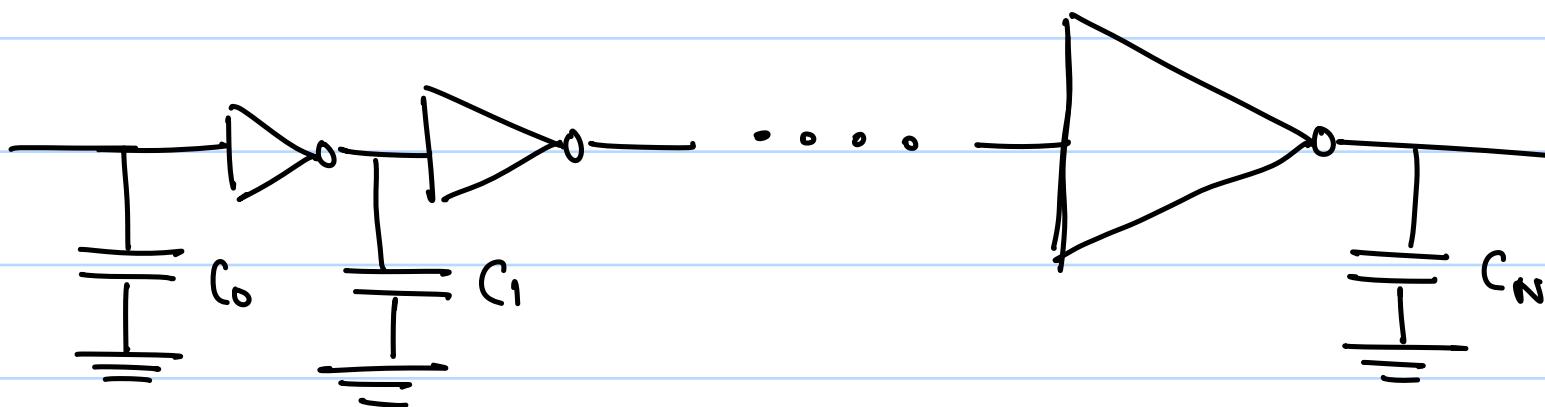


$$C_{out} = 2C_{in-inv}$$

$$\Rightarrow D_2 = \tau(2+p)$$



~ In an N -stage buffer chain,



$$D = D_1 + D_2 + D_3 + \dots + D_N$$

$$= \left(\left(\frac{C_1}{C_0} + \rho \right) + \left(\frac{C_2}{C_1} + \rho \right) + \dots + \left(\frac{C_N}{C_{N-1}} + \rho \right) \right) \tau$$

$$\Rightarrow D = \tau \left(\sum_{i=1}^N \frac{C_i}{C_{i-1}} + N\rho \right)$$

$$\Rightarrow D = \tau \left(\sum_{i=1}^N h_i + N\rho \right) \quad h_i - \text{Electrical Effort} = \frac{C_{\text{out}}}{C_{\text{in}}}$$

~ To optimize delay,

$$i) h_1 = h_2 = h_3 = \dots = h_N$$

$$\frac{SD}{SC_i} = \frac{S}{SC_i} \left(\frac{c_i}{c_{i-1}} + \beta + \frac{c_{i+1}}{c_i} + \beta \right) = 0$$

$$= \frac{1}{c_{i-1}} + c_{i+1} \left(\frac{-1}{c_i^2} \right) = 0$$

$$= \frac{1}{c_{i-1}} = \frac{c_{i+1}}{c_i^2}$$

$$= c_i = \sqrt{c_{i+1} c_{i-1}} \longrightarrow \text{For Min. delay}$$

$$h_i = \frac{c_i}{c_{i-1}} = \sqrt{\frac{c_{i+1}}{c_{i-1}}}$$

$$\Rightarrow h_1 = h_2 = h_3 = h_4 \dots \dots = h_N \quad (\text{On simplifying})$$

$$\text{Overall electrical effect } H = \frac{C_{ext}}{C_{in}}$$

$$\frac{C_N}{C_0} = \frac{c_1}{c_0} \times \frac{c_2}{c_1} \times \frac{c_3}{c_2} \times \dots$$

$$H = h_1 \times h_2 \times h_3 \times \dots$$

$$\Rightarrow h = H^{1/N}$$

$$D = \tau \left(\sum_{i=1}^N h_i + N_p \right)$$

$$= N \tau (h + \beta)$$

$$\Rightarrow D = N \tau (h^{1/N} + \beta)$$

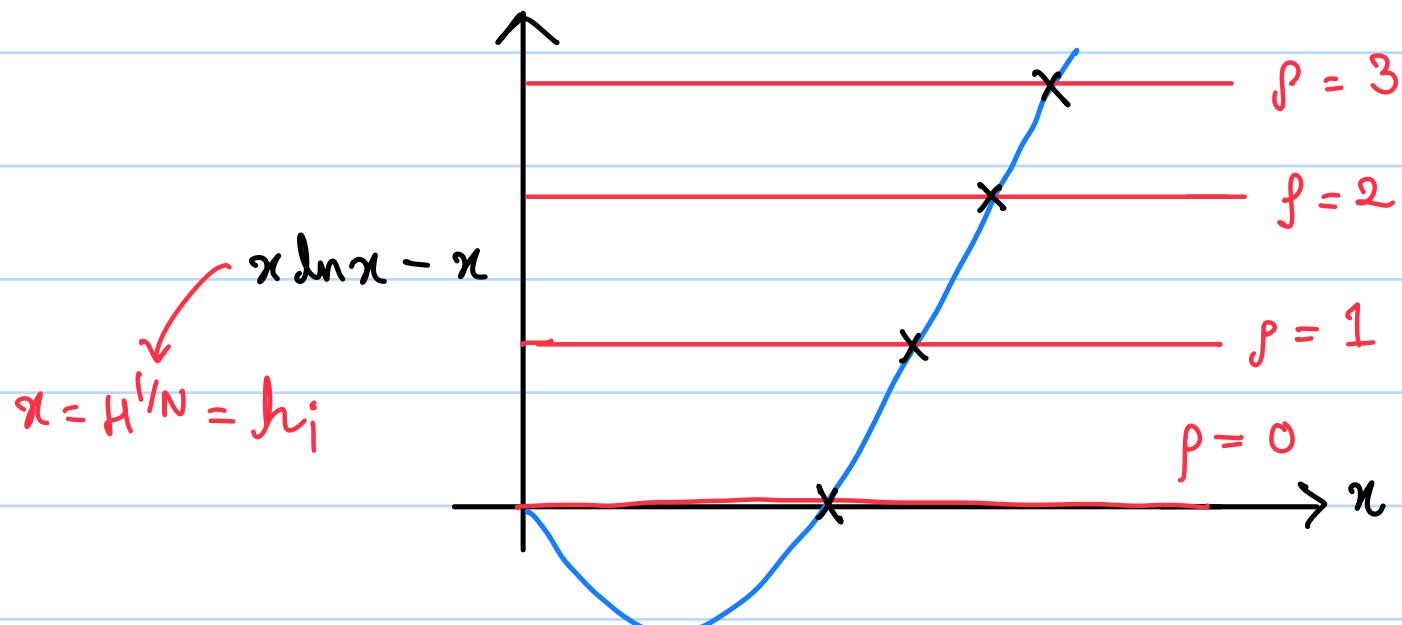
$$\text{Take } x = H^{1/N}, \Rightarrow \ln x = \frac{1}{N} \ln H \quad x = h_i$$

$$D(x) = \tau N(x + p)$$

$$\Rightarrow D(x) = \tau \frac{\ln H}{\ln x} (x + p)$$

$$D'(x) = \tau \frac{\ln H}{\ln x} \left[\frac{x \ln x - (x + p)}{x \ln x} \right] = 0$$

$$\Rightarrow x \ln x - x = p$$



The intersection points of x give us the value of $H^{1/N}$ and thereby, the value of N (H is known) needed for the tapered buffer.

p	h_i
0	2.73
1	3.59
2	4.31

Now for each inverter,

$$h_i = \frac{C_{out}}{C_{in}}$$

$$\Rightarrow C_{in} = \frac{C_{out}}{h_i}$$

Since $C_{in} = WL C_{ox,n} + W C_{ov,p} = w [const]$, we can determine the width of each inverter in the chain.

~ Newton Raphson Method to find h_i :-

Newton Raphson is an iterative method to find the zeros of any function

Let $f(x)$ be our function and let the approximate zero be m , then,

$$m_{next} = m - \frac{f(m)}{f'(m)}$$

Eventually, $f(m_{next})$ will start to converge to zero.

Here, our $f(x) = x \ln x - x - p$

$$m_{next} = m - \frac{m \ln m - m - p}{-\ln m}$$

$$\Rightarrow m_{next} = \frac{m + p}{\ln m}$$

Example: $H = \frac{C_L}{C_{in}} = 10^3$, $\beta = 1 \text{ or } 2$ Find the no. of stages required for an optimized non-inverting buffer.

$$f(x) = x \ln x - x - p$$

$$\text{If } p = 1, x = 3.59$$

$$x = H^{1/N} \Rightarrow N = \frac{\ln H}{\ln x} = \frac{\ln(1000)}{\ln(3.59)} \approx 5.404$$

$$\Rightarrow N = 5.404$$

$$\begin{aligned} D &= N\tau(H^{1/N} + \beta) \\ &= 4\tau(1000^{1/4} + 1) \quad \text{or} \quad 6\tau(1000^{1/6} + 1) \\ &\approx \underline{26.5\tau} \qquad \qquad \qquad \approx \underline{\underline{24.9\tau}} \end{aligned}$$

$N = 6$ has lower delay than $N = 4$

\therefore Our buffer chain should be 6 stage with $\chi_i = \underline{\underline{3.59}}$.

$$\text{If } p = 2, x = 4.319$$

$$N = \frac{\ln H}{\ln x} = \frac{\ln(1000)}{\ln(4.319)} = 4.72$$

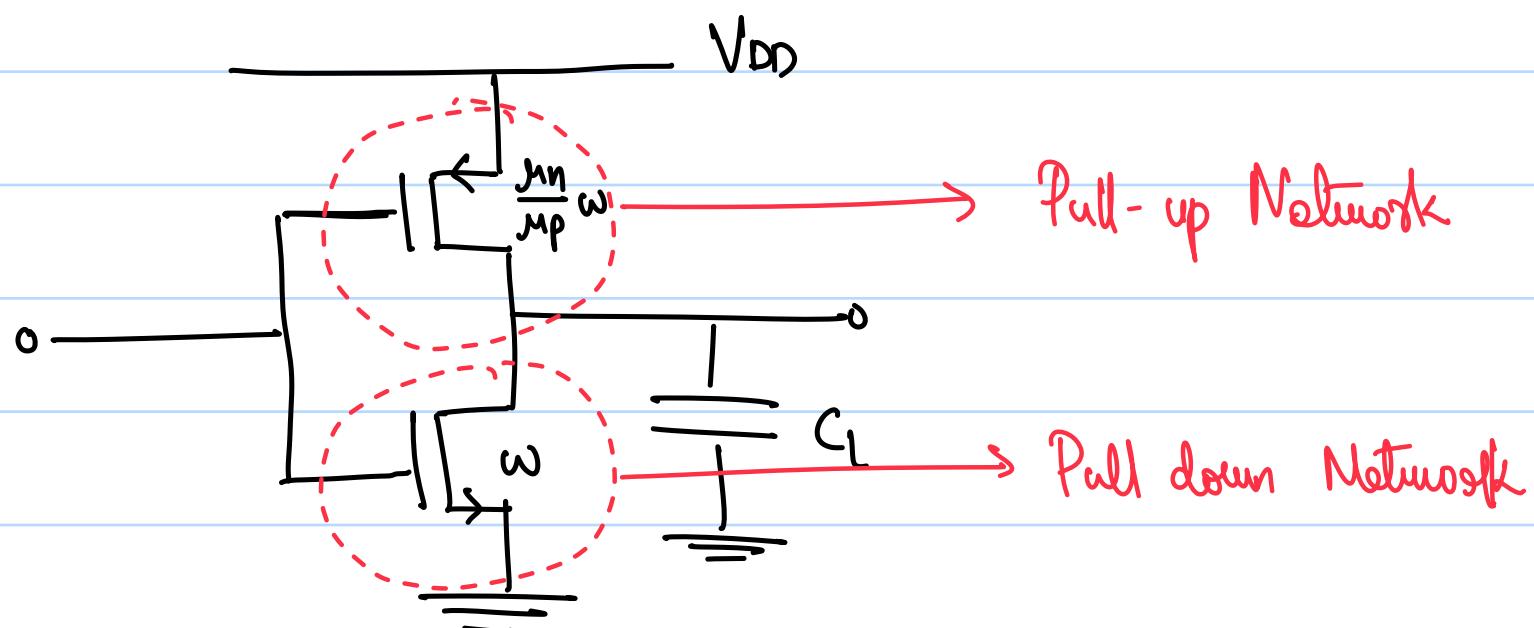
$$\begin{aligned}
 D &= N\tau(H^{1/N} + f) \\
 &= 4\tau(1000^{1/4} + 2) \quad \text{or} \quad 6\tau(1000^{1/6} + 2) \\
 &= 30.49\tau \quad = 30.97\tau
 \end{aligned}$$

\Rightarrow 4 stage is more optimized.

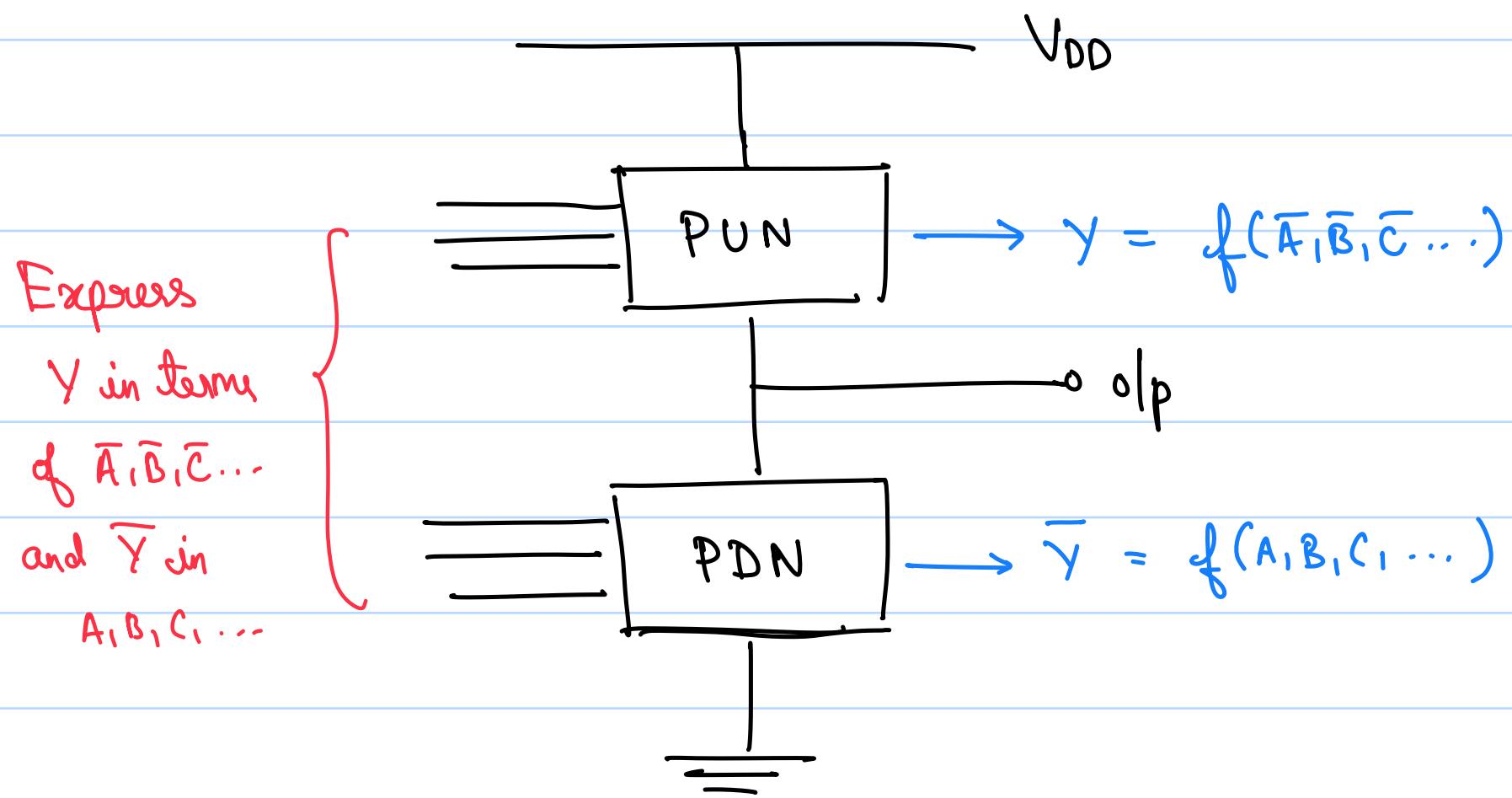
* Method Of Logical Effort :-

Ref: Sutherland | Sproull | Kaviraj
Designing fast CMOS logic

- In our CMOS Inverter,



- If we want to implement the logical circuit $y = \overline{A \cdot B}$, since the inverter is the most basic design in CMOS logic, we try to equate the delay of any logic gate to that of an inverter.
- Any CMOS logic device is a combination of a pull up network of PMOS's and a pull down network of NMOS's.
- The binary operations of a logic circuit are designed as follows,

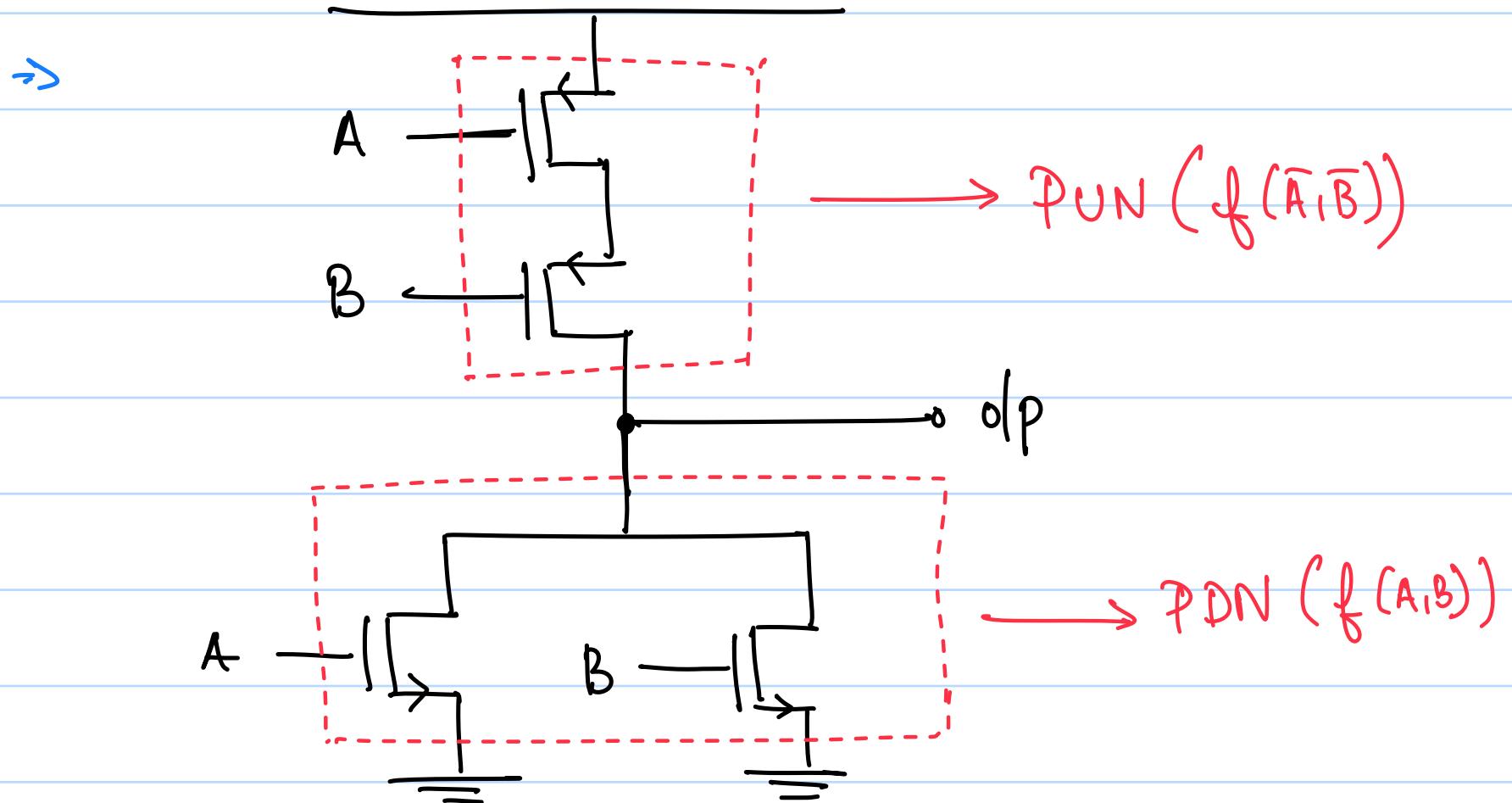


AND operation - MOSFETs in Series

OR operation - MOSFETs in Parallel

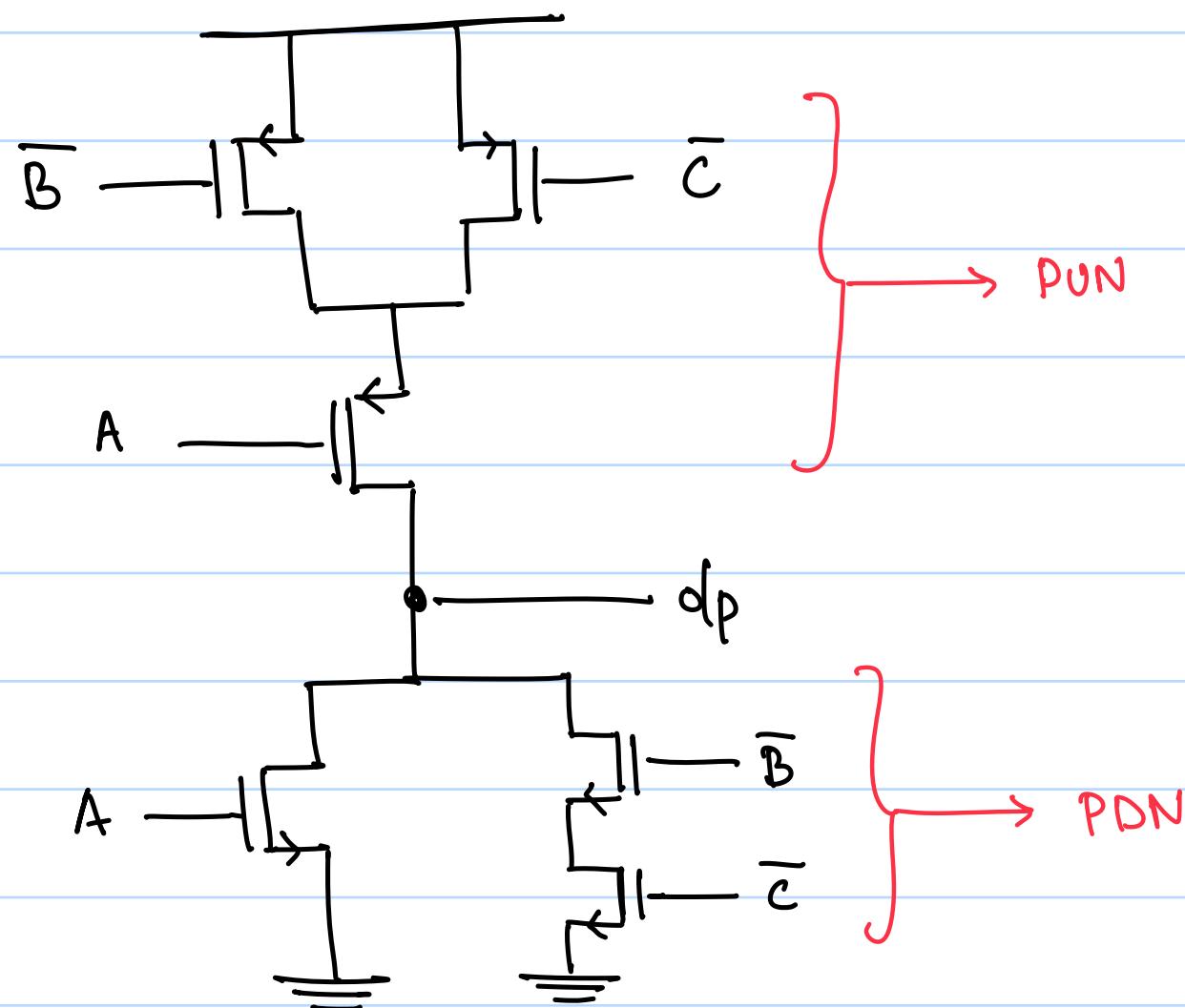
For logic $Y = \overline{A+B}$
 $\Rightarrow Y = \bar{A} \cdot \bar{B}, \bar{Y} = A + B$

(De Morgan's)



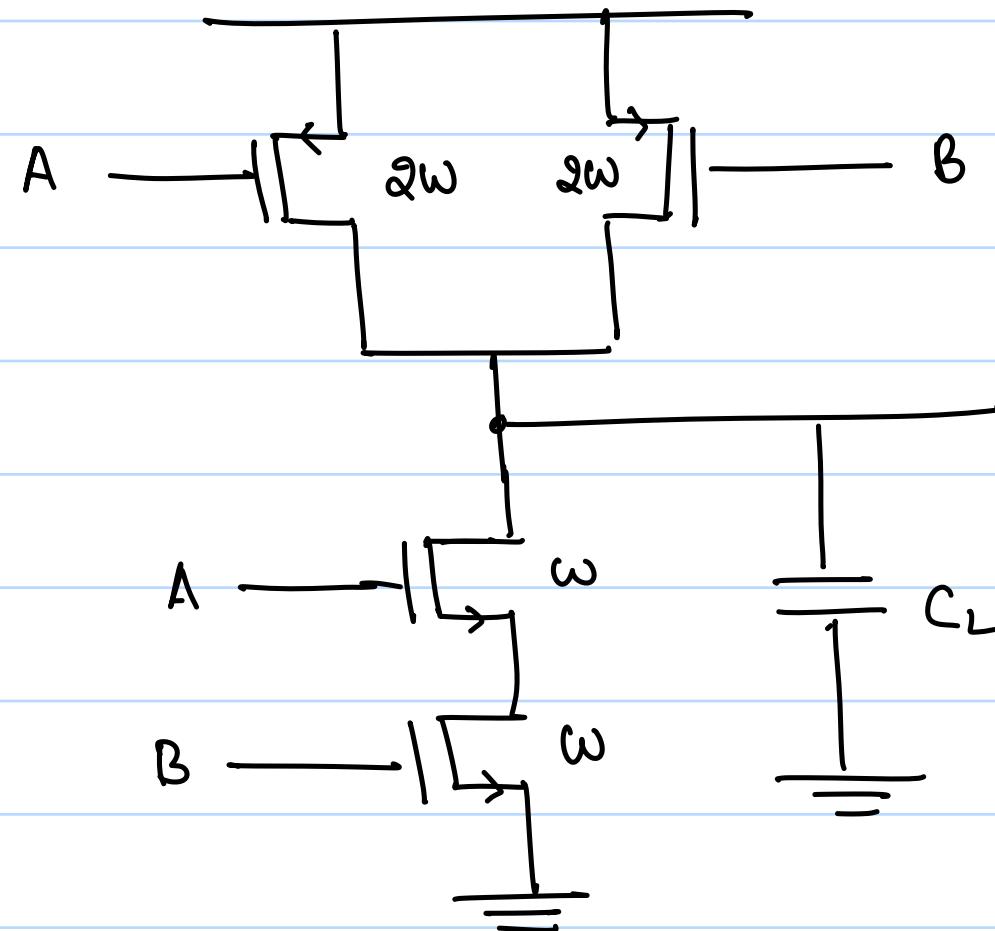
$$\text{For function } f = \bar{A}(B+C) \quad \bar{f} = A + (\bar{B} + \bar{C})$$

$$= \bar{A}(\bar{\bar{B}} + \bar{\bar{C}}) \quad = A + \bar{B}\bar{C}$$



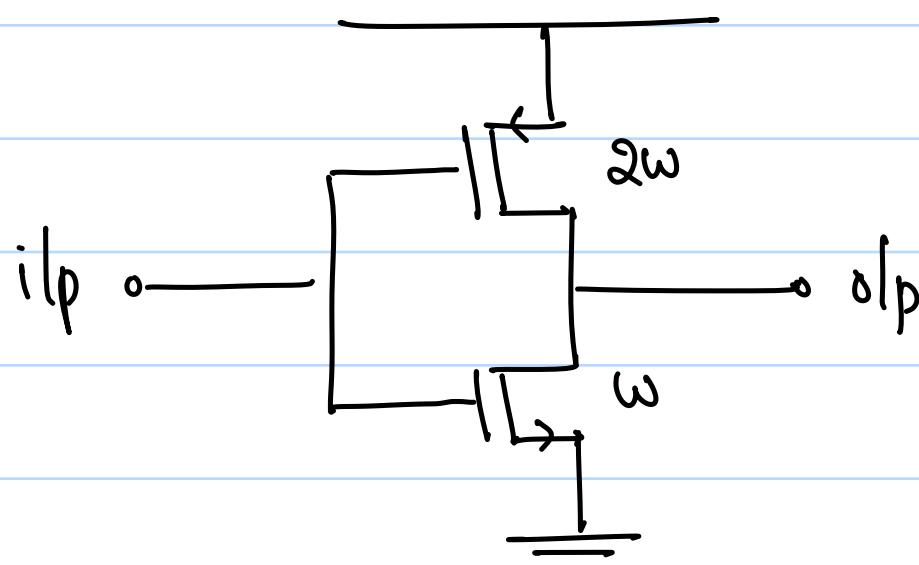
→ Delay of Combinational Circuits :-

- Take a NAND gate, with the following widths,



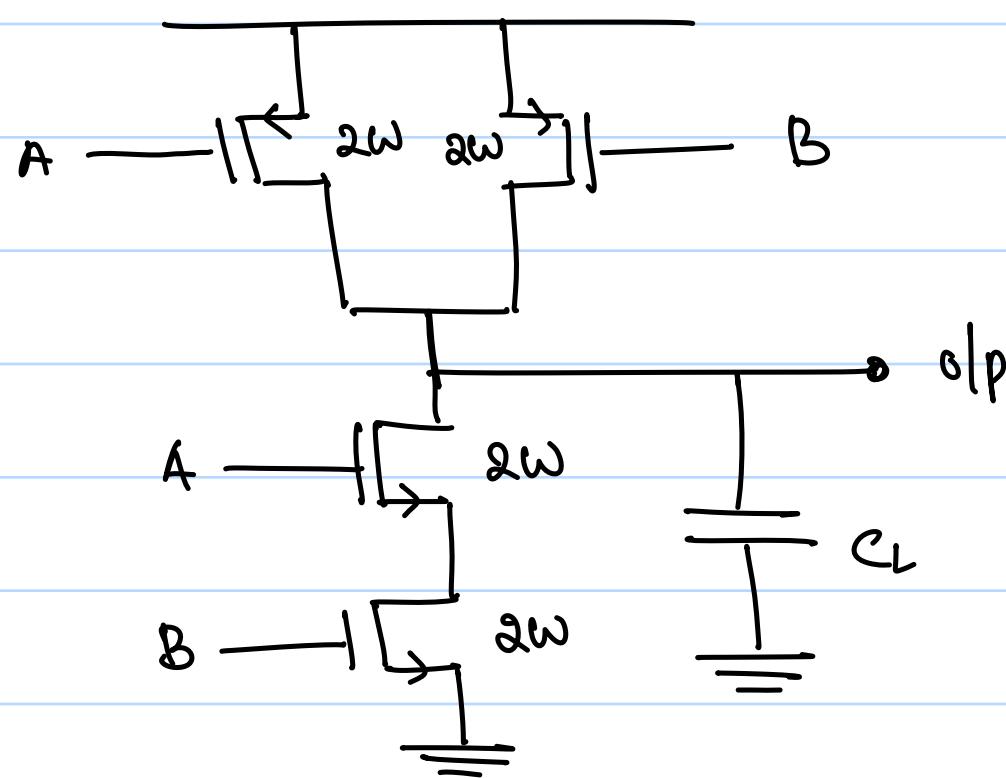
- We know that $R_{on} \propto \frac{1}{w}$ and greater the R_{on} , lower the driving capability of the device, since o/p current will be smaller.

- This can be thought of as the below inverter, for each input



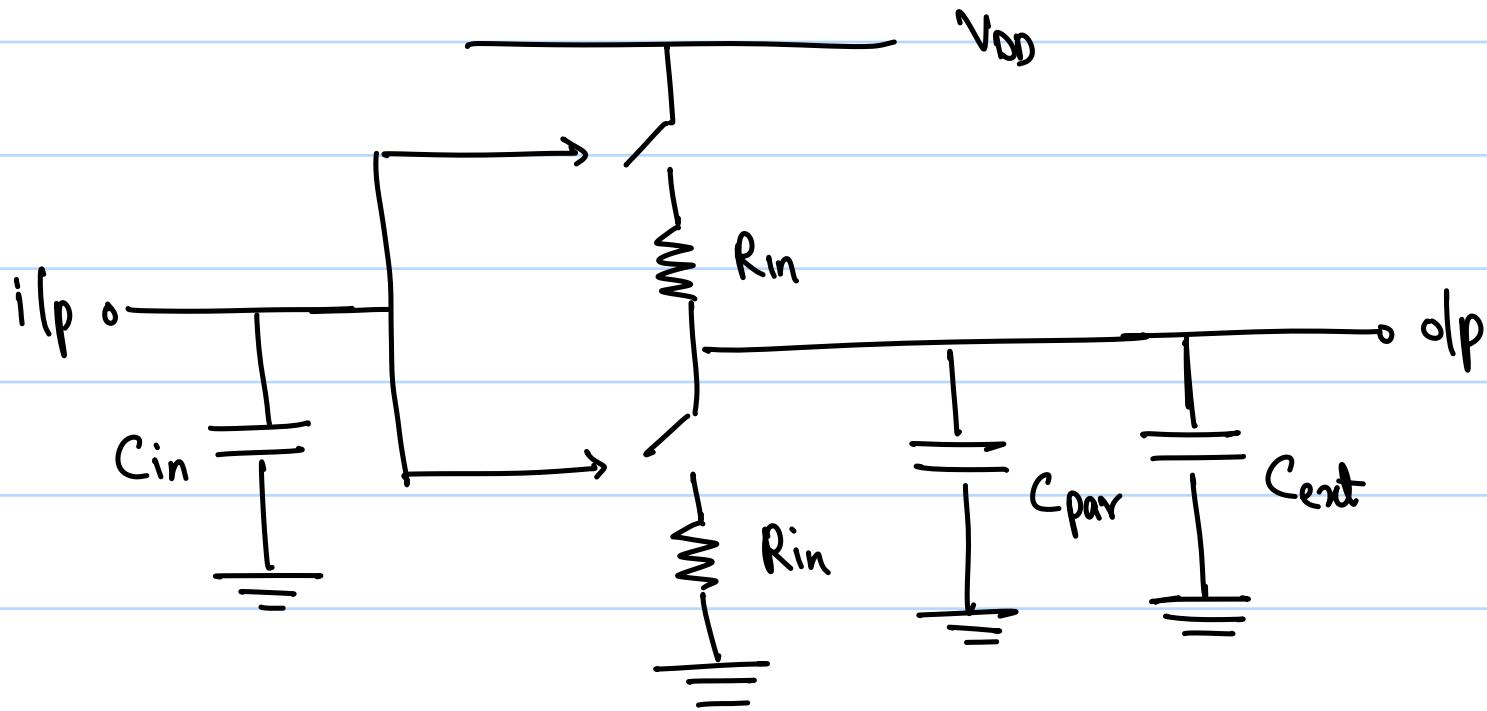
Each ilp in the NAND gate 'sees' $3w$ width of MOSFETs. In the above inverter, the ilp also 'sees' $3w$ width of MOSFETs.

- But in the NAND gate, when both the ilps are active, the PDN network's delay will be higher ($2Rc$) than the reference inverter (Rc). So to equalize delays with the reference inverter, we increase the NMOS widths to $2w$.



Here, the delays are similar to the reference inverter, but the widths 'seen' by the i/p's are higher $\Rightarrow C_{in}$ is higher.

- In our reference minimum sized inverter,



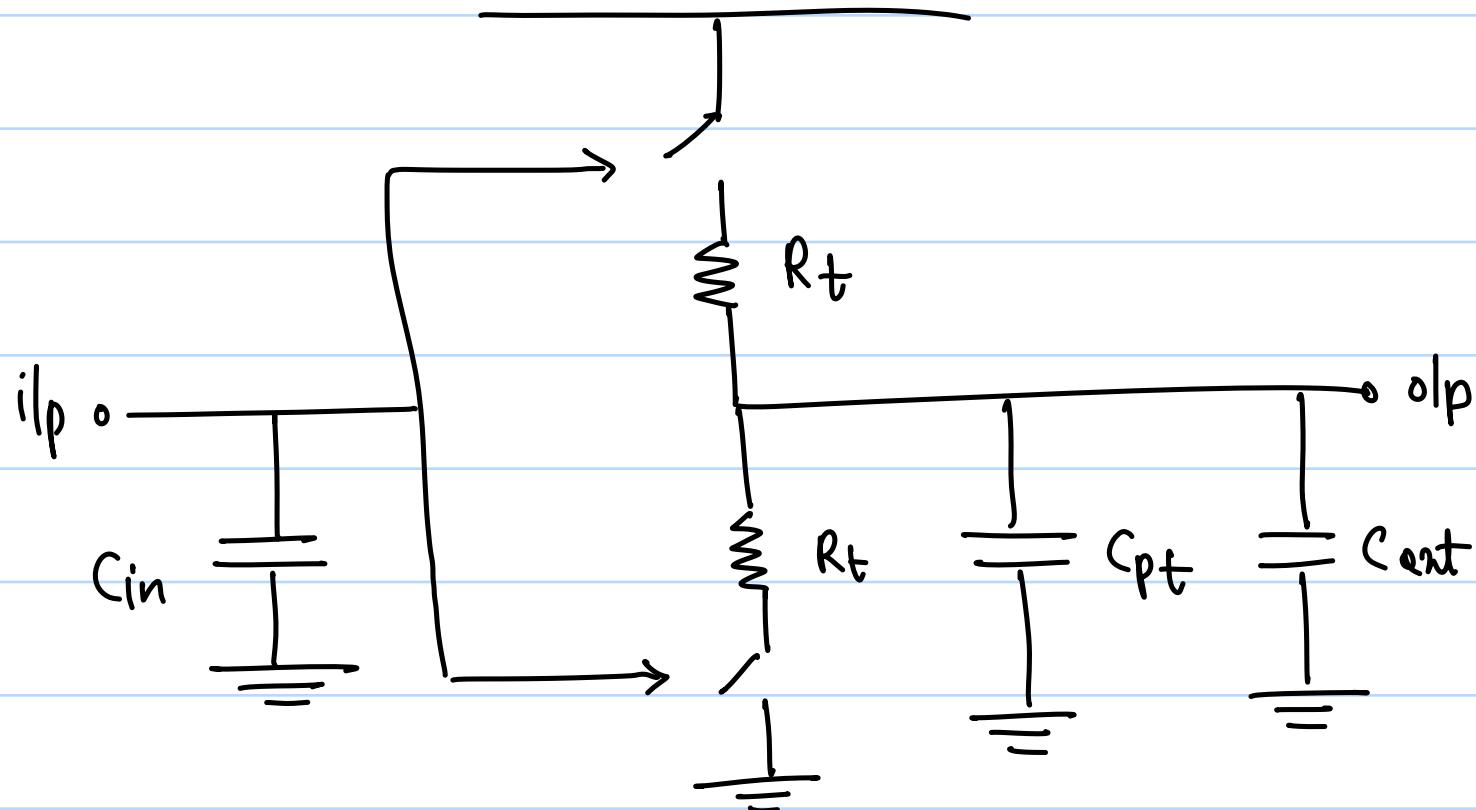
$$d_{inv} \propto R_{inv} (C_{par} + C_{ent})$$

$$\Rightarrow d_{inv} \propto R_{inv} C_{in} \left(\frac{C_{par}}{C_{in}} + \frac{C_{ent}}{C_{in}} \right)$$

$$\Rightarrow d_{inv} = \tau \left(\frac{C_{par}}{C_{in}} + \frac{C_{ent}}{C_{in}} \right)$$

$$\Rightarrow d_{inv} = \tau (p+1) \quad \left[\frac{C_{par}}{C_{in}} = p, \frac{C_{ent}}{C_{in}} = 1 \right]$$

- To understand the delay of any CMOS device, we use the following model of the PUN and PDN, for each single i/p.



$$d_{\text{logic}} \propto R_t (C_{pt} + C_{out})$$

$$= d_{\text{logic}} \propto R_t C_t \left(\frac{C_{pt}}{C_t} + \frac{C_{out}}{C_t} \right)$$

$$= d_{\text{logic}} \propto R_{\text{inv}} C_{\text{inv}} \left(\frac{R_t C_t}{R_{\text{inv}} C_{\text{inv}}} \cdot \frac{C_{pt}}{C_t} + \frac{R_t C_t}{R_{\text{inv}} C_{\text{inv}}} \cdot \frac{C_{out}}{C_t} \right)$$

$$= d_{\text{logic}} \propto R_{\text{inv}} C_{\text{inv}} \left(\frac{R_t C_t}{R_{\text{inv}} C_{\text{inv}}} \cdot \frac{C_{out}}{C_t} + \frac{R_t C_{pt}}{R_{\text{inv}} C_{\text{inv}}} \right)$$

$$\Rightarrow d_{\text{logic}} = \tau \left(\underbrace{\frac{R_t C_t}{R_{\text{inv}} C_{\text{inv}}} h}_{g} + \rho_{\text{logic}} \right) \quad [\tau \text{ is the same as in inverter. }]$$

$$\Rightarrow d_{\text{logic}} = \tau (gh + \rho_{\text{logic}})$$

Where $g = \text{Logical Effort} = \frac{R_t C_t}{R_{\text{inv}} C_{\text{inv}}}$

τ is the same since it is a technology-dependent parameter.

The term gh is denoted as the stage effort.

- In a multi-stage device, $d = \tau(gh + f)$ b - branching effort
- Logical Effort 'g':
- We know that if my reference inverter is seeing $3W$ switch of MOSFET, my NAND gate must be seeing $4W$ switch of MOSFET.
- $g = \frac{R_t C_t}{R_{inv} C_{inv}}$

In our NAND gate example, we tried to make $R_t = R_{inv}$

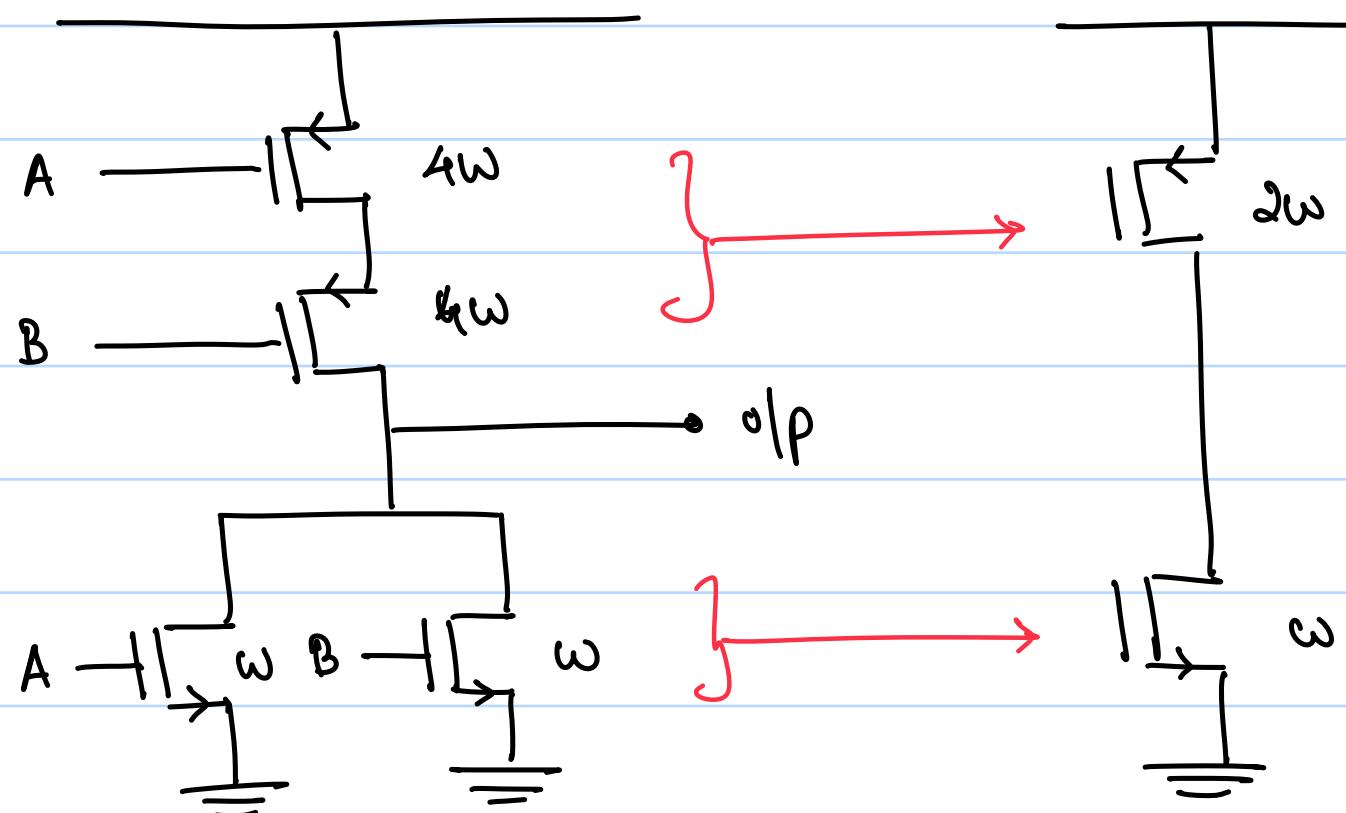
$$\Rightarrow g = \frac{C_t}{C_{inv}}, \quad C_t \propto 4W \text{ and } C_{inv} \propto 3W,$$

$$\Rightarrow g = \underline{\underline{\frac{4}{3}}}$$

$\therefore g$ can be thought of as the ratio required between the CMOS device and the reference inverter, in order to have similar driving capabilities.

- The widths must be calculated for worst case scenario, when only one of the ilp's is active. (lessen driving current through the device)

- For a NOR gate,



$$g = \frac{4w + w}{3w} = \underline{\underline{\frac{5}{3}}}$$

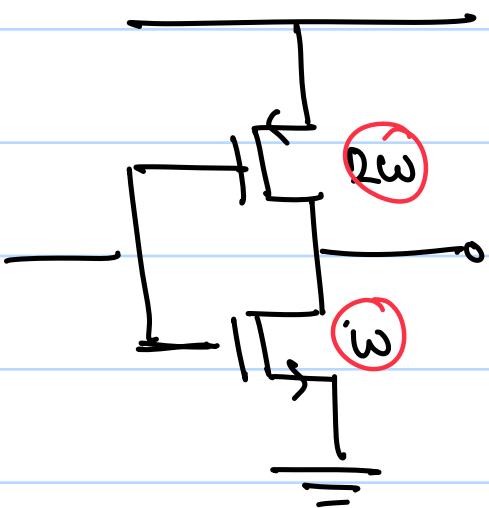
- For n-ilp NAND gate, $g = \frac{n+2}{3}$
- " " NOR gate, $g = \frac{2n+1}{3}$

- The parasitic delay is proportional to the width seen at the o/p

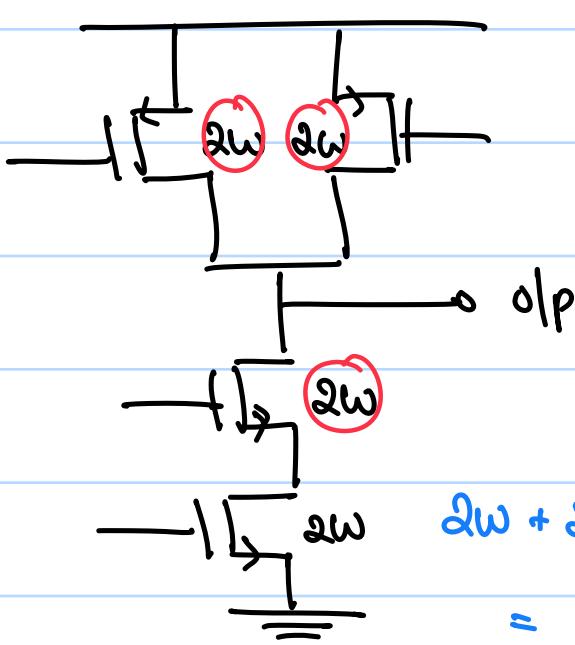
$$\tau_{\text{inv}} \propto 3w$$

$$\tau_{\text{NAND}} \propto 6w$$

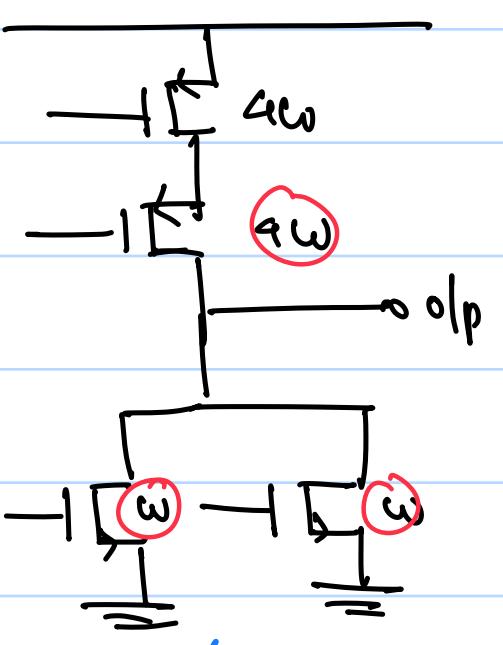
$$\tau_{\text{NOR}} \propto 6w$$



$$2w + w = 3w$$



$$2w + 2w + 2w = 6w$$

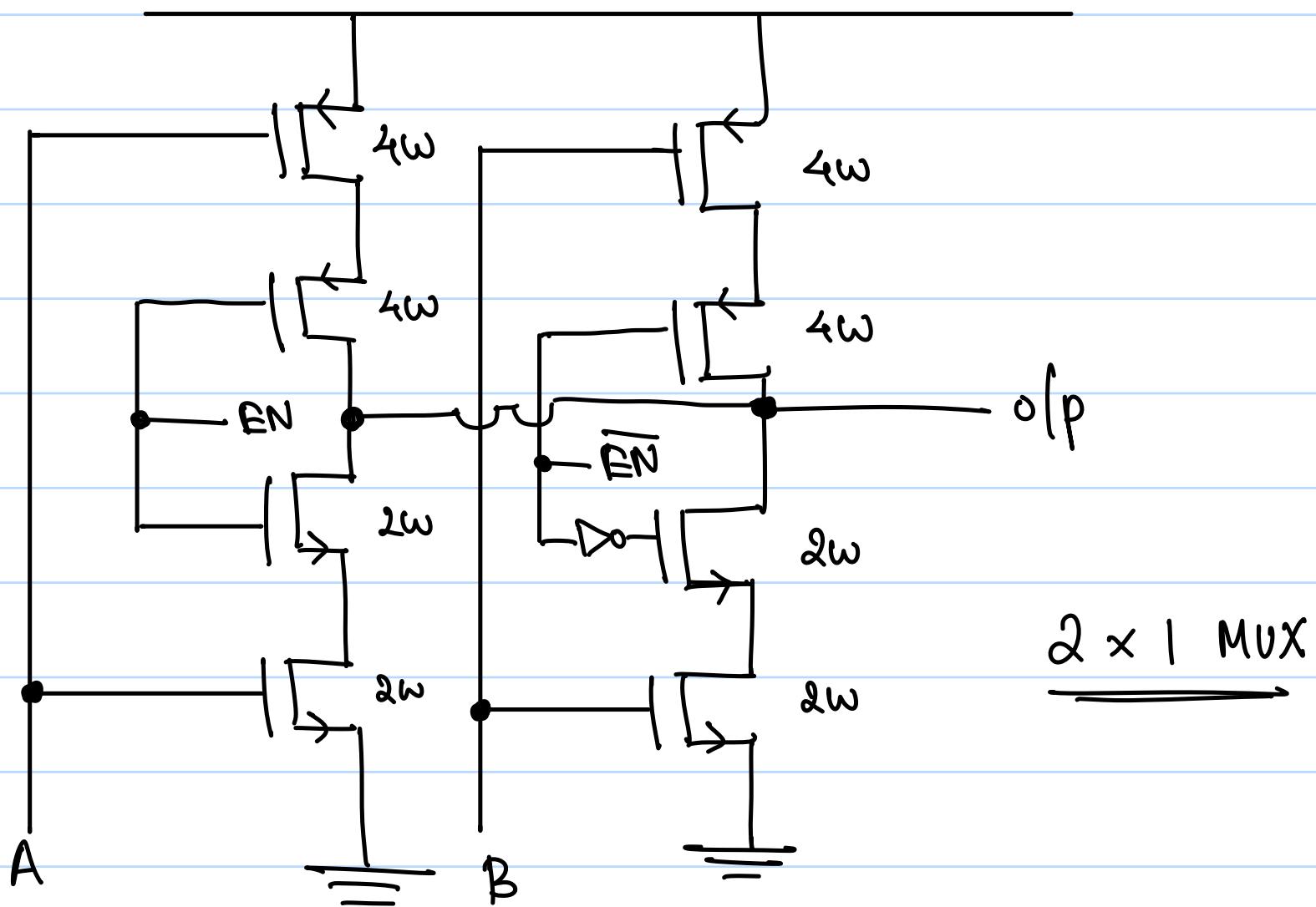


$$4w + w + w = 6w$$

$$f_{N-NOR} = N \cdot f_{inv}$$

$$f_{N-NAND} =$$

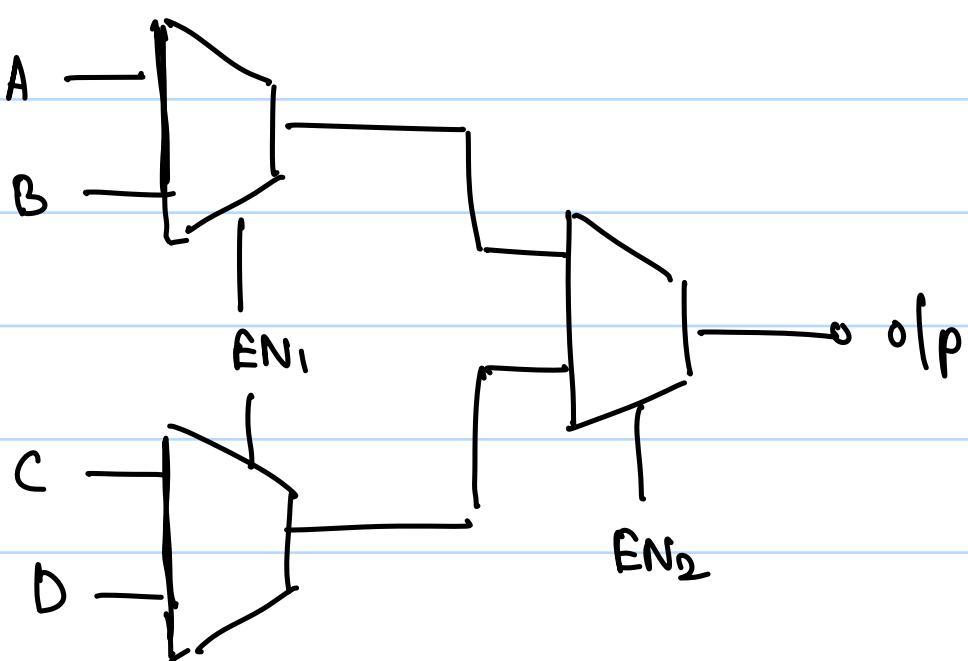
o



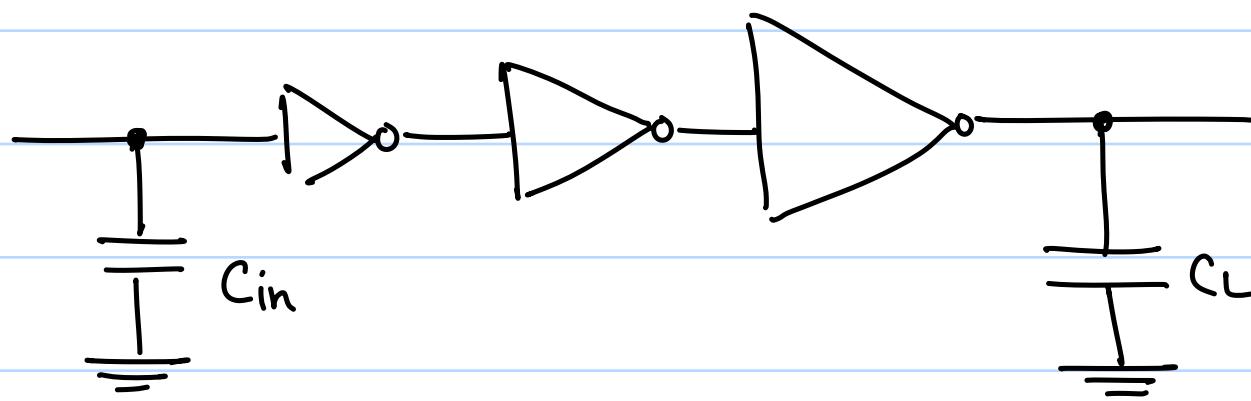
$$g_{2 \times 1 \text{ MUX}} = \frac{4W + 4W}{2W + 2W} = \underline{\underline{2}}$$

$$f_{2 \times 1 \text{ MUX}} \propto (4W + 2W)2 = 12W = 4f_{inv}$$

o We can make a 4×1 MUX by,



Recap:



- $\frac{K\tau}{c} = \text{const} \Rightarrow \tau \propto \frac{c}{K}$

- $d_i = \tau(h_i + \rho) = \tau \left(\frac{\text{Const}}{C_{in-i}} + \frac{C_{self}}{C_{in}} \right)$
 $= \tau \left(\frac{C_{in-inv2}}{C_{in-inv1}} + \rho_{inv} \right)$

- $C_{in-inv} = C_{GDP} + C_{ADn} + C_{DBn} + C_{DBp} \propto C_{ox}WL$

- $D = N\tau(H^{1/N} + \rho), H = \frac{C_L}{C_{in}}$

- To minimize delay, $h_1 = h_2 = h_3 \dots = h_N = H^{1/N}$,

h_i is the solution of $x \ln x - x = \rho \rightarrow h_i = \frac{w_{i+1}}{w_i}$

$$N = \ln H / \ln x = \ln H / \ln h_i$$

- If $N \uparrow, H^{1/N} \downarrow \Rightarrow h_i \downarrow$, but this decrease is not shown in delay due to the dominance of the $N\rho$ term.

$$D = N(H^{1/N} + \rho)\tau$$

- For multi-input combinational circuits, we analyze the delay by studying the critical path of any one of the inputs.

Critical path - path of longest delay.

- $D = (gh + p_{\text{logic}}) \tau$ All wrt to a reference min.sized inverter.

$$g = \frac{R_t C_t}{R_{\text{inv}} C_{\text{inv}}} \rightarrow \text{Keep } R_t = R_{\text{inv}} \text{ and find ratio of width}$$

to get C_t / C_{inv} .

$$h = \frac{C_{\text{ext}}}{C_t}, p_{\text{logic}} = \frac{R_t C_{\text{pt}}}{R_{\text{inv}} C_{\text{inv}}} \rightarrow \text{Proportional to the width}$$

"seen" at the op when $R_t = R_{\text{inv}}$

- Controlling delay is important when designing sequential clock-based circuits.

- $D = (gh + p_{\text{logic}}) \tau$

$\underbrace{\hspace{10em}}$ numbers \downarrow time unit

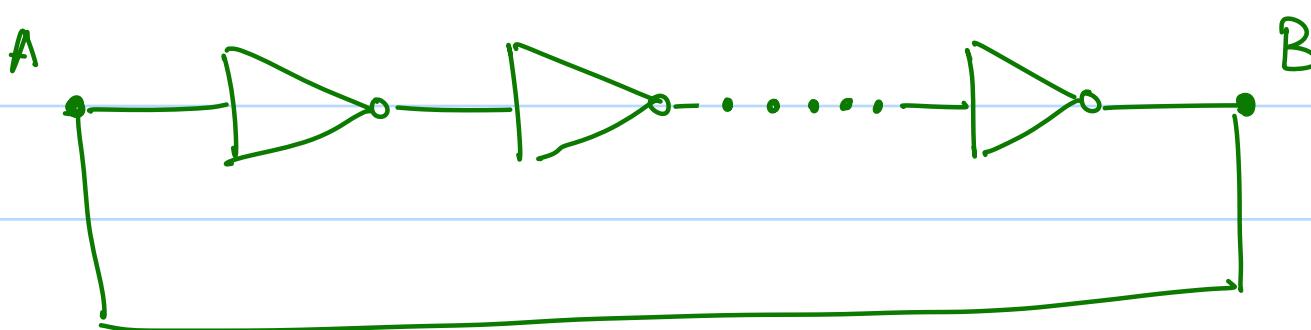
g depends on the topology of the circuit, ie, how the MOSFETs are connected.

- If we want to drive the same C_{ext} as the inverter, with the same delay as the inverter, then $C_{\text{in}} = g \times C_{\text{in-inv}}$

- If we want to keep $C_{in} = C_{in-inv}$, then the delay of the circuit will be increased.

- Overall logical effort = \sum logical effort of each flip-flop

Example: There is an N -stage Ring Oscillator, where N is odd and the inverters are identical.



Find the frequency of the ring oscillator.

$$d_i = \tau(1 + \rho)$$

$$\Rightarrow D = \sum_{i=1}^N \tau(1 + \rho) = (1 + \rho) N \tau$$

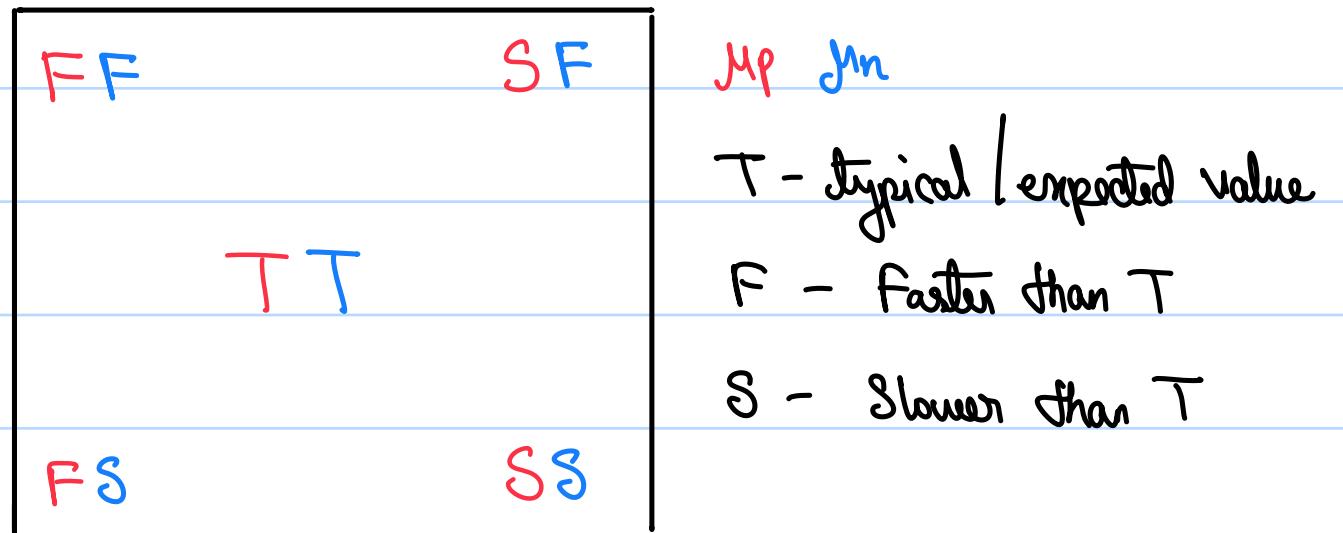
$$\Rightarrow f_{osc} = \frac{1}{T} = \frac{1}{2D} = \frac{1}{2N\tau(1 + \rho)} = \frac{1}{2Nd_i}$$

Ring Oscillator is used for parameter extraction, to get the delay of each inverter.

Large N is used since at low N , technology parameters will start to affect the frequency measured.

• Process Corners:

- Due to fabrication inefficiencies and inaccuracies, the μ_n and μ_p of the CMOS used may change, irrespective of the widths used.

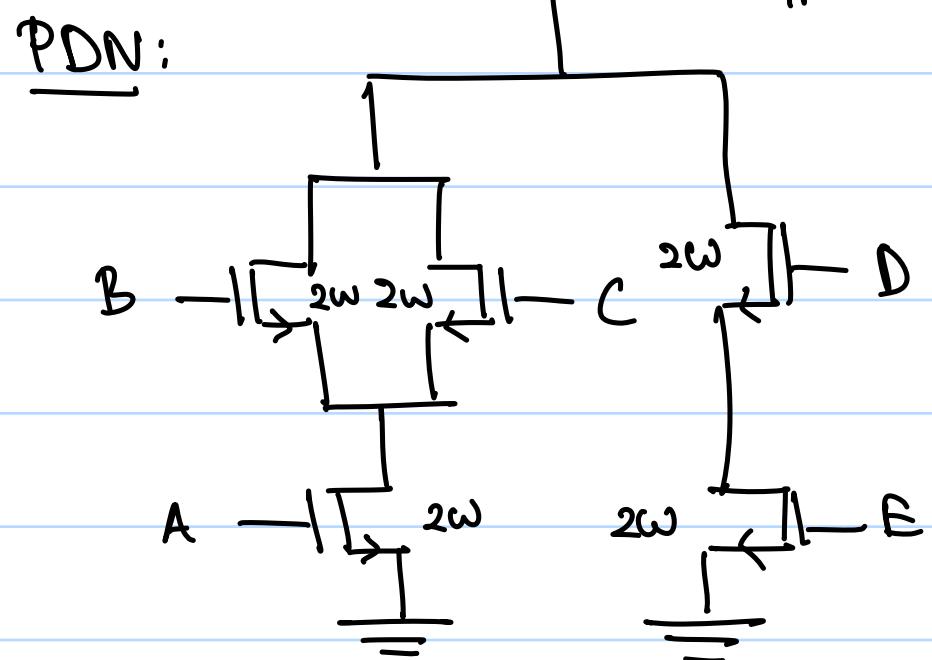
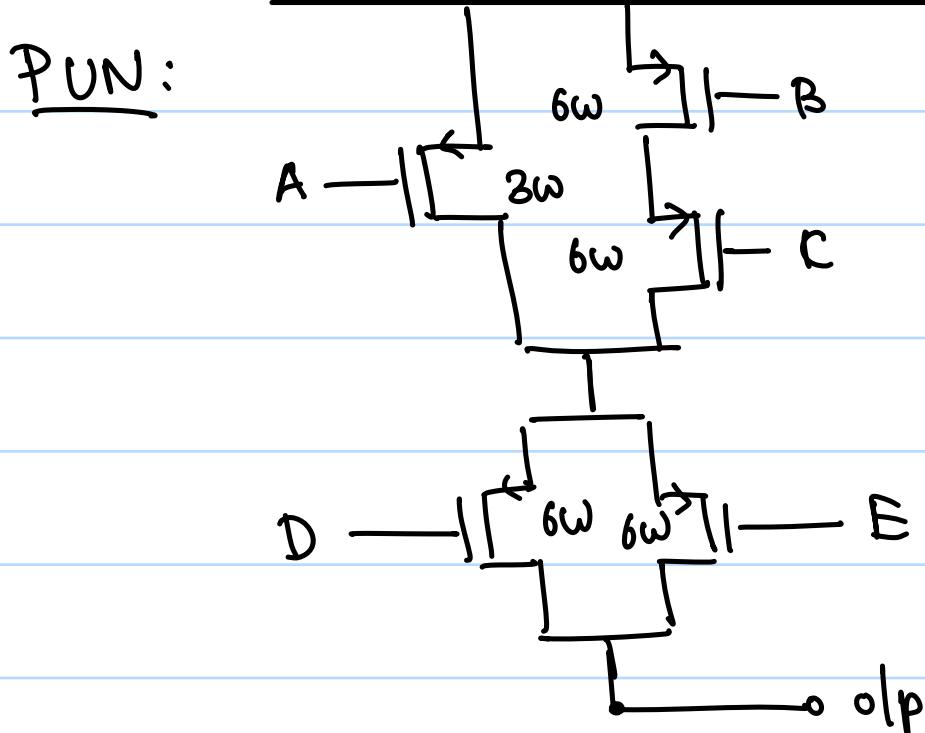


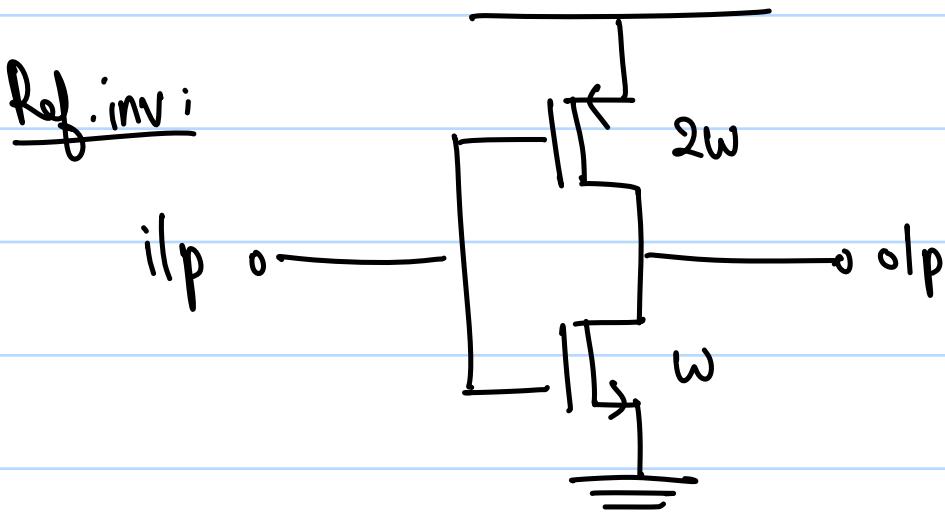
- Depending on the value of μ_n, μ_p measured, the CMOS is placed into one of the 5 regions of the above grid.

Example: Find the logical effort of each input in $Y = \overline{A(B+C) + DE}$

$$Y = \overline{A(B+C) + DE} = (\bar{A} + \bar{B} \cdot \bar{C})(\bar{D} + \bar{E})$$

$$\bar{Y} = A(B+C) + DE$$





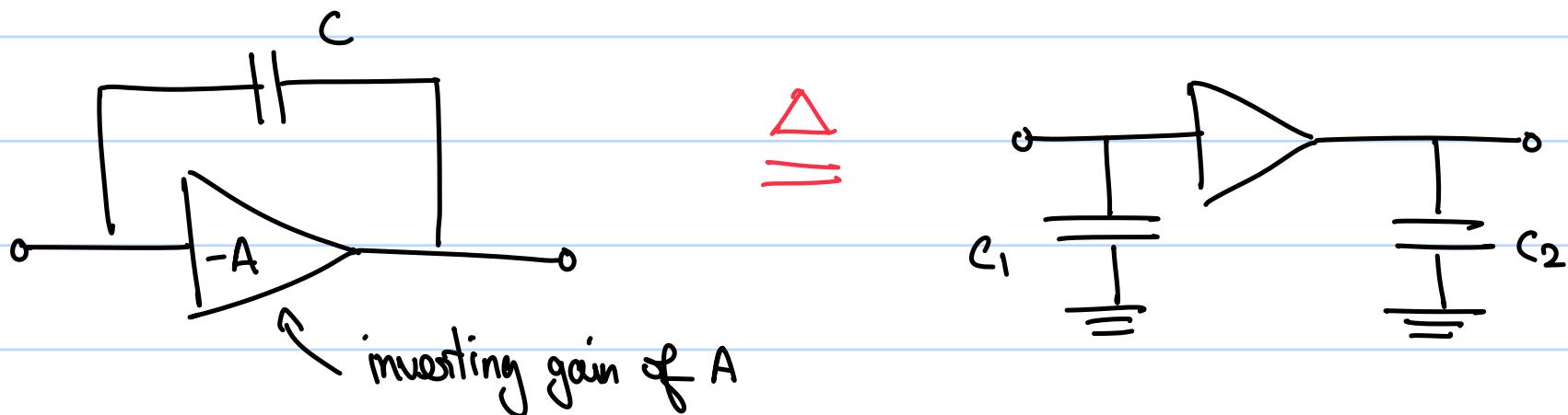
$$g_A = \frac{2w + 2w}{3w} = \frac{5}{3} \quad g_C = \frac{6w + 2w}{3w} = \frac{8}{3}$$

$$g_B = \frac{6w + 2w}{3w} = \frac{8}{3} \quad g_D = \frac{6w + 2w}{3w} = \frac{8}{3}$$

$$g_E = \frac{6w + 2w}{3w} = \frac{8}{3}$$

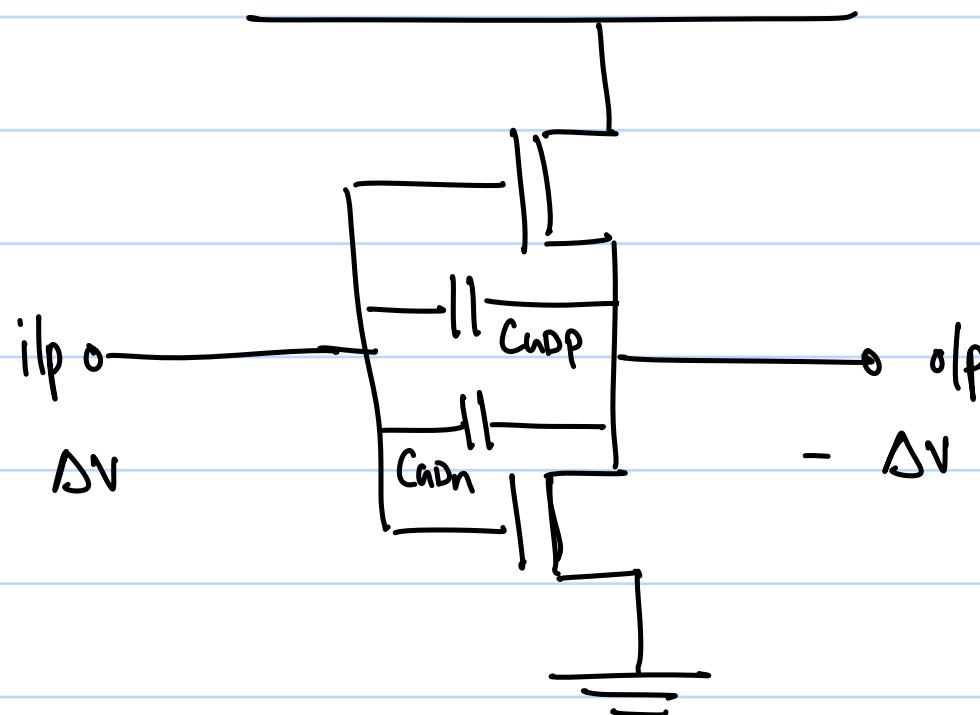
$f_{\text{logic}} \propto 18w$

Note: Miller Effect:



$$C_1 = C(1+A), \quad C_2 = C\left(1+\frac{1}{A}\right)$$

Applying Miller's effect in CMOS inverter,



$$A = \frac{\Delta V - (-\Delta V)}{\Delta V} = 2$$

$$\Rightarrow C_{ilp} = 2C_{aoN} + 2C_{apP} \quad \left. \begin{array}{l} \\ \end{array} \right\} + \text{other terms}$$
$$C_{olp} = \frac{3}{2}C_{aoN} + \frac{3}{2}C_{apP} \quad \left. \begin{array}{l} \\ \end{array} \right\} + \text{other terms}$$

→ Upcoming Topics:-

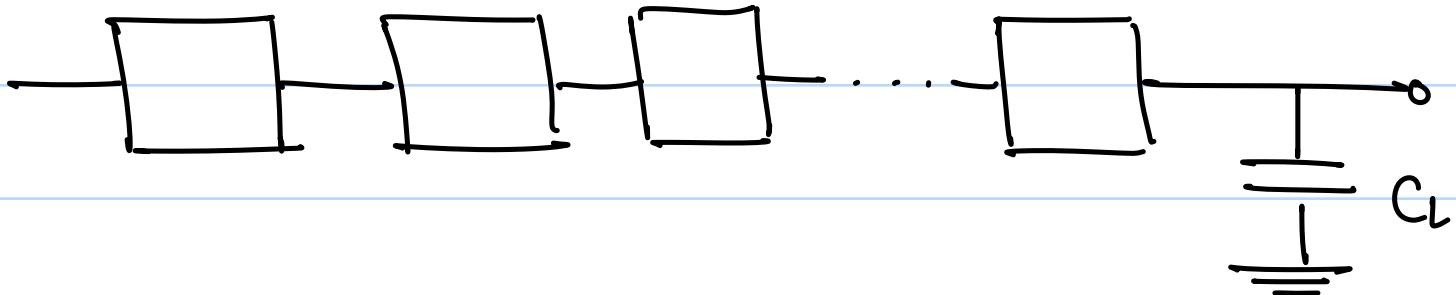
1) Logic Optimization

2) Other logic types : P-NMOS, PTL

3) Sequential Circuit fundamentals : Timing Analysis, Latches, Flip-flops, memory.

→ Multi Stage Logic :-

- Suppose we have realised the topology for a certain logic function, the algorithm to minimize delay is as follows.



$$D_i = (f_i + p_i) \tau, \quad f_i = g_i \cdot b_i \cdot h_i$$

g_i - Logical effort of i

h_i - Electrical effort of i

b_i - Branching effort of i = $\frac{\text{Con-the-path} + \text{Off-the-path}}{\text{Con-the-path}}$

$$D = D_1 + D_2 + D_3 \dots = \tau \left(\sum_i f_i + \sum_i p_i \right)$$

- The total delay is minimized when $f_1 = f_2 = f_3 \dots = f_i$

- However, the delay of each gate won't be the same as like in the buffer chain design, since f_i is not equal τ_i .

Define $G_i = \prod_i g_i$, $H = \prod_i h_i$, $B = \prod_i b_i$, then

$$\Rightarrow GBH = \prod_i f_i^N = F \rightarrow \text{path effect}$$

↓ stage effect

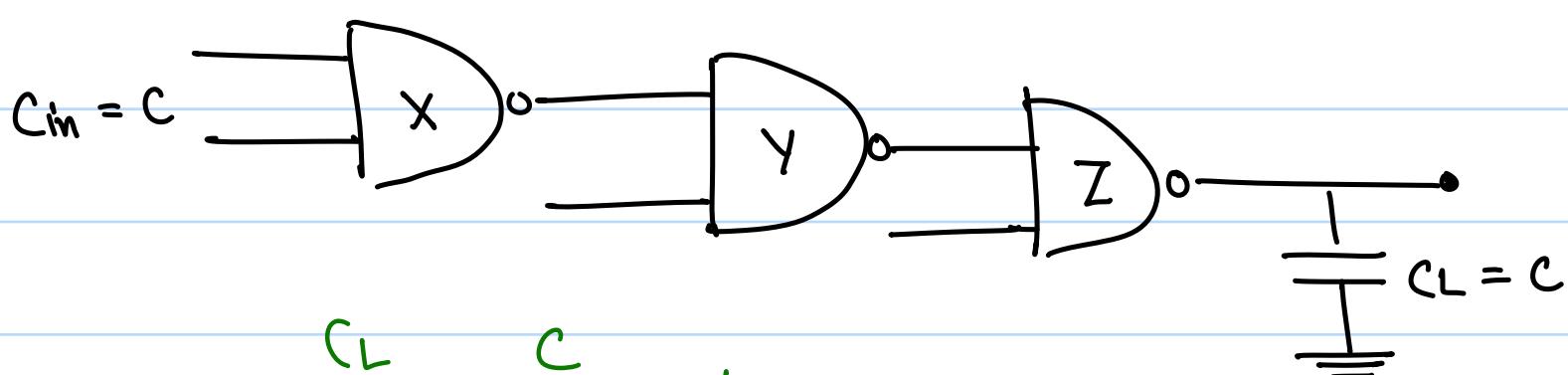
$$\Rightarrow D = (\sum f + \sum p_i) \tau$$

$$= (\hat{Nf} + \sum p_i) \tau$$

$$\Rightarrow D = (N^{1/N} + \sum p_i) \tau$$

$$\Rightarrow h_i = \frac{F^{1/N}}{g_{ibi}} \longrightarrow \text{gives us the size for each gate.}$$

Example:



Optimize delay across
this cascade of
NAND gates.

$$H = \frac{C_L}{C_{in}} = \frac{C}{C} = 1$$

$$G = \prod g_i = \frac{4}{3} \times \frac{4}{3} \times \frac{4}{3} = \frac{64}{27}$$

$$B = 1$$

$$\Rightarrow F = \frac{64}{27}, \quad f = \left(\frac{64}{27}\right)^{1/3} = \underline{\underline{\frac{4}{3}}}$$

$$h_i = \frac{4/3}{4/3 \cdot 1} = 1 + i \Rightarrow \text{All the gates have the same width}$$

$$D = (N^{1/N} + \sum p_i) \tau$$

$$= (3(\frac{4}{3}) + 6g_{inv}) \tau$$

$$\Rightarrow D = (4 + 6g_{inv}) \tau$$

Suppose $C_L = 8C$

$$H = \frac{C_L}{C_{in}} = 8$$

$$\Rightarrow F = 8 \times \frac{64}{27} \times 1 = \frac{512}{27} \Rightarrow f = \left(\frac{512}{27}\right)^{1/3} = \frac{8}{3}$$

$$h_i = \frac{\frac{8}{3}}{\frac{4}{3} \times 1} = 2 \Rightarrow \omega_y = 2\omega_x, \omega_z = 4\omega_x$$

\hookrightarrow ref. inverter size

$$D = \left(3 \times \frac{8}{3} + \sum p_i \right) \tau = \left(8 + 6p_{inv} \right) \tau$$

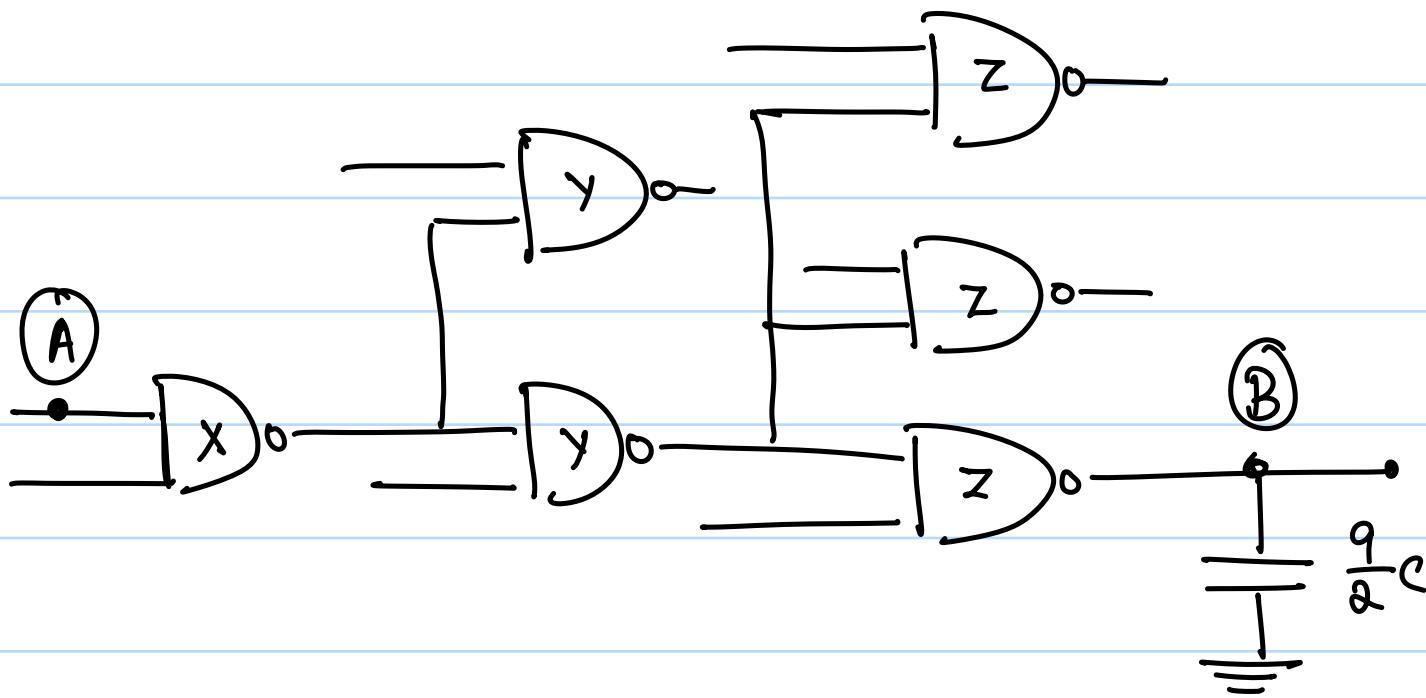
$$f = h_z \times g_z \times b_z \Rightarrow \frac{8}{3} = \frac{C_L}{C_{in-z}} \times \frac{4}{3}$$

$$C_{in-z} = \frac{C_L}{2} = 4C$$

$$h_y \times g_y = f$$

$$C_{in-y} = \frac{C_z}{2} = \frac{C_z}{2} = 2C$$

Example:



Optimize delay across A, B.

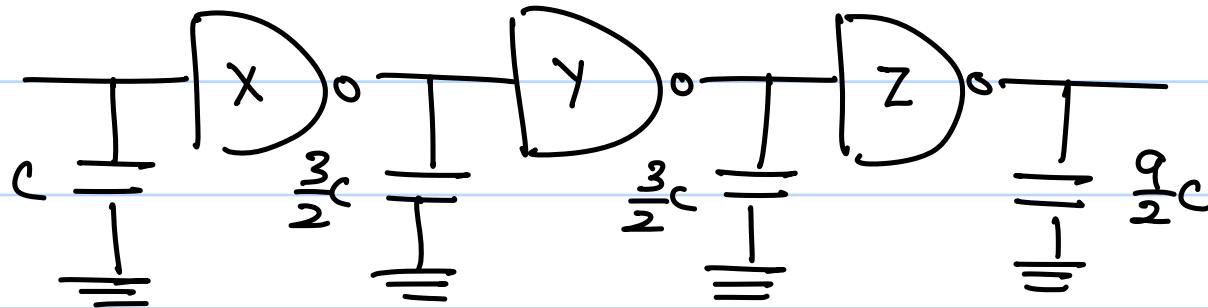
$$G_1 = \left(\frac{1}{3}\right)^3, B = 2 \times 3 \times 1 = 6, H = \frac{9}{2}$$

$$\Rightarrow F = \left(\frac{4}{3}\right)^3 \times 6 \times \frac{9}{2} = \frac{4^3 \times 9}{2^2} = \underline{\underline{4^3}}$$

$$\Rightarrow \hat{f} = 4$$

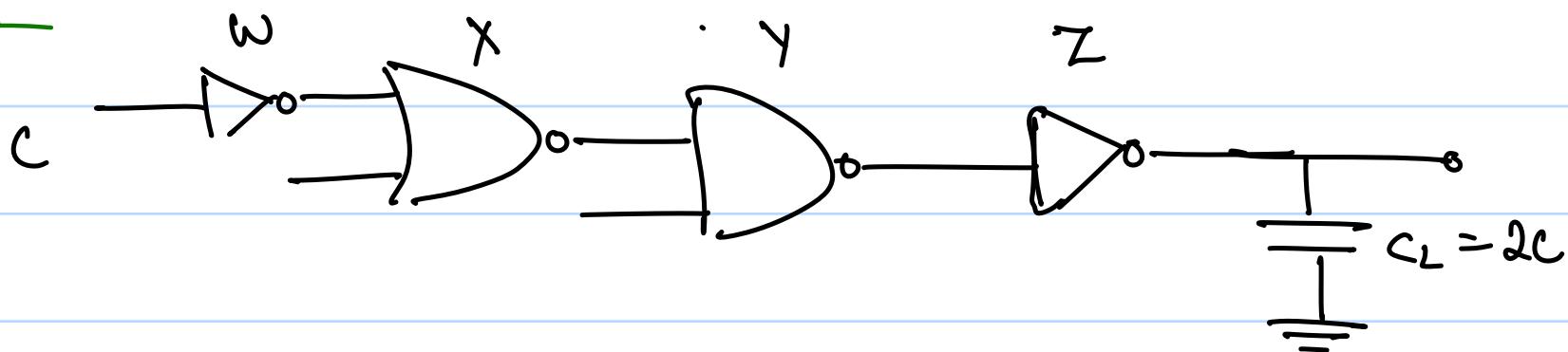
$$h_x = \frac{4}{\frac{4}{3} \times 2} = \frac{3}{2}, \quad h_y = \frac{4}{\frac{4}{3} \times 3} = 1, \quad h_z = \frac{4}{\frac{4}{3} \times 1} = 3$$

Let ref. inv of the sized ω ,



$$\therefore \omega_y = \frac{3}{2} \omega, \quad \omega_z = \frac{3}{2} \omega$$

Example:



$$H = 2$$

$$G = 1 \times \frac{5}{3} \times \frac{4}{3} \times 1 = \frac{20}{9} \quad h_w = \frac{1.452}{1 \times 1} = 1.452$$

$$B = 1 \quad h_x = \frac{1.452}{\frac{5}{3} \times 1} = 0.871$$

$$\Rightarrow F = \frac{40}{9} \Rightarrow f = \underline{1.452}, \quad h_y = \frac{1.452}{\frac{4}{3} \times 1} = 1.089$$

$$D = \left(4 \left(\frac{40}{9} \right)^{1/4} + \sum p_i \right) \tau \quad h_z = \frac{1.452}{1 \times 1} = 1.452$$

$$= \left(4 \times 1.452 + 6 f_{inv} \right) \tau \Rightarrow \omega_x = 0.871 \omega$$

$$\omega_y = 0.949 \omega$$

$$\omega_z = 1.378 \omega$$

Example: Given $C_{in} = C$, $C_{out} = 25C$, $f_{pin} = 1$, then for values of N will the buffer chain be minimized. $N = 1, 3, 5$.

$$D = N(F)^{1/N} + Nf_{pin} = N(F^{1/N} + 1)$$

$$F = 25, \Rightarrow D = N(25^{1/N} + 1)$$

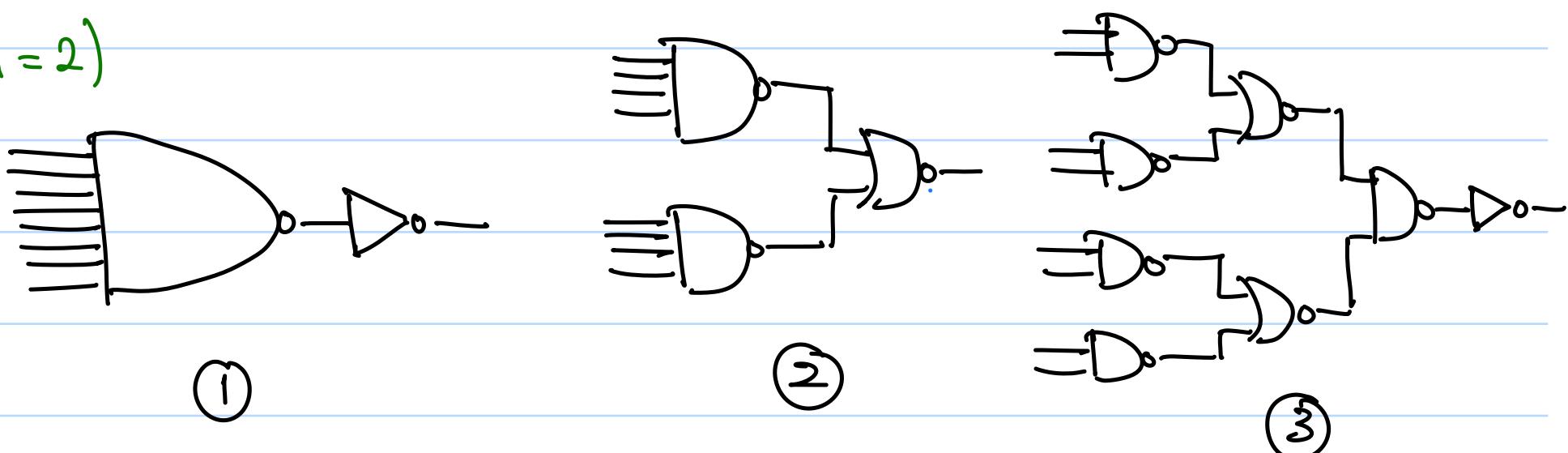
$$D_1 = 26$$

$$D_3 = 3(25^{1/3} + 1) = 3(3.924) = 11.772$$

$$D_5 = 5(25^{1/5} + 1) = 5(2.904) = 14.52$$

Example: 3 implementation of an 8 ilp AND gate are as below.

(Let $m = 2$)



Check which implementation has the lowest delay for $H = 1, 10, 100$ and discuss the sizing of the gates.

Arrangement 1,

$$F = GBH \Rightarrow F = \frac{10}{3}H$$

$$G = \frac{8+2}{3} = \frac{10}{3}$$

$$B = 1,$$

$$D = \left(\frac{10}{3}H\right)^{1/2} + \sum f_i = \frac{10}{3}H + 9$$

Arrangement 2,

$$G = \left(\frac{4+2}{3}\right) \left(\frac{5}{3}\right) = \frac{30}{9}$$

$$\begin{aligned} B &= 1 \\ \Rightarrow F &= \frac{30}{9} H \quad \Rightarrow D = 2 \left(\frac{30}{9} H\right)^{1/2} + 2(4+2) \\ &\qquad\qquad\qquad D = 2 \left(\frac{30}{9} H\right)^{1/2} + 12 \end{aligned}$$

Arrangement 3,

$$G = \frac{4}{3} \times \frac{5}{3} \times \frac{4}{3} = \frac{80}{27}$$

$$\begin{aligned} B &= 1 \\ \Rightarrow F &= \frac{80}{27} H \quad \Rightarrow D = 4 \left(\frac{80}{27} H\right)^{1/4} + 4(2+2+2+1) \\ &\qquad\qquad\qquad = 4 \left(\frac{80}{27} H\right)^{1/4} + 28 \end{aligned}$$

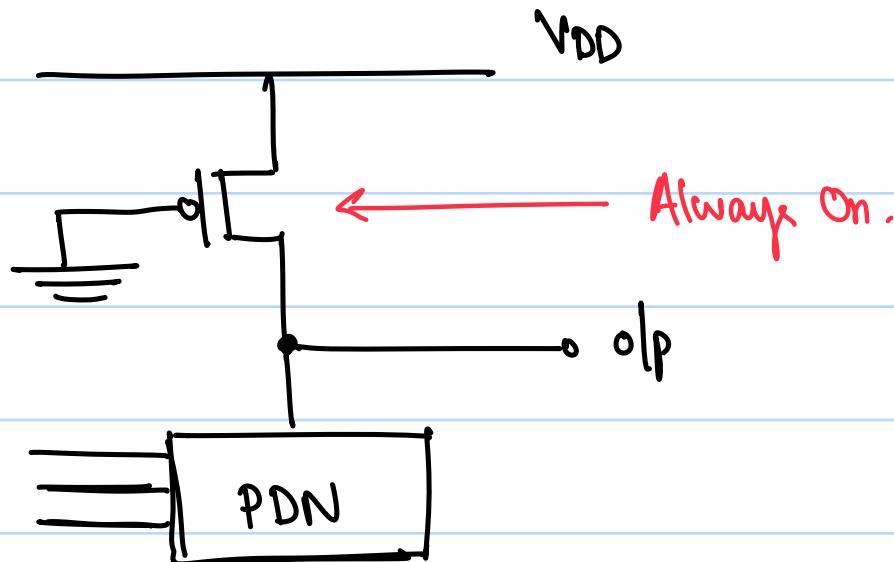
D/H	1	10	100
①	10.82	14.77	27.25
②	15.65	23.54	48.51
③	33.24	37.33	44.59

* Other Logic Styles :-

Static Logic Styles

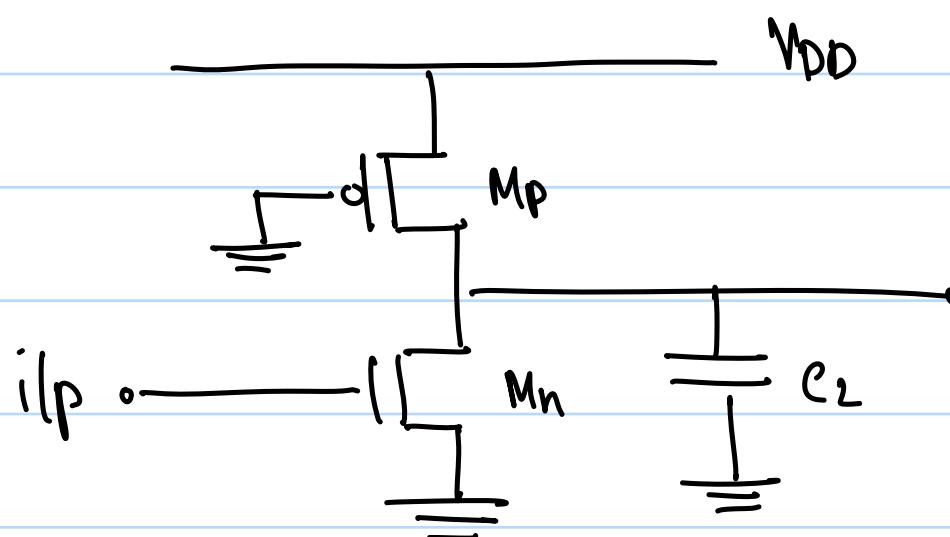
Cmos Pseudo-NMOS Pass Transistor Logic Cascaded Voltage Sw. Logic
pNMOS (or Complement PTL)
PTL, CPTL/CPL CNVL

→ Pseudo - NMOS :-

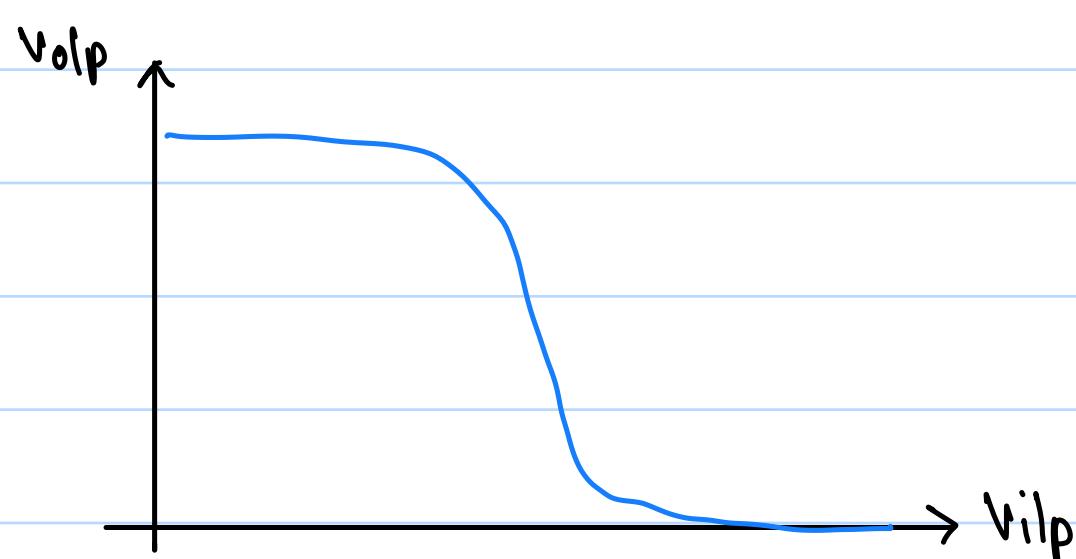


- The PDN is just one PMOS transistor which is always on.

• p-NMOS Inverter :-



- When i_{lp} is low, M_N is off and C_L will get charged through M_P , giving us a high o_{lp} at the end at steady state.
- When i_{lp} is high and M_N can give large current draw, the load C_L is discharged, giving us a low o_{lp} at the end at steady state.

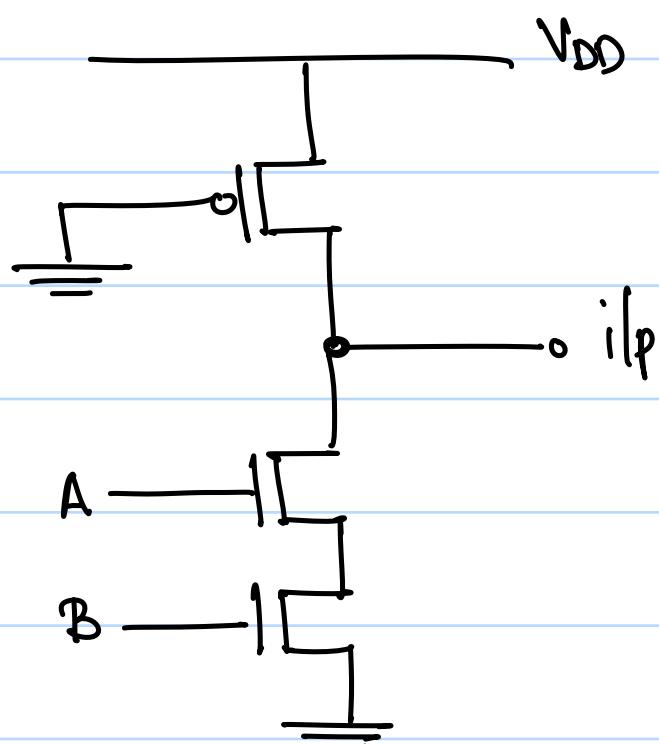


- This inverter is similar to a CMOS inverter, so parameters like Noise Margin, Delay, etc can be extracted through a similar process as in static CMOS style.
- In static CMOS design, the widths of the PMOS and NMOS can be anything, if symmetric delay is not required. There will be no difference in the logical operation. So CMOS style is a statistics style.

However in p-NMOS style, there is a strict lower bound on the width of the NMOS, with respect to the width of the PMOS. ($w_n > w_p$), so p-NMOS is graded style.

- The design of the PDN network follows the same procedure as in CMOS style.

p-NMOS 2inp NAND gate :



- Since the PDN network is just one PMOS transistor, the area of our circuit decreases, due to the absence of the PMOS stack.

- But due to the much higher width of the NMOS, C_{in} can be higher than in CMOS style.

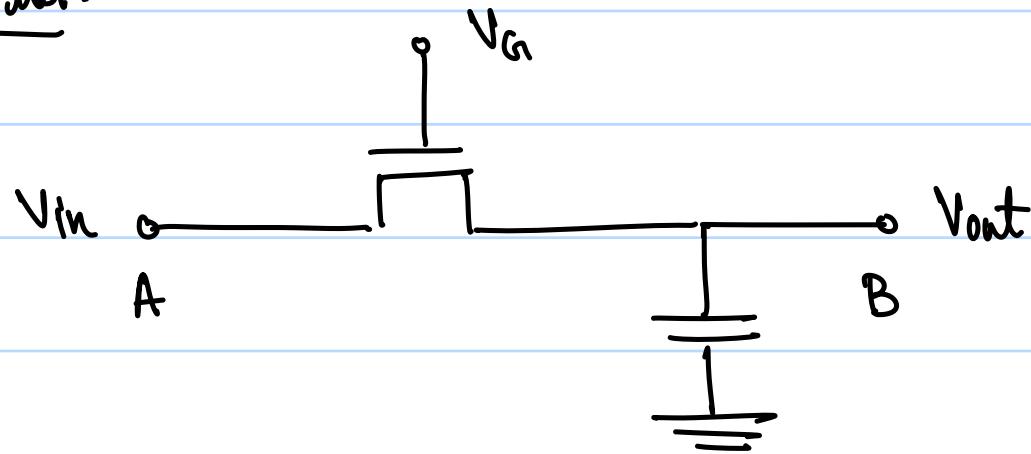
Also, since the PMOS is always on, static power consumption is non-zero. (when i_{lp} is high)

- p-NMOS is used in devices that stay at a certain logic level most of the time, ex: Reset circuit.

- Pass Transistor Logic / Complementary Pass Transistor Logic :-

- A MUX based logic style.

- Pass Transistor:

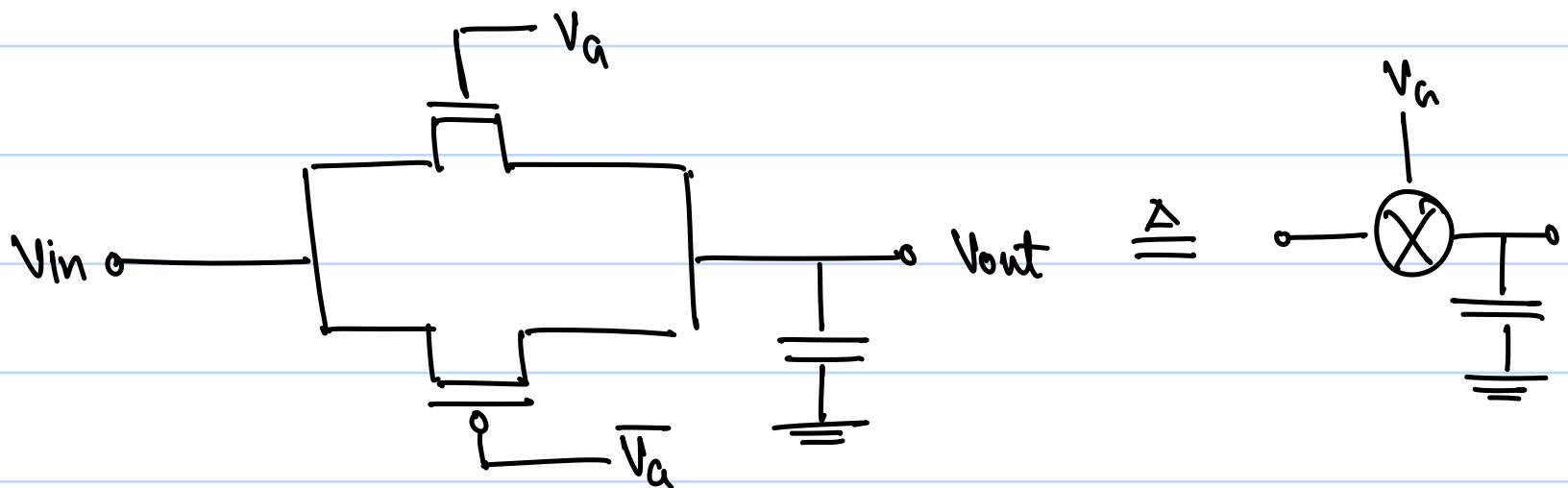


In the above circuit, at high V_G , if $V_{in} = 0$, $V_{out} = 0$ and if $V_{in} = V_{DD}$, $V_{out} = V_{DD} - V_{TN}$

Similarly if a PMOS is used, at low V_G , if $V_{in} = V_{DD}$, $V_{out} = 0$ and if $V_{in} = 0$, $V_{out} = |V_{TP|}$

So in a NMOS, PMOS pass transistor circuit, the logic levels are not proper high and low, either one of the MOS is non-ideal.

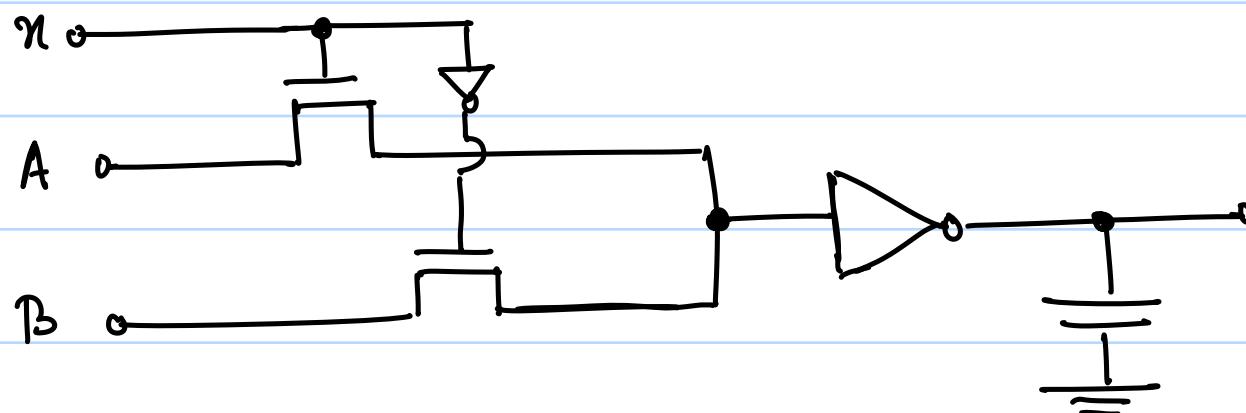
Therefore a Complementary Pair Transistor Gate is used,



Using a CPTL consumes more area than p-NMOS and CMOS, creating higher parasitics and increasing circuit complexity. Also, the usage of complementary controls (V_a and \bar{V}_a) also adds complexity.

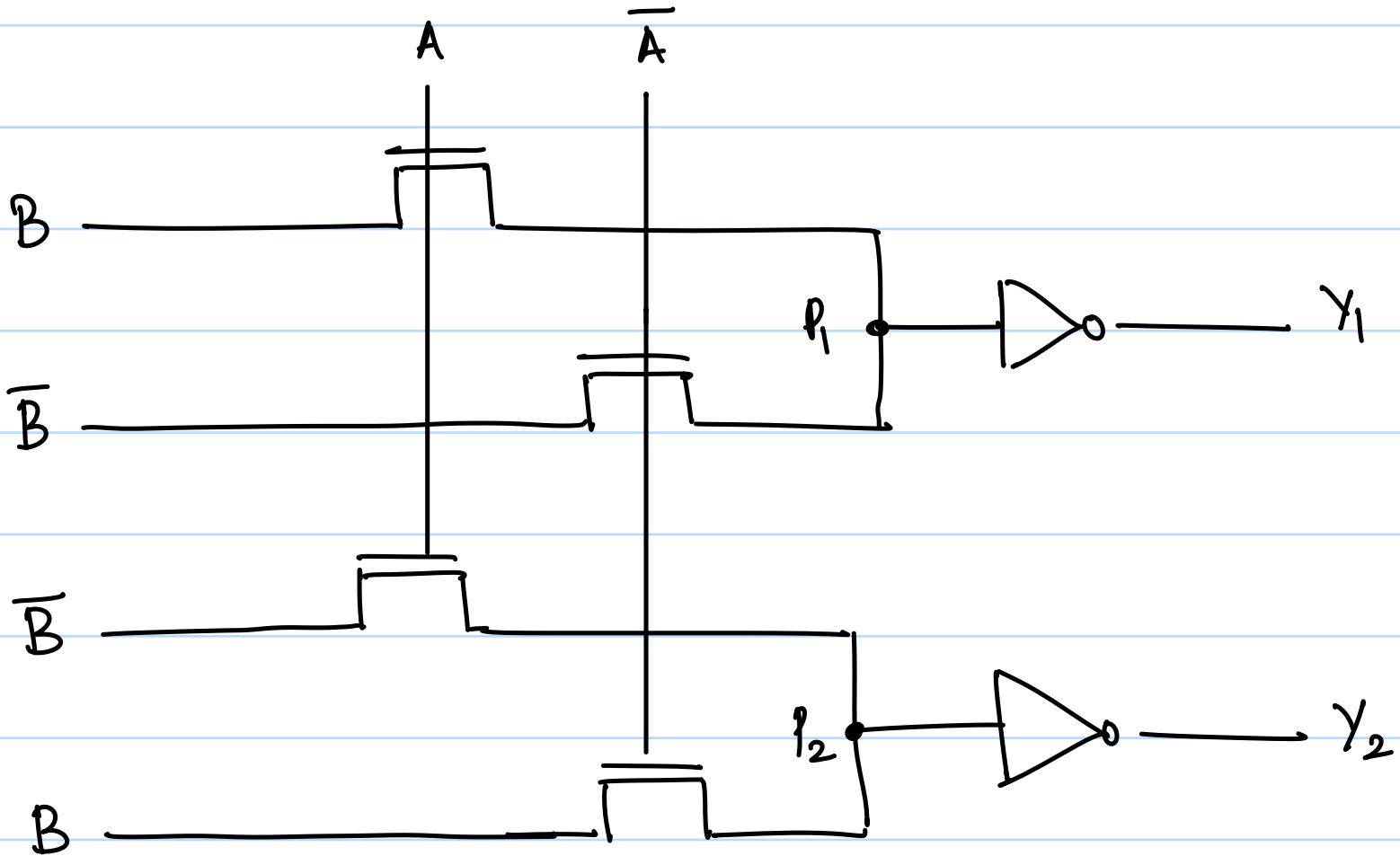
We can also use a CMOS inverter to invert the logic levels, in an NMOS / PMOS pass transistor, due to the idea of noise margin.

- Implementing logic functions in PTL :-



- The above circuit is an example of an inverting 2×1 MUX, with inputs A, B and selection line X.

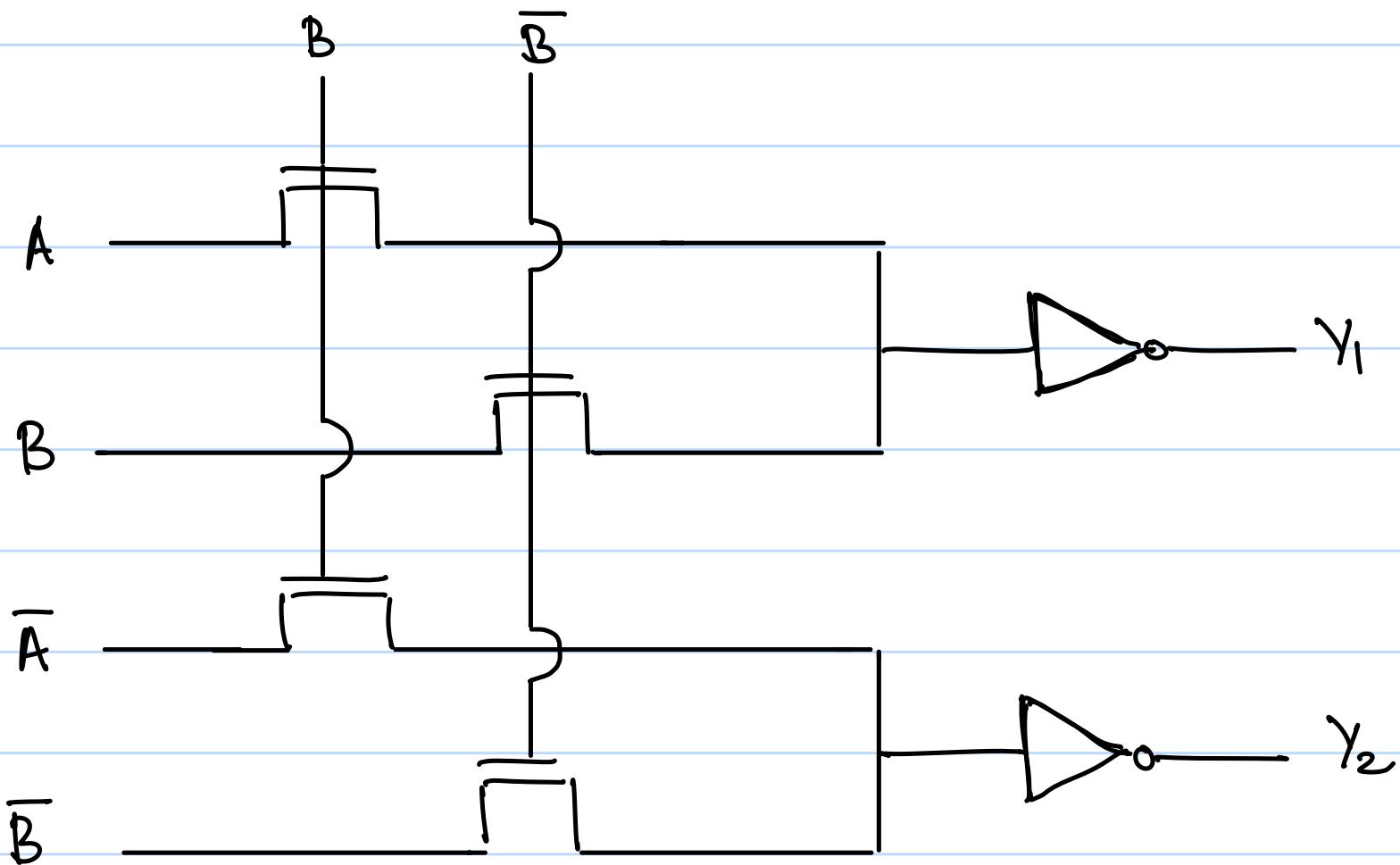
• By Shannon's expansion, any logic function can be implemented on a combination of MUXes.



$$\begin{aligned} P_1 &= AB + \bar{A}\bar{B} \xrightarrow{\text{XNOR}} \gamma_1 : \text{XOR} \\ P_2 &= \bar{A}\bar{B} + \bar{A}B \xrightarrow{\text{XOR}} \gamma_2 : \text{XNOR} \end{aligned}$$

This implementation of XOR and XNOR are much more efficient than CMOS topologies.

Since XOR and XNOR are the building blocks of arithmetic blocks like Adder and Multiplier, such topologies can vastly increase the efficiency of the design.



$$Y_1 = (AB + B\bar{B})^I = (AB)^I : \underline{\text{NAND}}$$

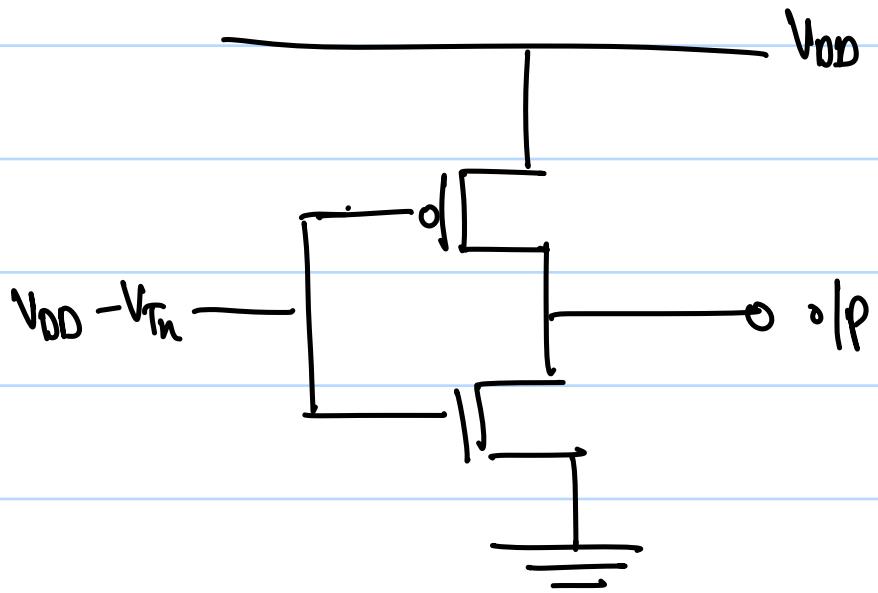
$$\begin{aligned} Y_2 &= (\bar{A}B + \bar{B}\bar{B})^I = (\bar{A}B + \bar{B})^I = (A + \bar{B})B \\ &= AB + \bar{B}B = AB : \underline{\text{AND}} \end{aligned}$$

Here the same topology is used for a different logic function by just changing the inputs.

Also, since the path of each ilp is identical, the delay of each ilp is the same for any logic function.

But static power dissipation is still present and the logic levels are not rail to rail, like in CMOS style.

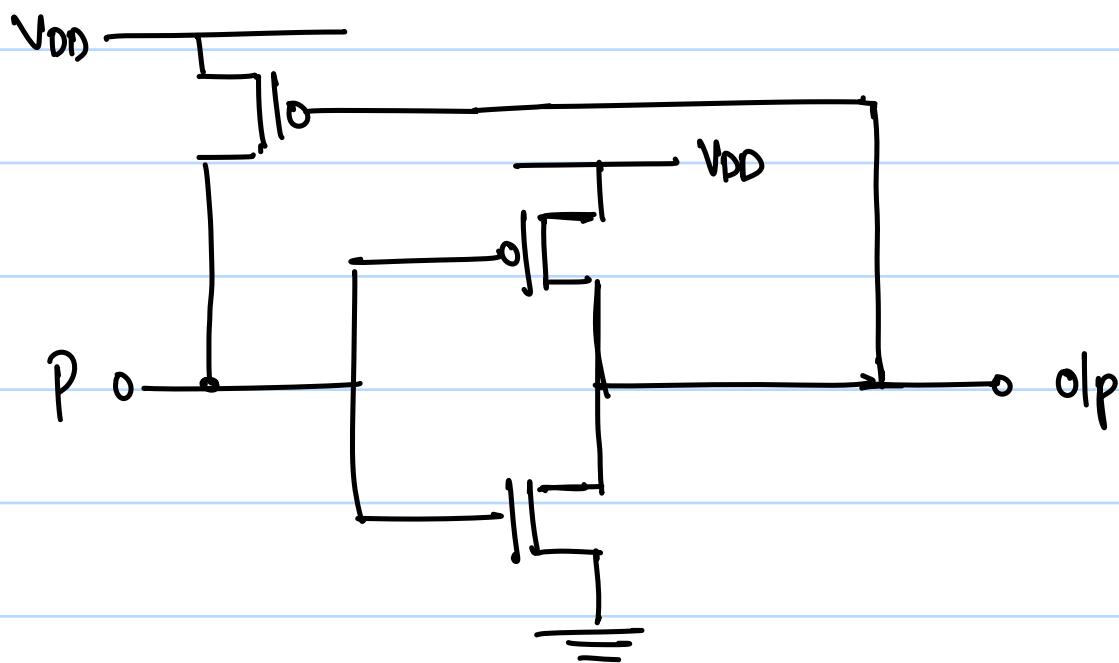
Since the high off of the NMOS PT is $V_{DD} - V_{Th}$, if this is given as ilp to the CMOS inv



- If $V_{Tn} = |V_{Tp}|$, $V_{Sap} = V_{DD} - (V_{DD} - |V_{Tp}|)$
 $= |V_{Tp}| \longrightarrow$ Edge of cutoff

Therefore the PUN is never fully turned off, causing current leakage and significant static power consumption in the CMOS inverter (like in p-NMOS)

To fix this, we use a keeper circuit, a kind of feedback circuit



If $o/p = \text{low}$, the keeper circuit is active and the voltage at P increases to V_{DD} , thus restoring the logic levels and reducing static power consumption.

If $o_{lp} = \text{high}$, the keeper circuit is inactive, which is necessary as keeper circuit is not required at that point.

However, if $P: V_{DD} - V_{Th} \rightarrow 0$, node P tries to discharge through the NMOS PT, but the keeper circuit is still momentarily charging.

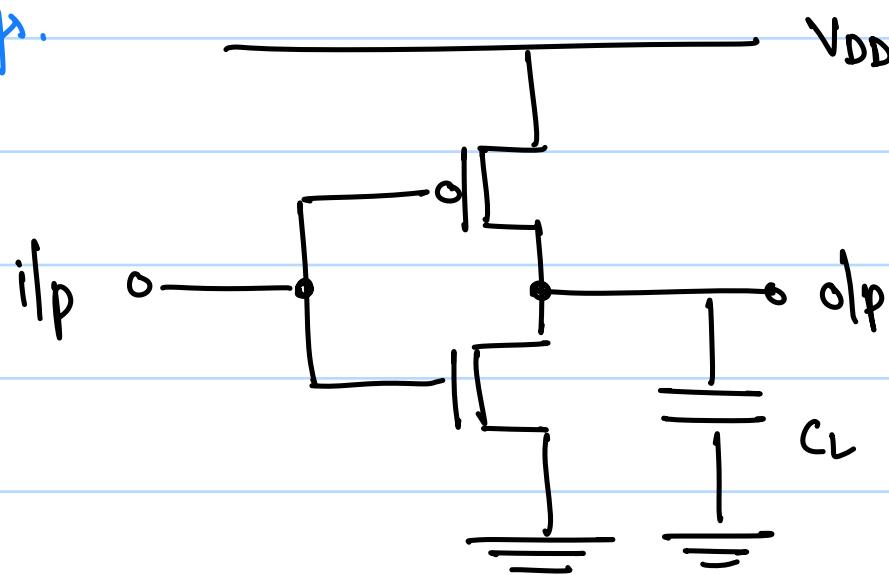
Therefore the NMOS must be stronger than the keeper PMOS, or the PMOS keeper should be weaker.

stronger \rightarrow higher current draw $\rightarrow W \uparrow$

Making the NMOS stronger \rightarrow Increase C_{in} .

Making the keeper weak \rightarrow Increase delay.

- Say we cannot implement a keeper PMOS, and we want to equalize rise/fall delays.



Time taken for C_L to discharge at $V_{DD} ip = t_{PHL1}$

" " " " " $V_{DD} - V_{Th} ip = -t_{PHL2}$

$t_{PH1} < t_{PH2}$, due to lesser current draw.

When $V_{ilp} = V_{DD}$, $I_1 \propto \frac{w}{L} (V_{DD} - V_{Th})^2$
 $V_{ilp} = V_{DD} - V_{Th}$, $I_2 \propto \frac{w}{L} (V_{DD} - 2V_{Th})^2$

$\left. \begin{array}{l} \\ \end{array} \right\} \frac{w}{L} \rightarrow \text{Inv. NMOS aspect ratio}$

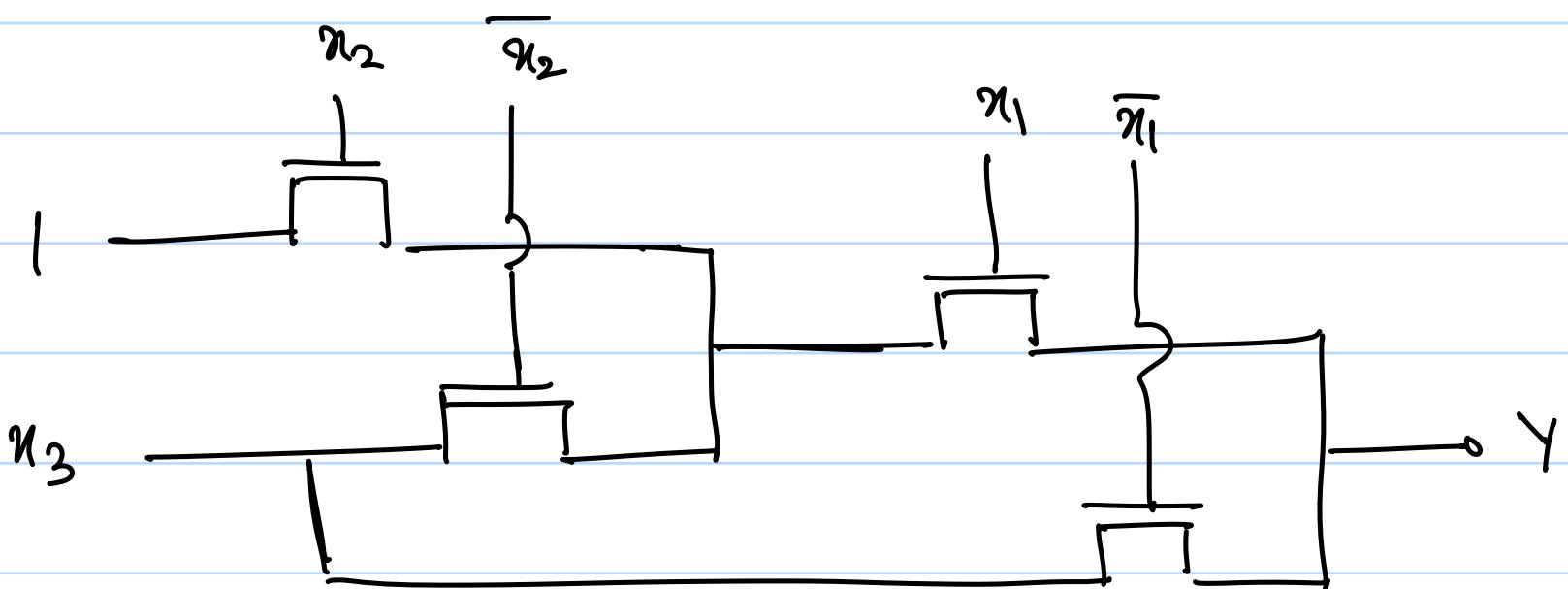
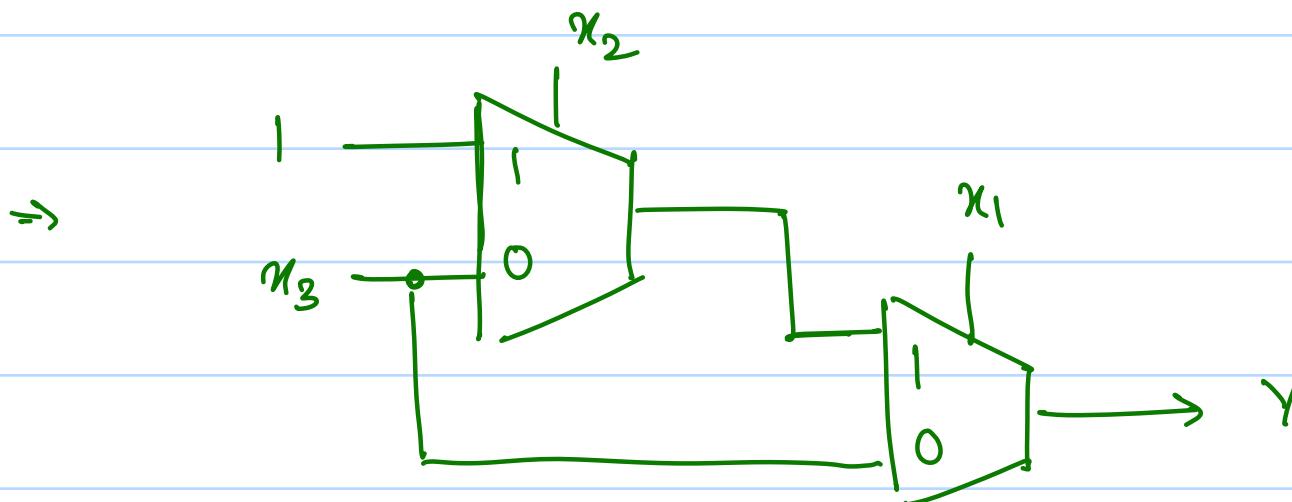
If we want to equalize the delays, $I_1 = I_2$

$$\Rightarrow w_1 (V_{DD} - V_{Th})^2 = w_2 (V_{DD} - 2V_{Th})^2$$

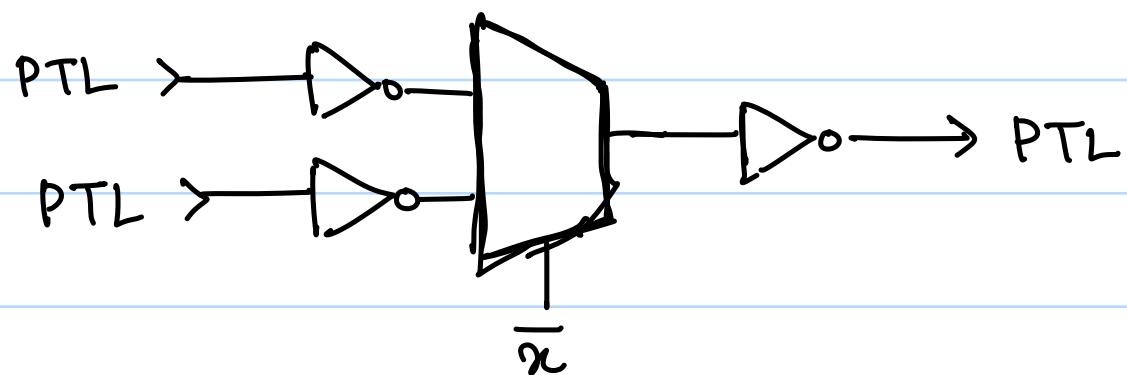
$$\Rightarrow w_2 = w_1 \frac{(V_{DD} - V_{Th})^2}{(V_{DD} - 2V_{Th})^2} > w_1 \rightarrow \text{Current draw is more.}$$

Example: Implement a PTL topology for $f = x_1x_2 + \bar{x}_2x_3 + x_3\bar{x}_1$

$$\begin{aligned} f &= x_1x_2 + \bar{x}_2x_3 + x_3\bar{x}_1 \\ &= x_1(x_2 + \bar{x}_2x_3) + \bar{x}_1(\bar{x}_2x_3 + x_3) \\ &= x_1(x_2(1) + \bar{x}_2(x_3)) + \bar{x}_1(x_3) \end{aligned}$$

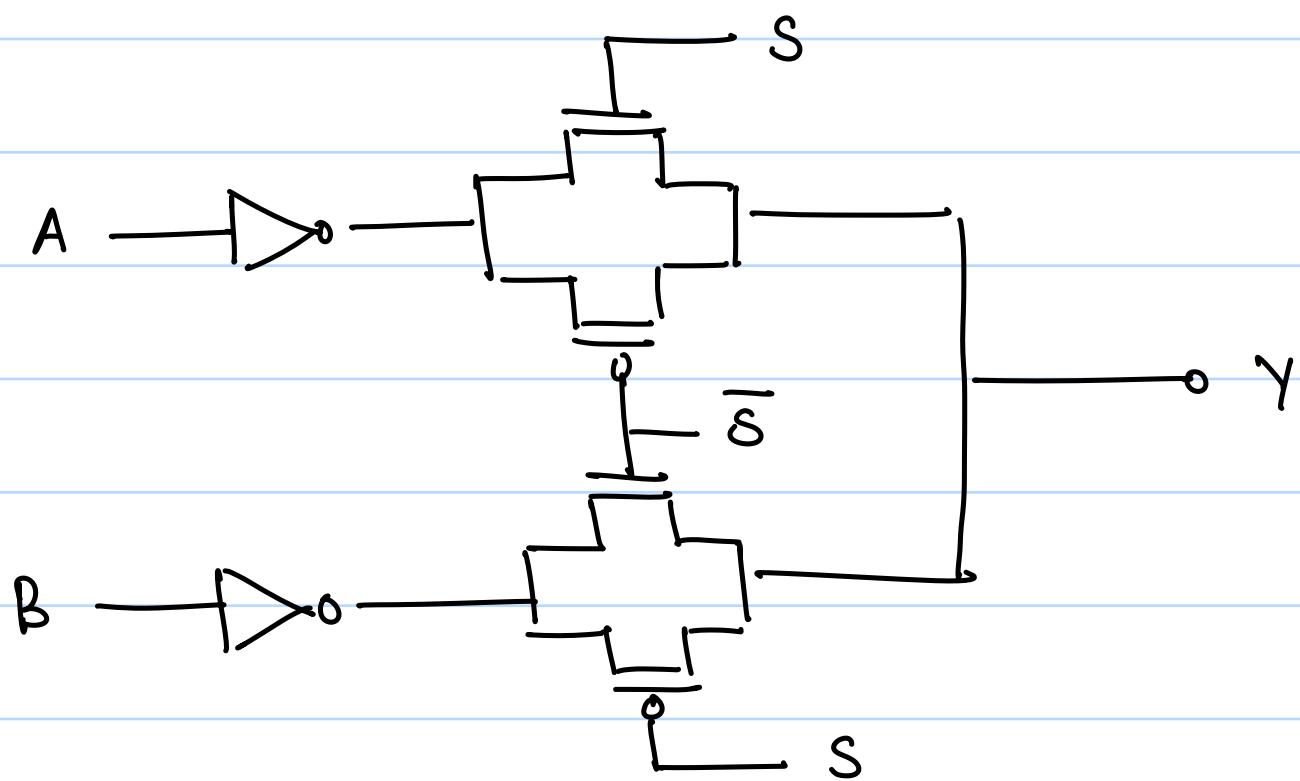


- When chaining multiple MUXes, since logic 1 is not fully passed by the pass NMOS, we can introduce inverters in between each of the MUXes, as "repeaters", ensuring that each MUX gets rail-to-rail inputs.



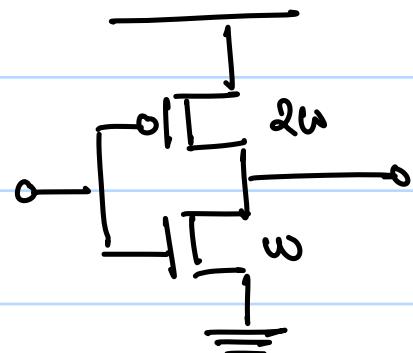
Note: The inverters used in PTL circuits is also termed as a decision circuit.

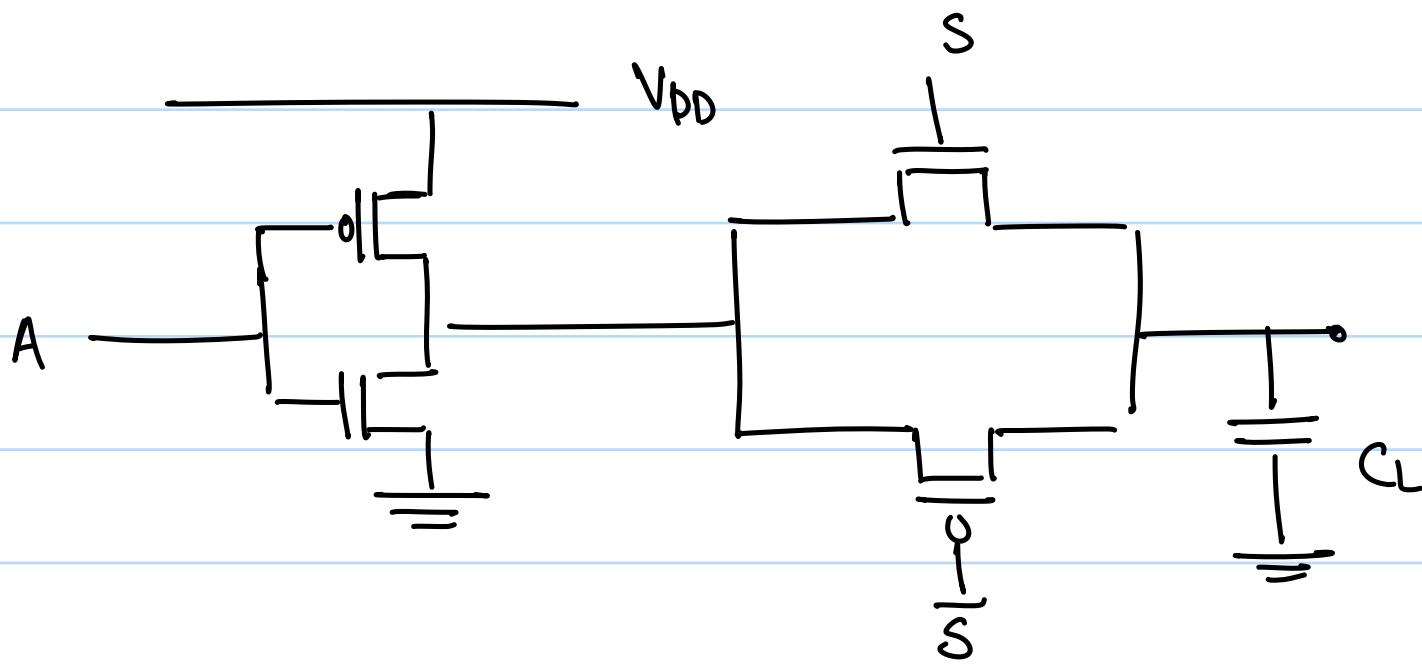
- We can remove the need of decision circuit by using a complementary pass transistor, at the cost of an higher area requirement.



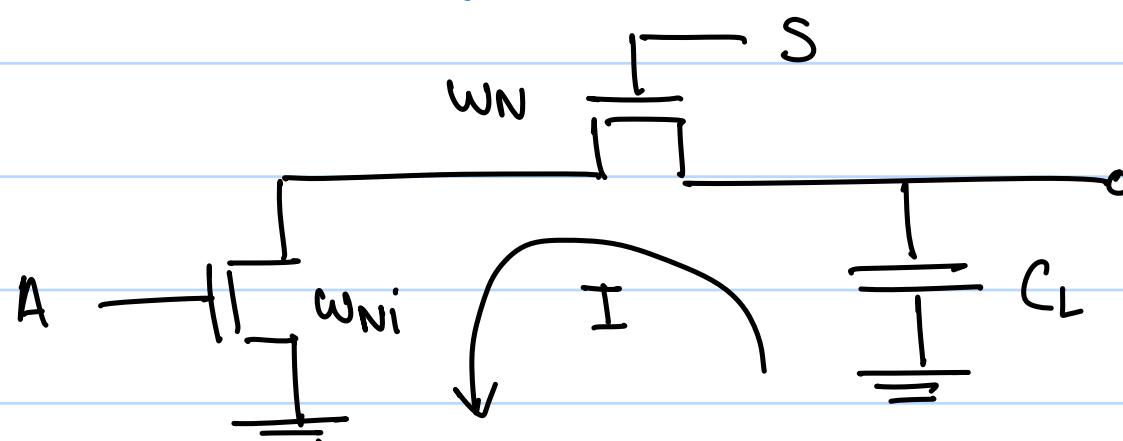
To size the pass transistors of the CPT, we will try to equalize the delay to that of a reference inverter.

(Let $m = \frac{M_n}{M_p} = 2$ for the reference inverter)





A suggest new path for C_L to discharge will be,



This is like an RC circuit, with the resistance provided by the pair NMOS and inv. NMOS

$$\Rightarrow R \propto \frac{1}{w_N} + \frac{1}{w_{Ni}}$$

$$\text{If } w_N = w_{Ni} \Rightarrow R \propto \frac{2}{w_N} \Rightarrow \text{NMOS width : } 2w \quad (\text{Ref. inv. w})$$

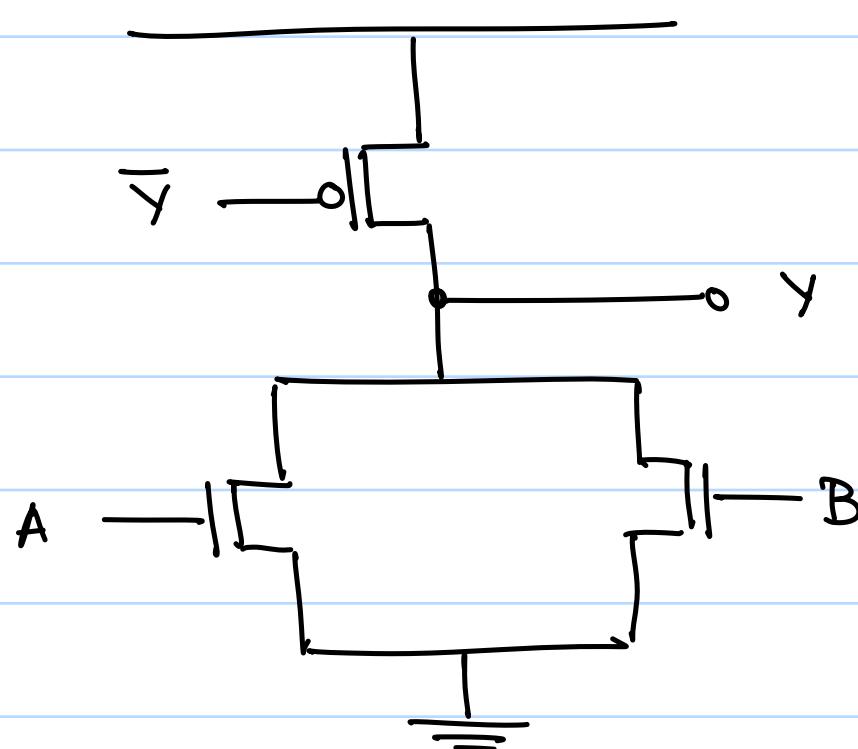
likly $R \propto \frac{1}{w_p} + \frac{1}{w_{pi}}$ in the C_L charging path.

$$\text{If } w_p = w_{pi}, \text{ then } R \propto \frac{2}{w_p} \Rightarrow \text{PMOS width} = 4w$$

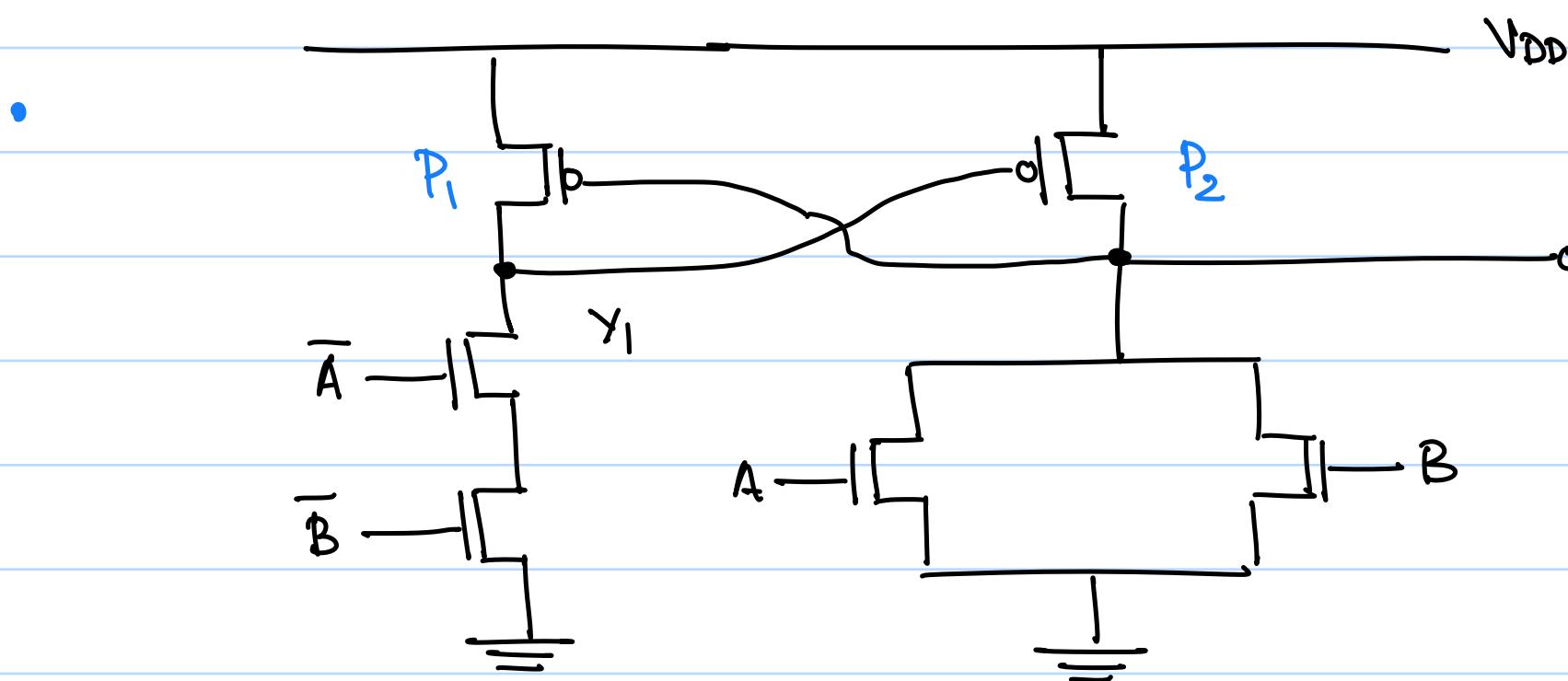
- Using repeaters in a cascade of pass transistors will reduce the charging/discharging path of the load capacitance, reducing delay.

◦ Cascade Voltage Switch Logic (CVSL) :-

- A big problem in p-NMOS is the non-zero static power consumption.
- The problem can be solved by turning off the PMOS when the PDN is active.



PDN is active $\Rightarrow Y = 0 \Rightarrow \bar{Y} = 1 \Rightarrow$ PMOS is off



$$Y = (\bar{A} \cdot \bar{B}) = A + B$$

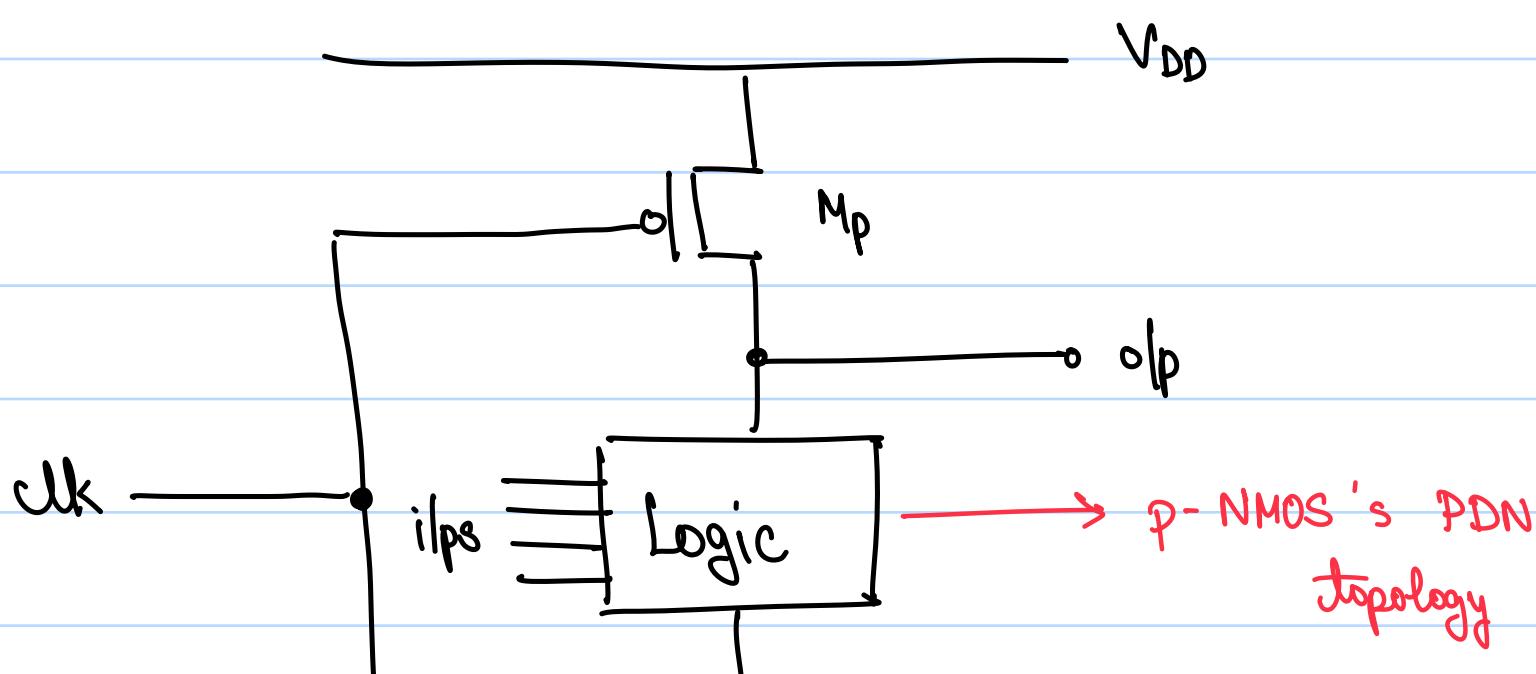
$$Y = \overline{A+B}$$

In the above circuit,

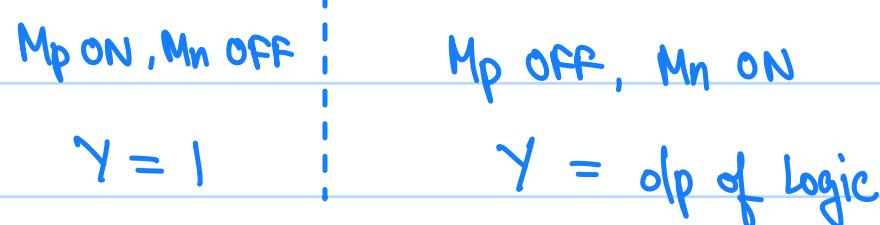
A	B	γ_1	γ_2	
0	0	0	1	$\rightarrow P_1 \text{ is off}$
0	1	1	0	$P_2 \text{ is off}$
1	0	1	0	
1	1	1	0	

This topology eliminates the static power consumption as the compl. - activity of p controlling the PMOS will be such that the PMOS is turned off when the PDN is active.

* Dynamic Logic :-



Clk :



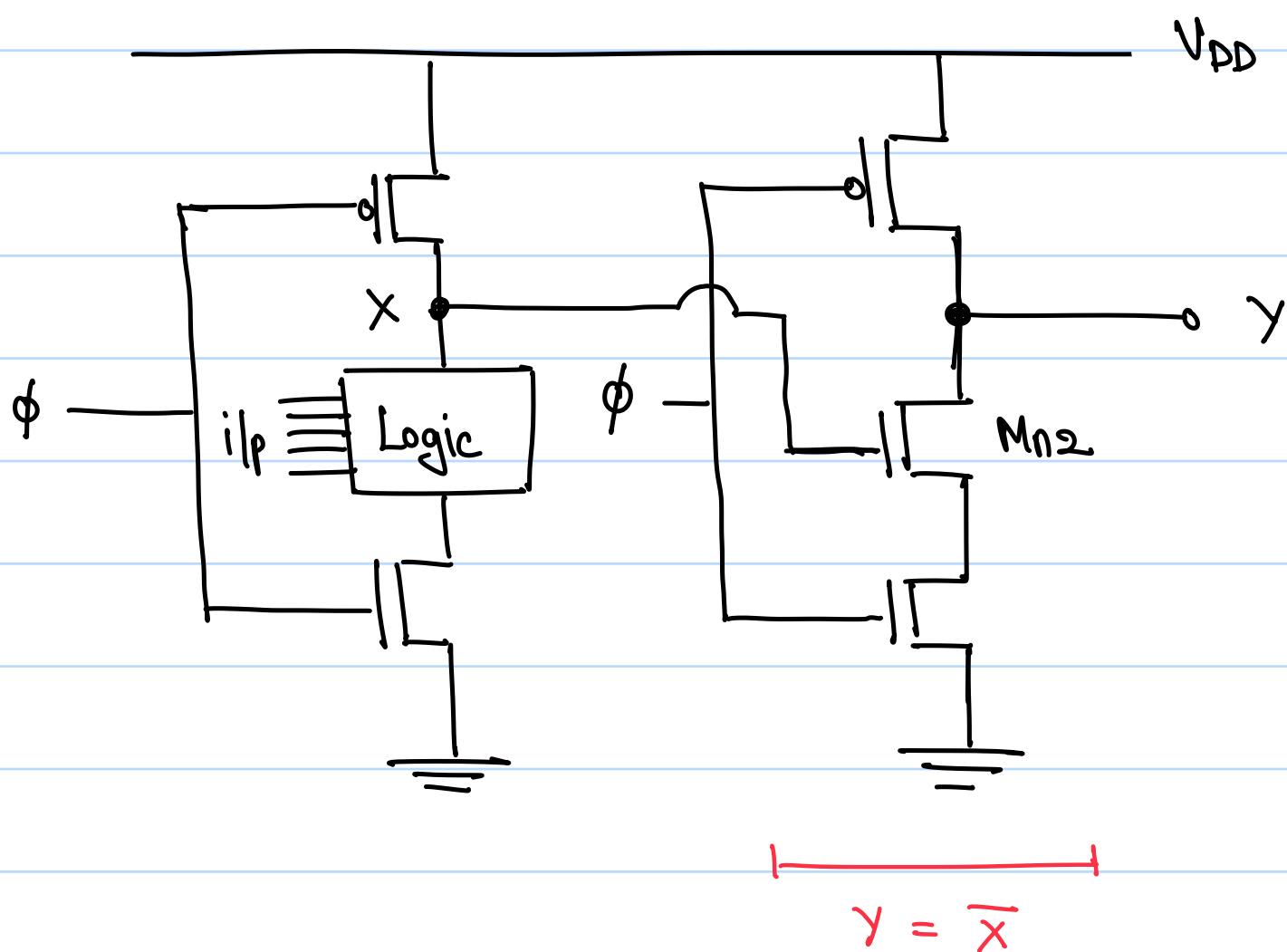
Precharge phase

Evaluation Phase

- Dynamic logic solves the problem of subthreshold conduction that occurs when the capacitive load is charging.

The precharge phase charges the capacitor to 1. There is no leakage current in the logic circuit since it is disconnected due to M_{N1} being in cutoff.

The actual opf is shown during the evaluation phase, where it either stays at 1 or discharges to 0.



For the above circuit,

In pre-charge phase, $X = 1, Y = 1$

In eval phase,

Logic = True, $X = 0, Y = 1$

Logic = False, $X = 1, Y = 0$

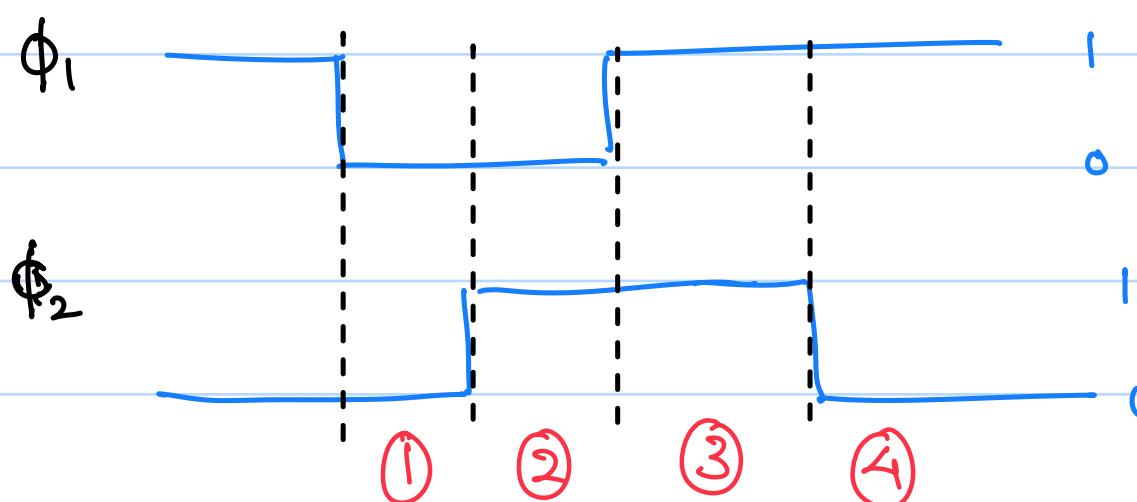
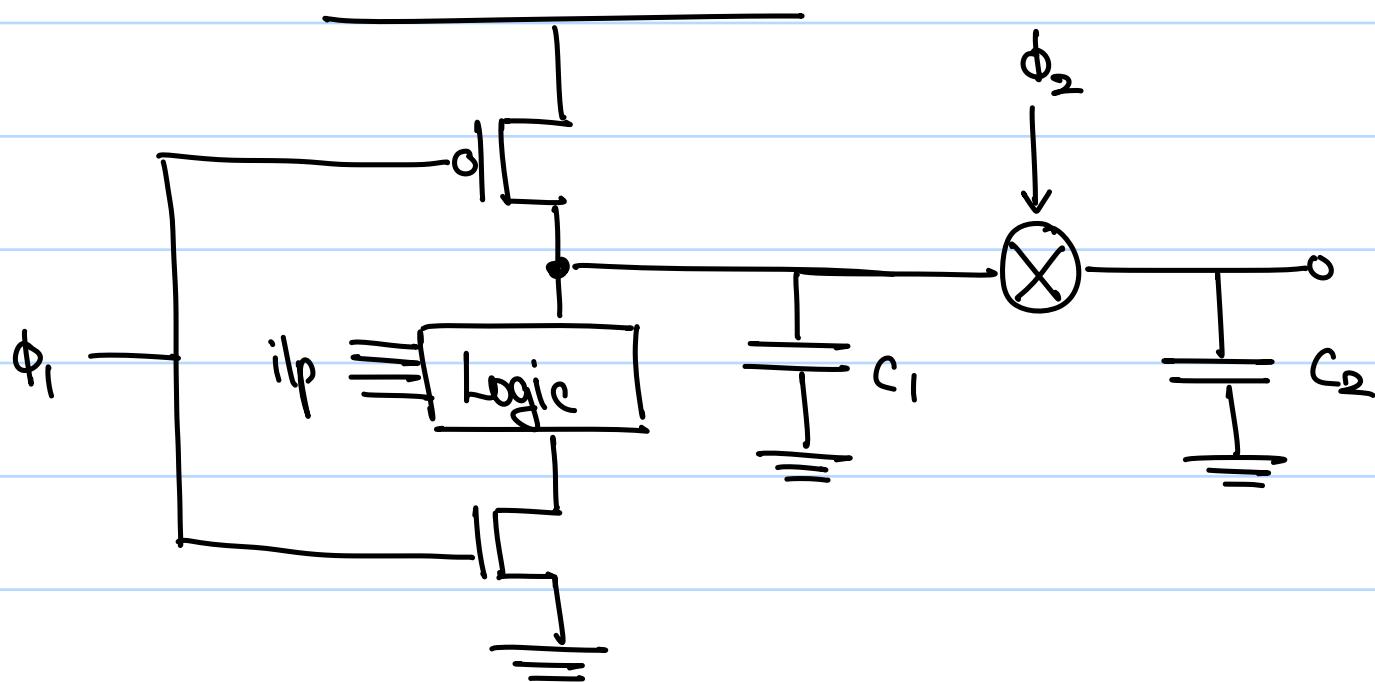
In the logic = True scenario, $X: 1 \rightarrow 0$ (due to precharge), which means M_{N2} will conduct for some time, because of which the capacitor load will discharge for some time.

$$\therefore \text{olp} = V_{DD} - \Delta V < V_{DD} \quad (\Delta V \text{ depends on the NMOS strength})$$

The load cannot be charged by the PMOS in the eval stage since the clock PMOS is off.

→ Pass Gate & Multi-Phase Clock :-

- A way to fix the above problem.



The pass gate gives high impedance at the olp if $\phi_2 = 0$. So Y will retain the last value it obtained when $\phi_2 = 1$.

In the above circuit,

P①, $\phi_1 = 0$, $\phi_2 = 0$

$X = 1$, $Y = 0$ (say)

P②, $\phi_1 = 0$, $\phi_2 = 1$

$X = 1$, $Y = 1$

P③, $\phi_1 = 1$, $\phi_2 = 1$

$X = Y = \text{evaluated logic}$

P④, $\phi_1 = 1$, $\phi_2 = 0$

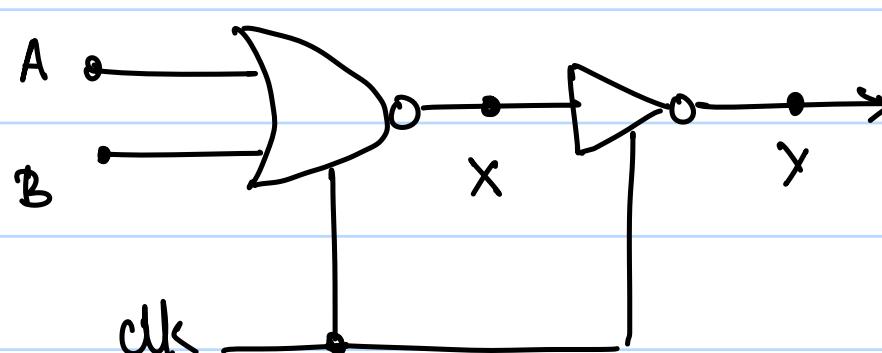
$X = 1$, $Y = \text{evaluated logic in P③}$.

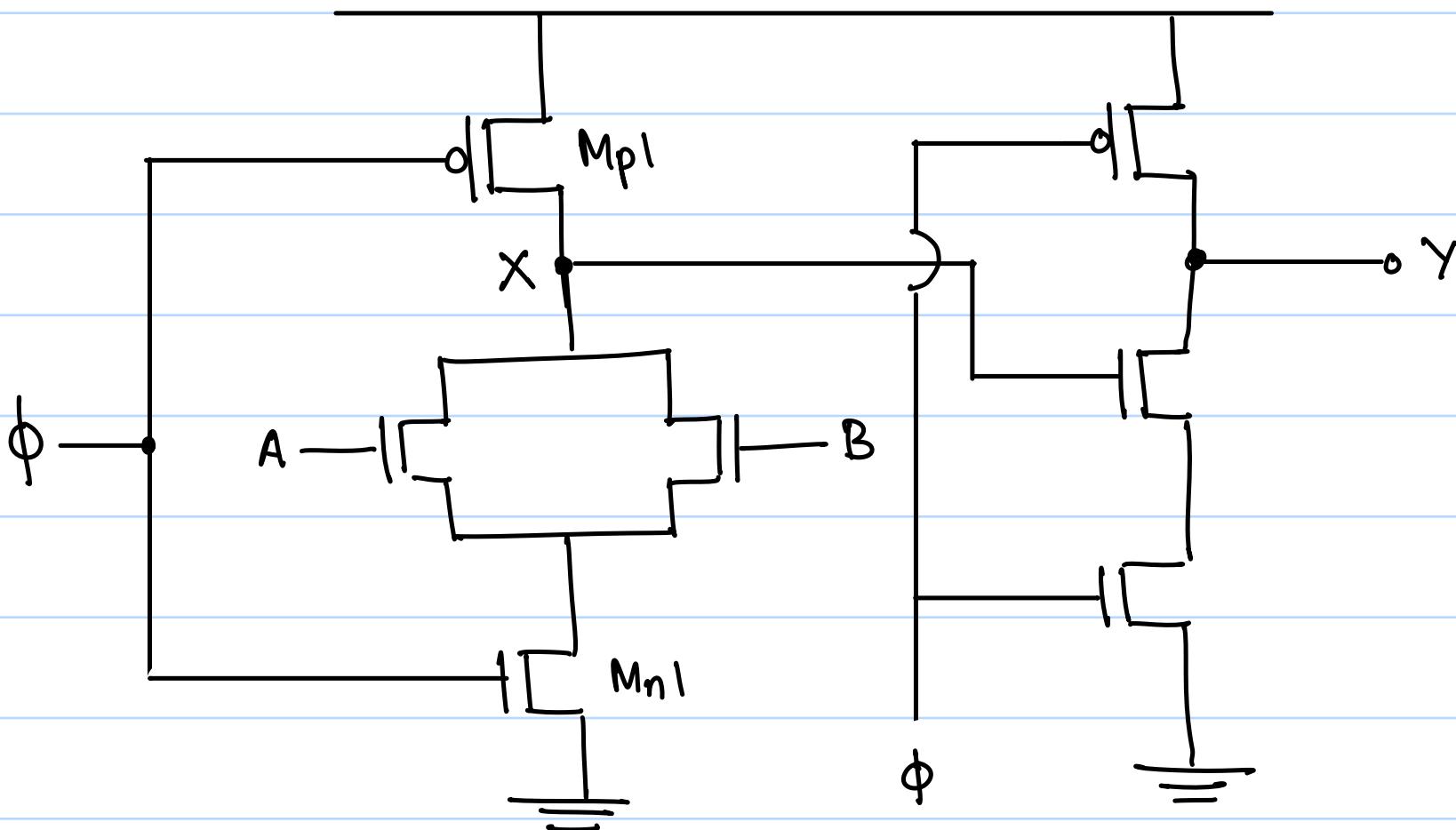
This topology gives us rail-to-rail outputs at the end since it solves the partial discharging problem.

- We can also solve this problem by using a CMOS inverter without any clock signal, to get the rail-to-rail output back. But it makes our logic inverting, which complicates things when cascading.

Domino / NP Logic :-

- Say we want to implement the logic function,





	X	Y
$\phi = 0$	1	1

(Precharging)

$\phi = 1, A+B = 0$	1	0
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(Evaluation)

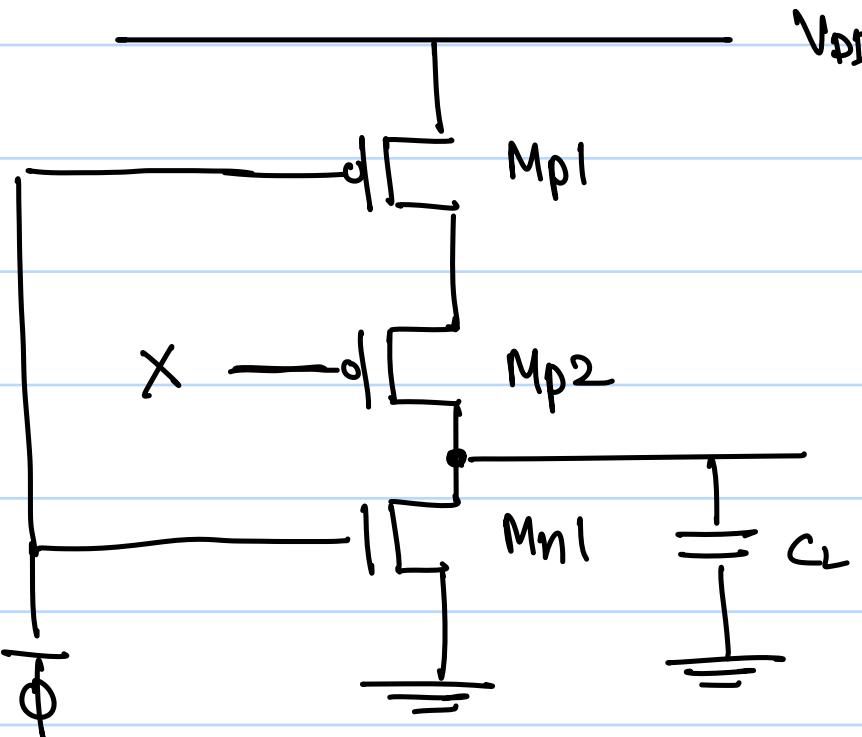
$\phi = 1, A+B = 1 = -$	0	$V_{DD} - \Delta V$
-------------------------	---	---------------------

- Now if we use PMOS logic for the second gate, with clock signal $\bar{\phi}$,

	X	Y
$\phi = 0$	1	0

$\phi = 1, A+B = 0$	1	0
$A+B = 1$	0	V_{DD}

Here, we get rail to rail o/p, since,



At $\phi = 1$, $\bar{\phi} = 0 \Rightarrow M_N1$ is OFF

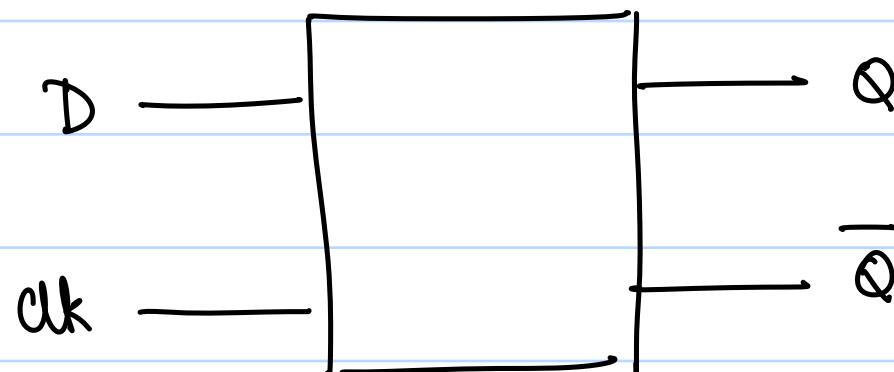
$X = 0 \Rightarrow M_P2$ is ON \Rightarrow o/p is 1

$X = 1 \Rightarrow M_P2$ is OFF \Rightarrow o/p is 0 since node is at \bar{X} and prev. o/p was 0

- The partial discharge by the NMOS will not happen since it is off due to the clock signal, giving us rail to rail o/p.

- This logic design is termed as Domino / NP design.

→ Latche :-



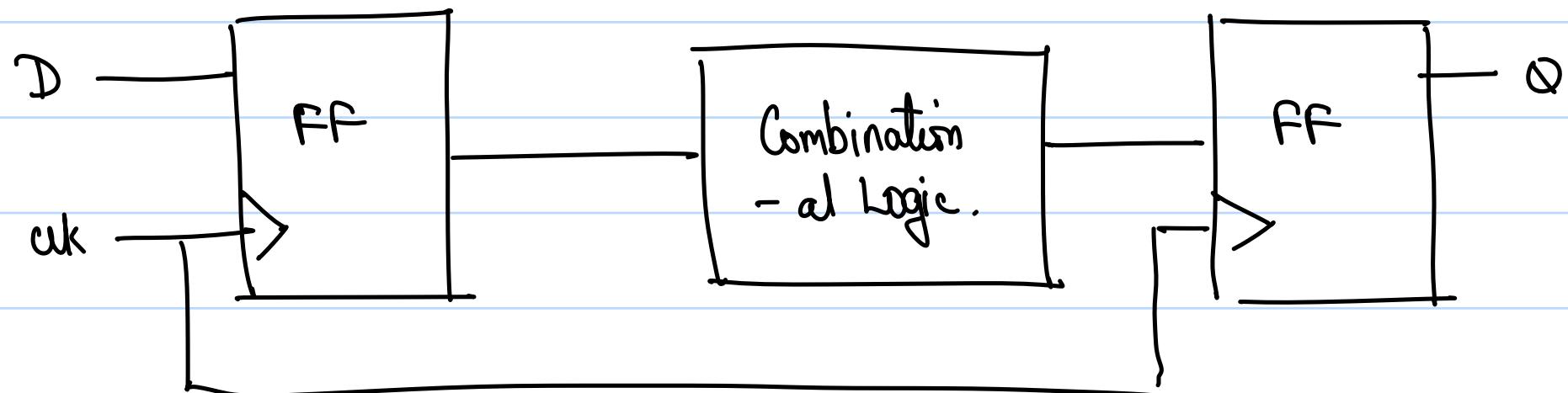
- A device such that, $Q = D$ if $Clk = 1$, $Q = \bar{Q}$ if $Clk = 0$.

- Latche are used in the creation of Gatekeeper circuit, which slow down / regulate the speed of the inputs to a device.
- Latche and Flipflops' use case in memory is not as RAM, SRAM, etc. It is for input regulation / data sequencing.
- The set time of a flipflop is the minimum amount of time before the clock edge, where the input has to be constant for normal operation of the flipflop. (t_{su})

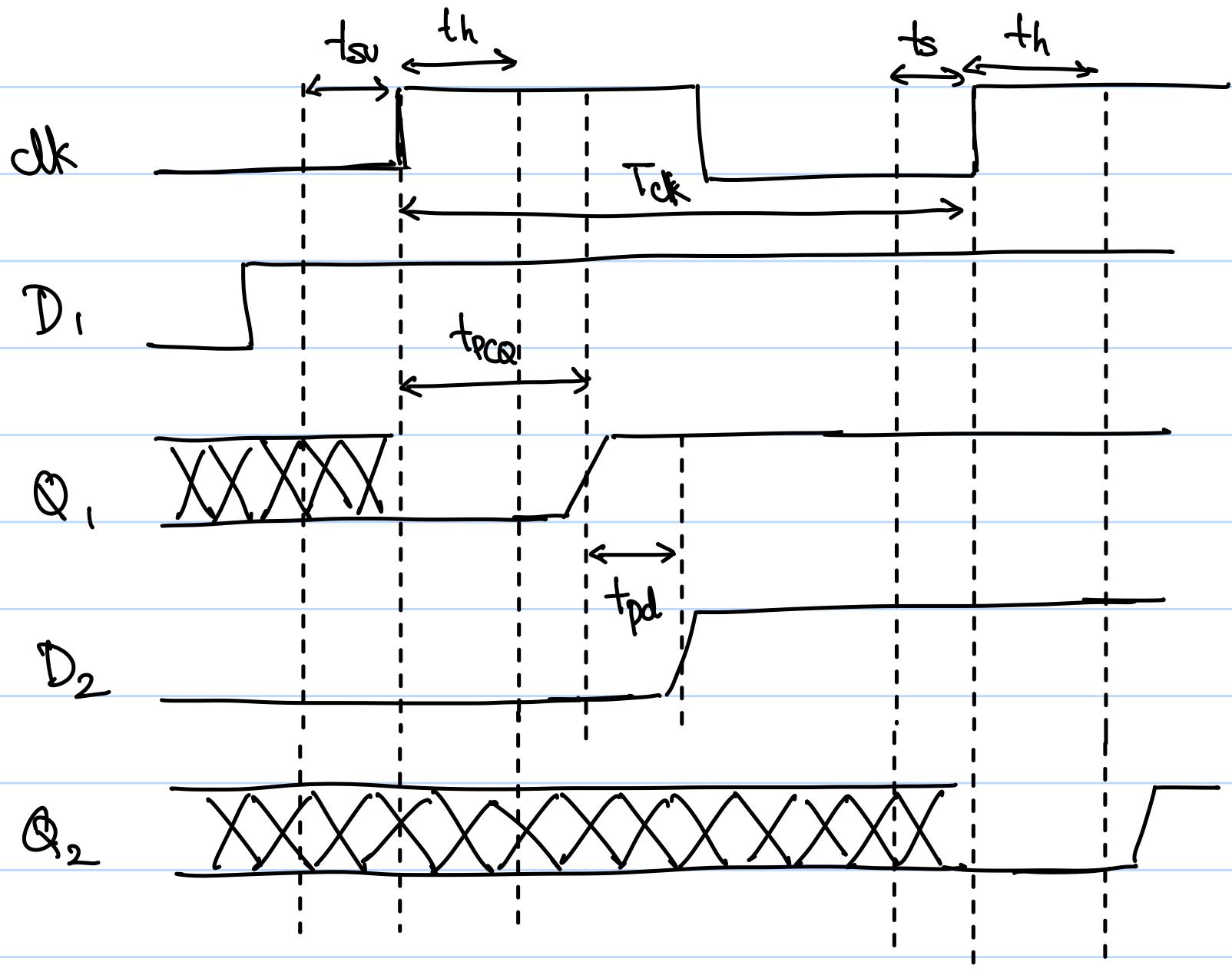
The hold time is the min amount of time for which ip has to be constant, after the clock edge. (t_h)

There is also some propagation delay between the clock edge and when the output reaches Q (t_{pQ}).

- Static Timing Analysis :-



- Static timing analysis is used to analyse the sequential behaviour of circuits.



t_{pd} - Propagation delay of combinational circuit

- From the above timing diagram, we get the constraint that,

$$t_{pcq} + t_{pd} \leq T_{clk} - t_{sv} \quad (\text{Set-up time constraint})$$

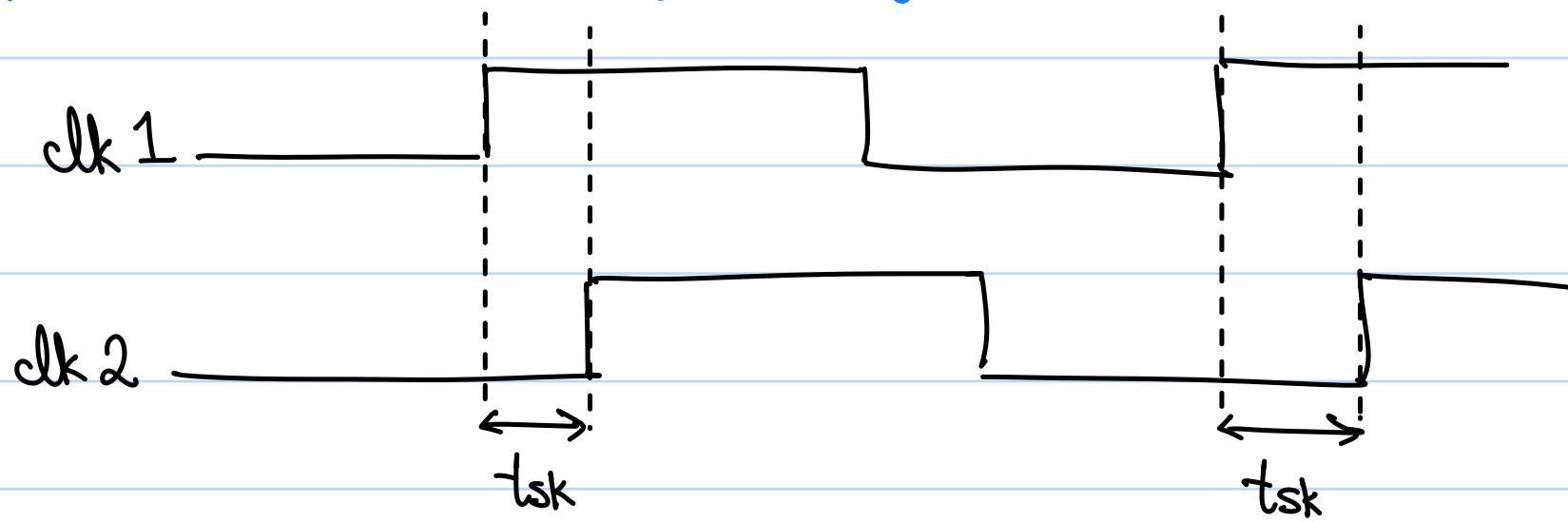
time for input to
 pass through FF and
 combinational logic.

$$\Rightarrow T_{clk} \geq t_{pcq} + t_{pd} + t_{sv} \rightarrow \text{Gives an upper bound on the clock freq.}$$

And, $t_{pcq} + t_{pd} \geq t_h$ (Hold time constraint)

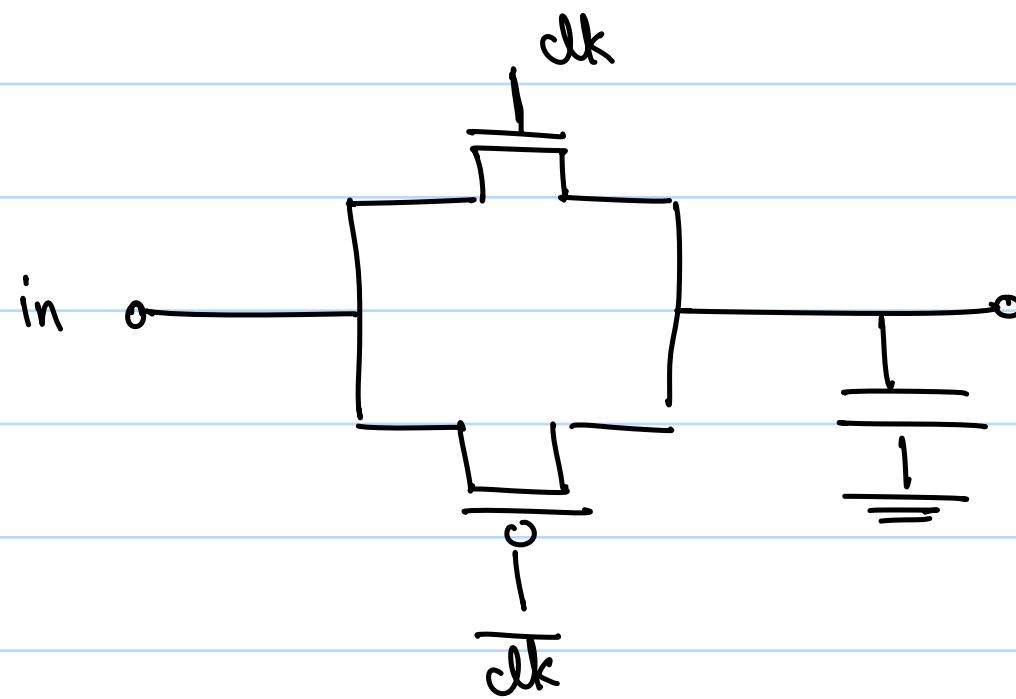
$\rightarrow D_2$ should not change within t_h of
 the second flip-flop.

- Suppose there is a delay / skew of t_{sk} between the 2 clock signals.



Then, the above mentioned inequalities change. They can be derived through appropriate timing analysis.

- Topology :-



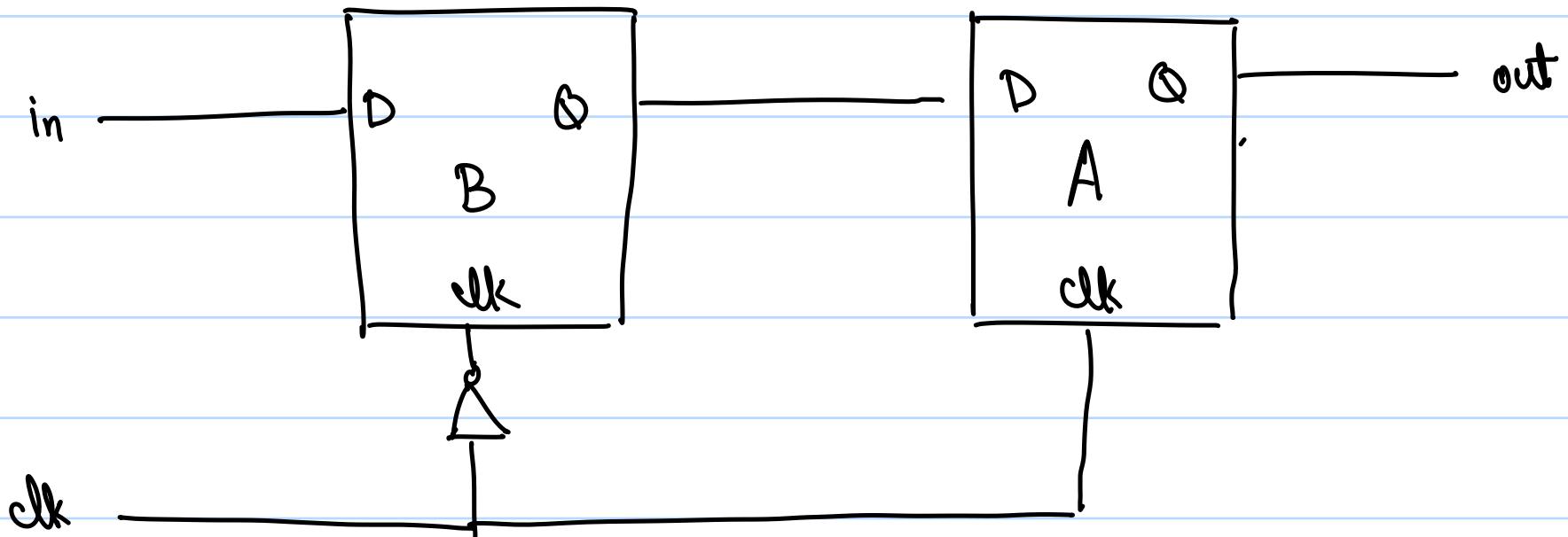
- In the above topology,

$$clk = 1, \quad out(t) = in(t) \rightarrow \text{Evaluation}$$

$$clk = 0, \quad out(t) = out(t-1) \rightarrow \text{Retention}$$

So the given circuit acts like a positive-level triggered latch.

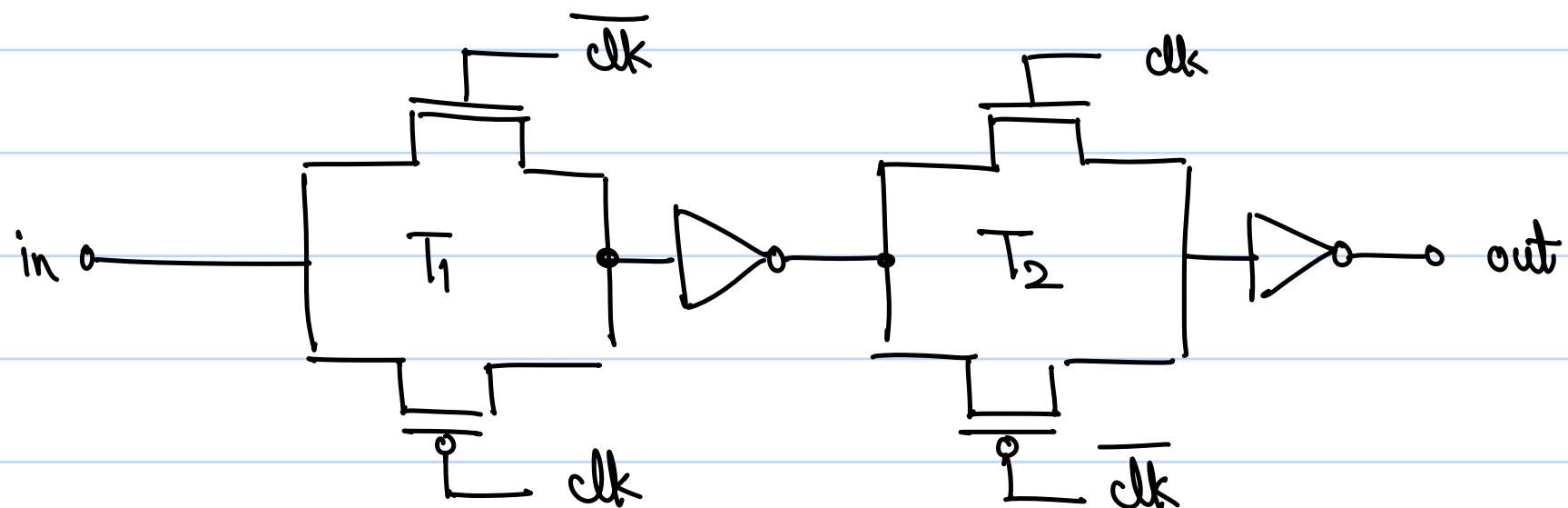
- A flip flop can be made from latches through a master-slave configuration.



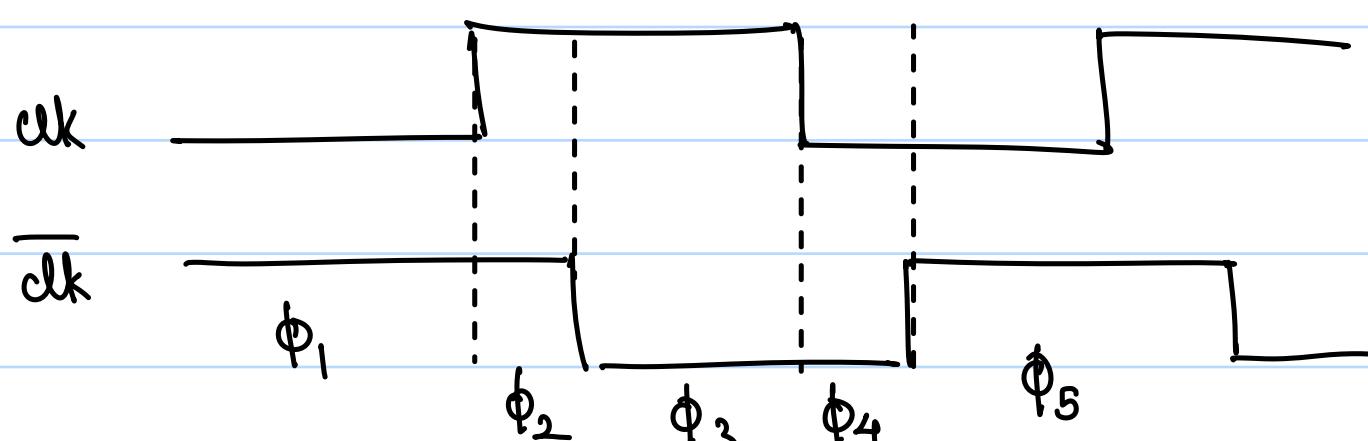
B, if $\text{clk} = 0$, $Q(t) = D(t)$, else $Q(t) = Q(t-1)$

A, if $\text{clk} = 1$, $Q(t) = D(t)$, else $Q(t) = Q(t-1)$

This circuit acts like a positive-edge triggered flip flop.



- Due to routing differences, there will be some propagation delay between clk and $\bar{\text{clk}}$.



	ϕ_1	ϕ_2	ϕ_3	ϕ_4
T_1	ON	ON	OFF	OFF
T_2	OFF	ON	ON	OFF

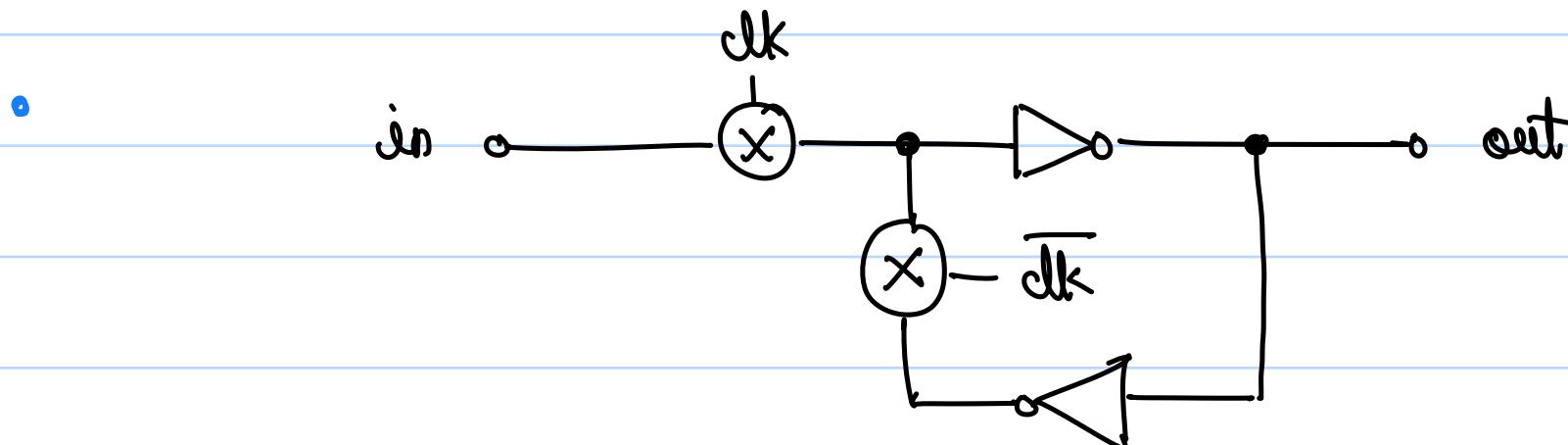
- In the ϕ_2 time period, both the gates are on so any output change in that time will be instantly reflected at the o/p.

Therefore, no changes should be allowed during ϕ_2 . This is the origin of the hold time constraint.

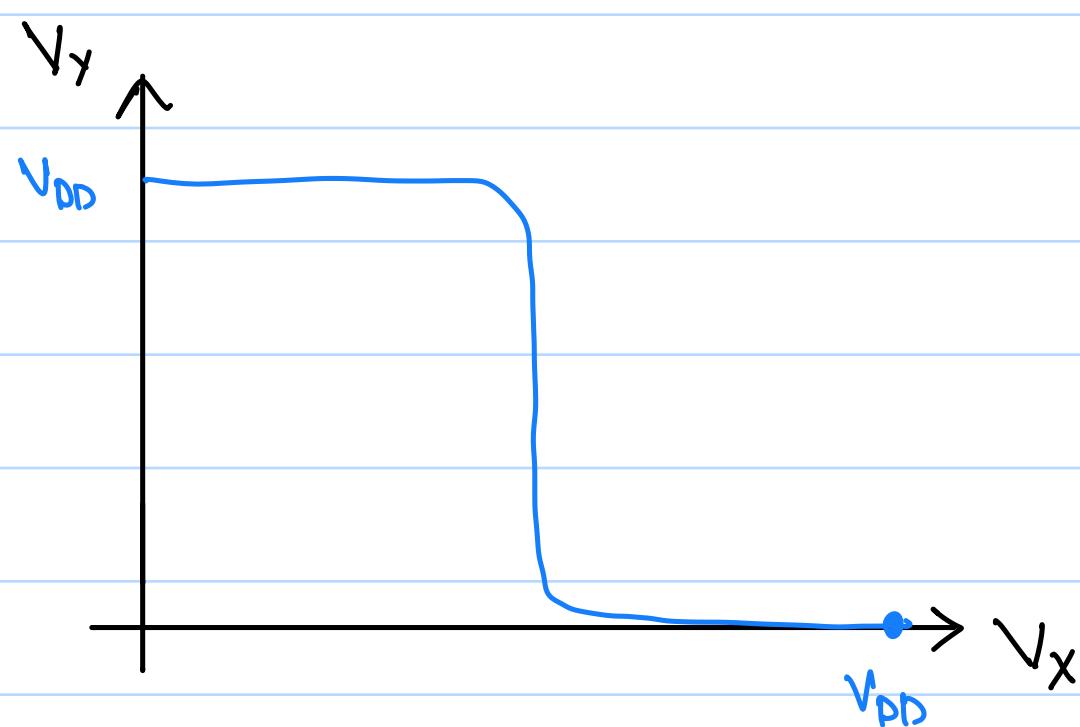
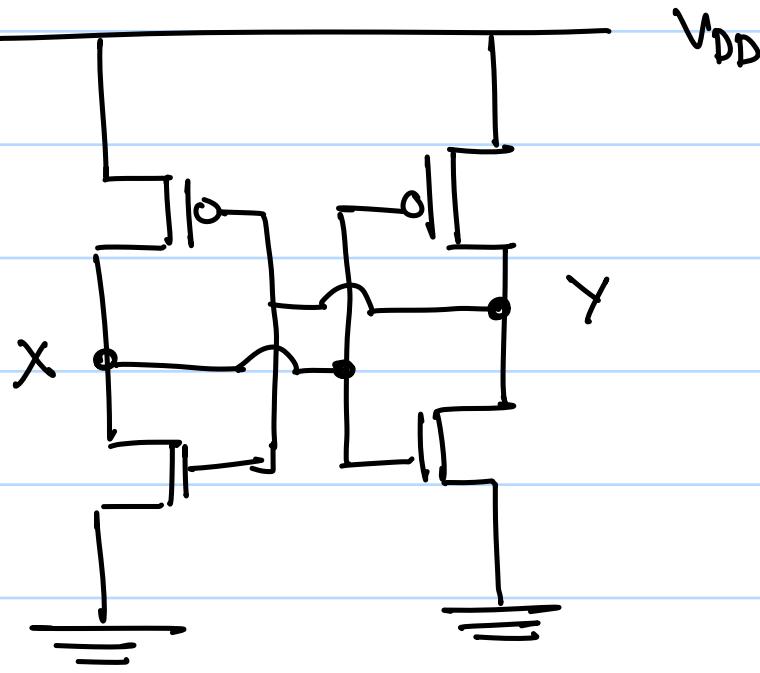
- Since there will be some delay in the transmission gate, if the clock closes the gate within that delay, then data will be lost. So, the input must be settled for a time period greater than the delay, before the clock signal, creating the setup-time constraint.

$$\therefore t_h > \text{Delay b/w clk and } \bar{\text{clk}}$$

$$t_{su} > T_1 \text{ transmission gate delay.}$$

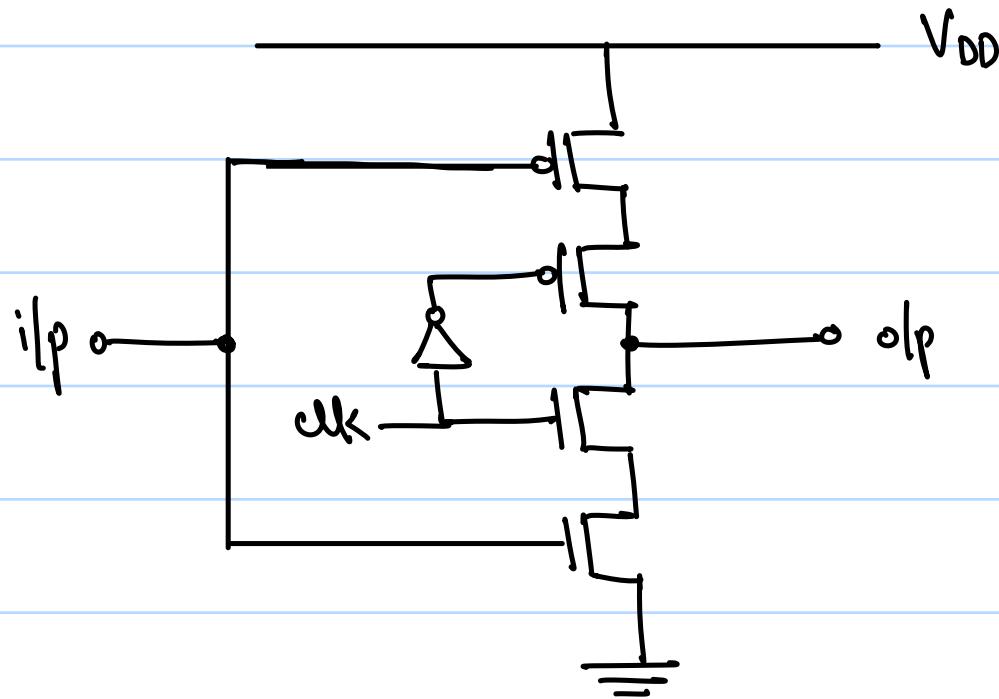


The above device will also act like a latch, since the NOT inverter cycle will retain any o/p it has.



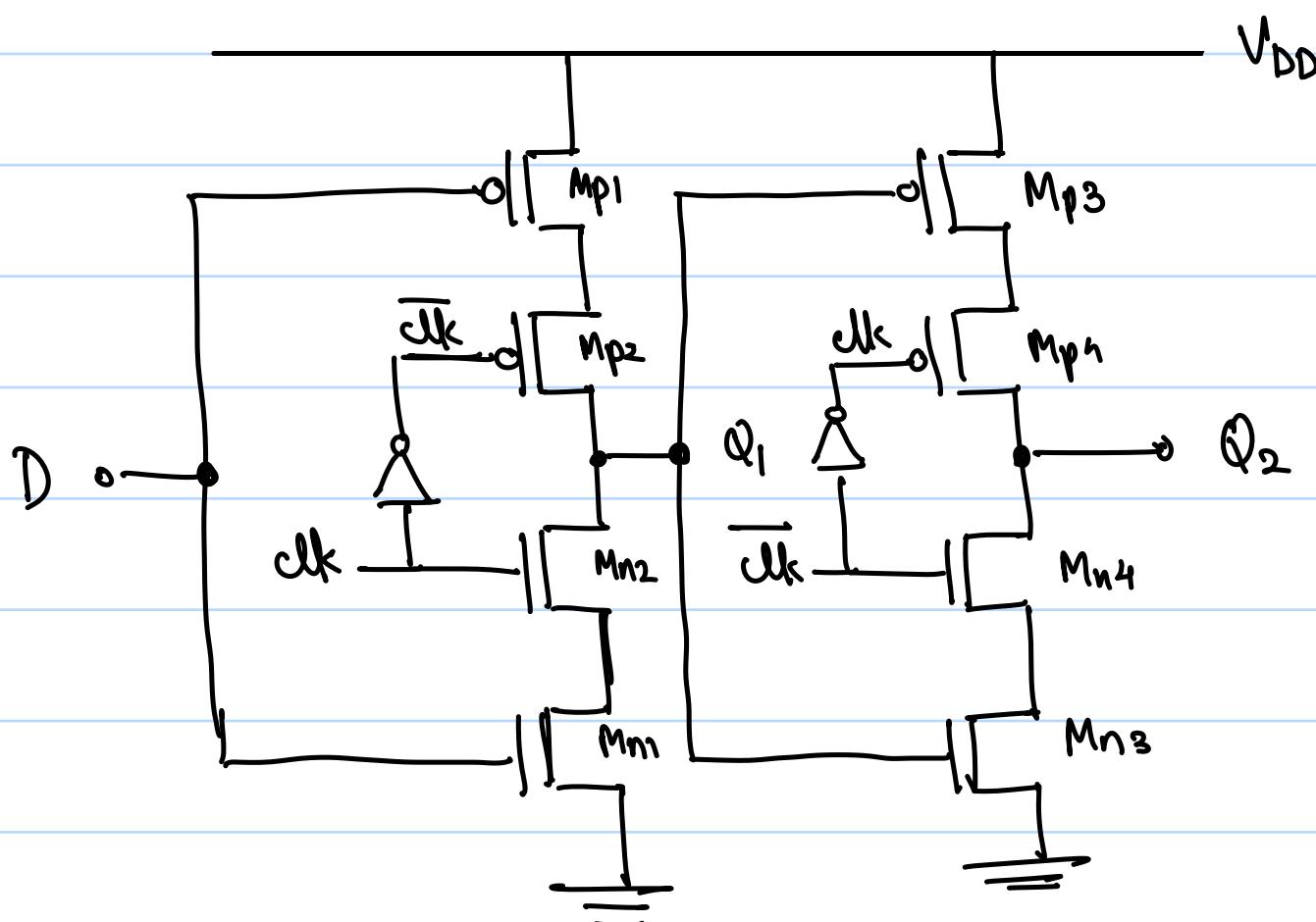
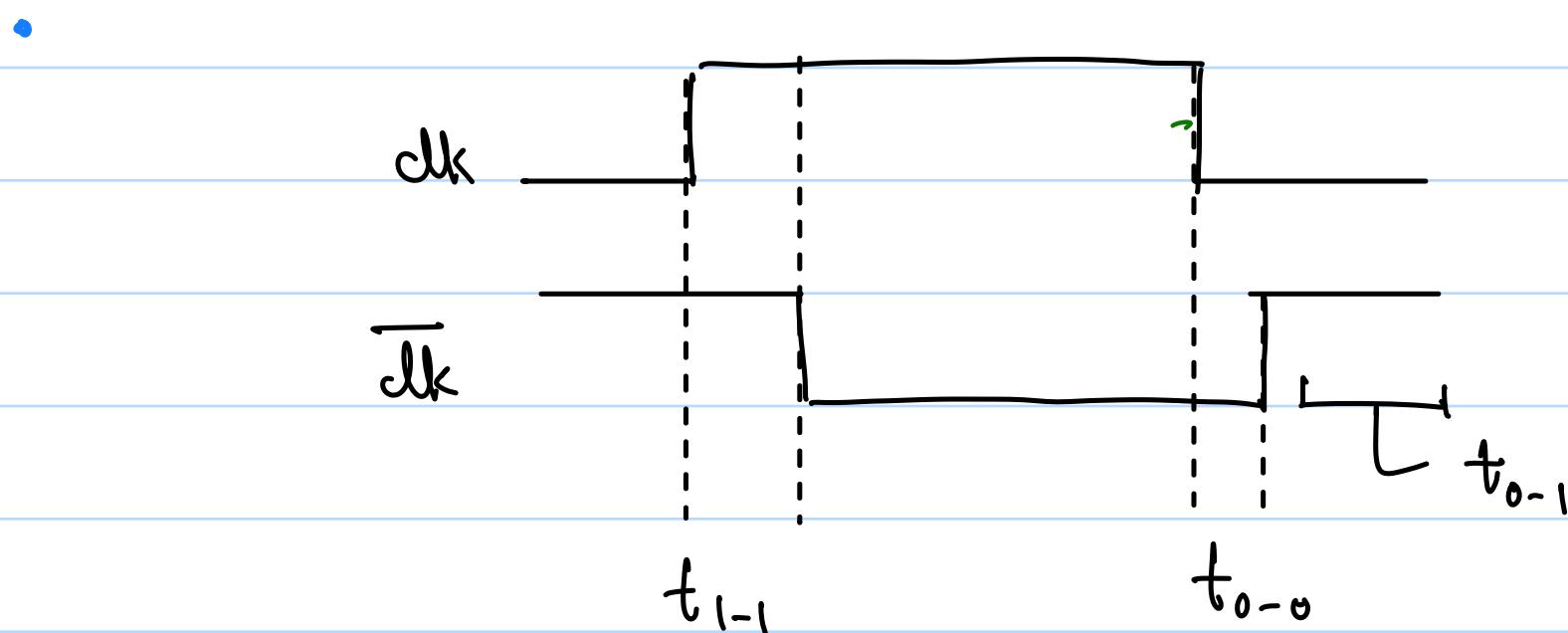
The inverter cycle acts like a positive feedback loop, keeping the voltages stable. The feedback loop makes the topology insensitive to noise.

- Clocked CMOS (C^2MOS) Latch :-



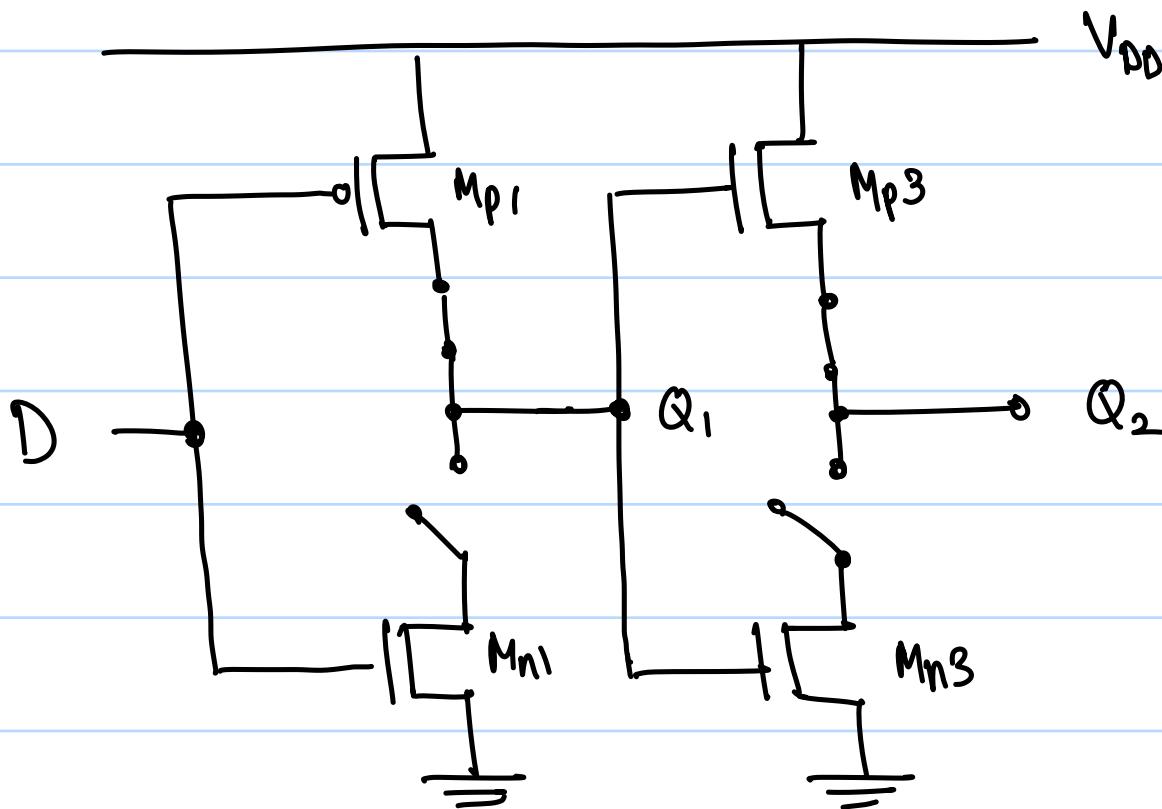
- When $\text{clk} = 0$, $\text{o/p} = \underline{z} \Rightarrow Q(t) = Q(t-1)$
- When $\text{clk} = 1$, $\text{o/p} = \overline{\text{i/p}} \Rightarrow Q(t) = \overline{D(t)}$

- If we keep this latch in a master-slave configuration, we can implement an edge triggered flip flop.



Negative Edge Triggered FF

At t_{0-0} ,



If $D = 1 \rightarrow 0$,

$M_{P1} = \text{ON} \Rightarrow Q_1 = 1 \Rightarrow M_{P3} = \text{OFF} \Rightarrow Q_2 = \text{Jatched}$

Then if we reach t_{0-1} ,

$M_{P1} = \text{OFF}, M_{N1} = \text{OFF} \Rightarrow Q_1 = \text{Jatched} \Rightarrow Q_1 = 1$

$Q_1 = 1 \Rightarrow M_{P3} = \text{OFF}, M_{N3} = \text{ON}$

and $M_{N4} = \text{ON}, M_{P4} = \text{OFF} \Rightarrow Q_2 = 0$

Since input changes from $1 \rightarrow 0$ at $t_{0-0} \Rightarrow D = 1$ before the negative edge, meaning we want $Q_2 = 1$ beyond the negative edge. However as we can see here that due to the change of D in t_{0-0} , $Q_2 = 0$.

\therefore The change of D in t_{0-0} (after the -ve. edge) affects Q_2

$\Rightarrow t_{0-0}$ defines the hold time of the flipflop.

If $D: 0 \rightarrow 1$,

$M_{p1} = \text{OFF}, M_{n1} = \text{ON} \Rightarrow Q_1 = \text{Latched}$

Since Q_1 is latched, Q_2 will not be affected by D .

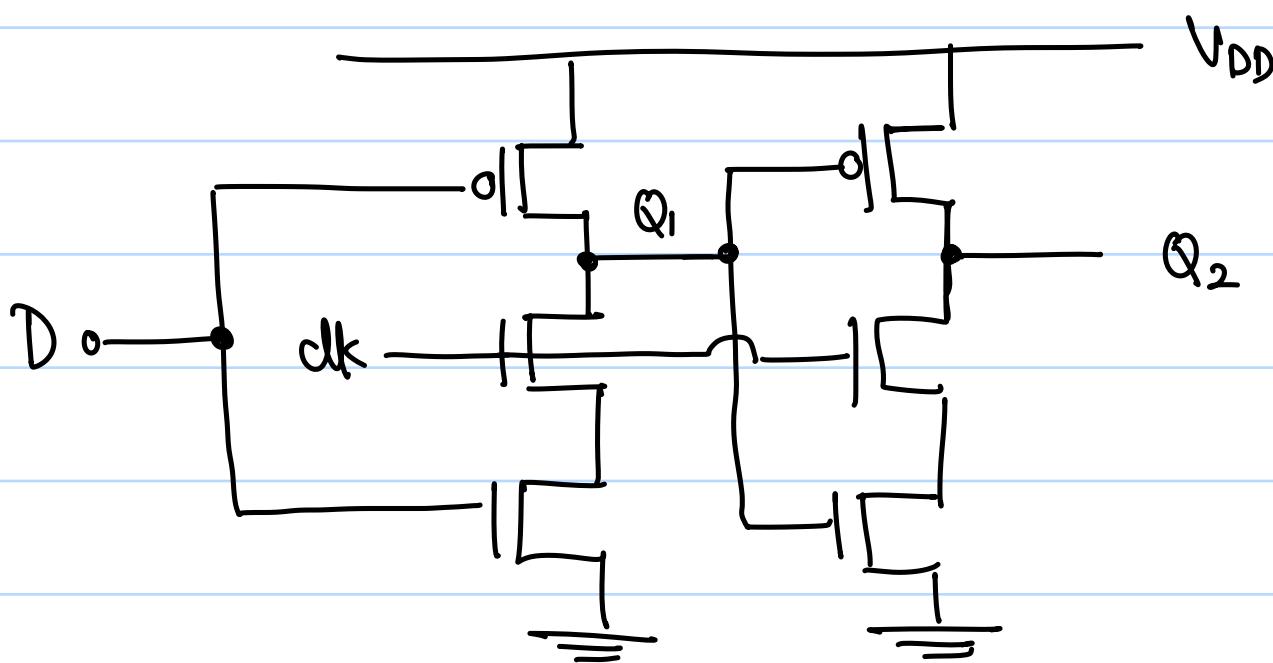
\therefore Hold time constraint is due to $D: 1 \rightarrow 0$.

- The setup time constraint will be defined by the $D \rightarrow Q_1$ delay, i.e. the propagation delay of the first inverter.

Q_1 to Q_2 delay is a part of t_{PCQ} .

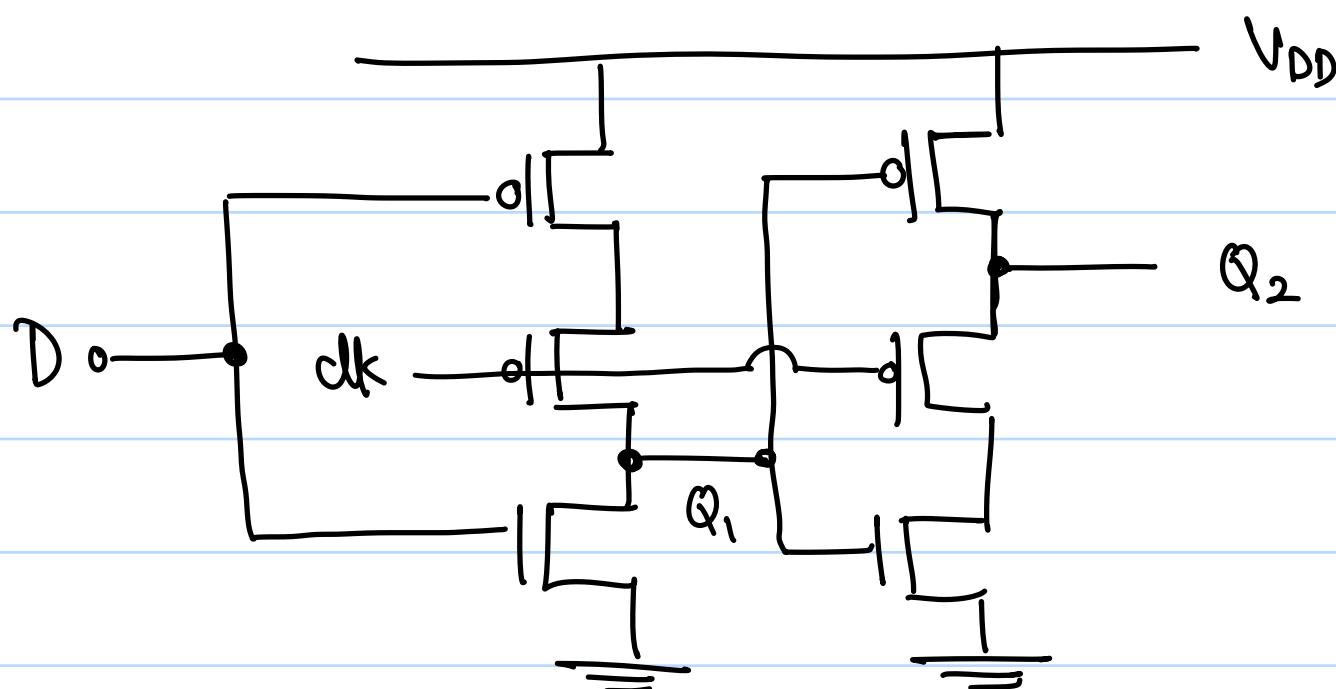
\rightarrow True Single Phase Clock Design : (TSPC Design)

- As seen in the above 2 designs, the clk to $\bar{\text{clk}}$ delay is the cause of the hold time constraint.
- Using a single clock line can solve this problem.



- If $\text{clk} = 0$, $Q_1 = \underline{D}$, $Q_2 = \underline{\bar{Q}_1} = \underline{\underline{D}}$
 - $D = 0 \quad D = 1$
 - $Q_1 \quad I \quad L$
 - $Q_2 \quad L \quad L$
 - $\text{clk} = 1, \quad Q_1 = \bar{D}, \quad Q_2 = \bar{Q}_1 = \underline{\underline{D}}$
- } +ve level triggered latch

- If we modify the device as,



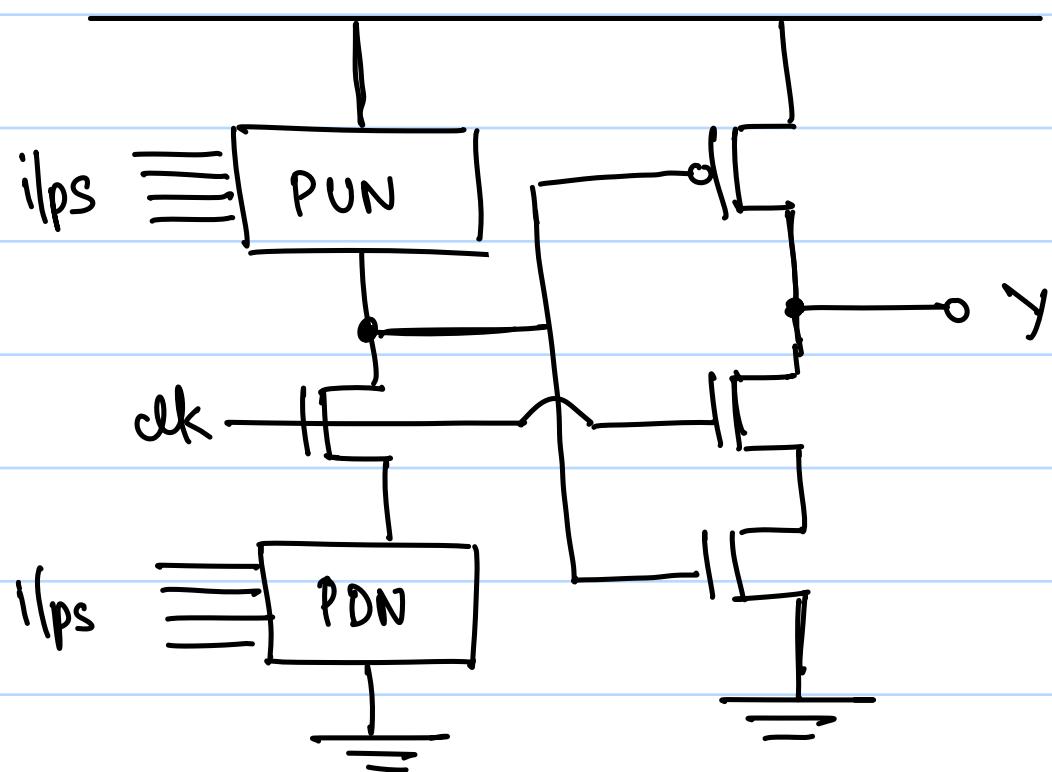
$$\begin{aligned}
 & \text{clk} = 0, \quad Q_1 = \bar{D}, \quad Q_2 = D \\
 & \text{clk} = 1, \quad D = 1, \quad Q_1 = 0 \quad \} \quad Q_2 = L \\
 & D = 0, \quad Q_1 = L
 \end{aligned}
 \quad \} -\text{ve level triggered latch}$$

- Logic functionalities in TSPC :-

- Say we want a latch such that,

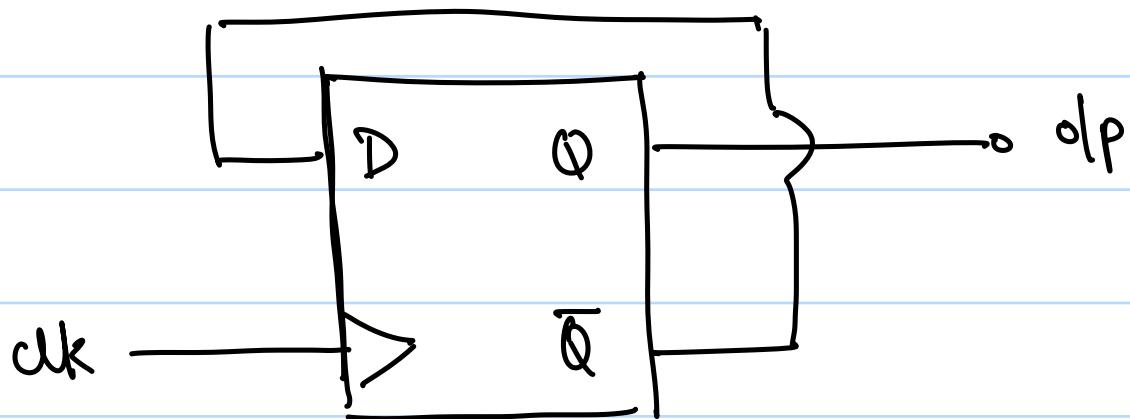
$$\begin{aligned}
 & \text{if } \text{clk} = 1, \quad Y(t) = f(A, B, \dots, t) \\
 & \text{clk} = 0, \quad Y(t) = Y(t-1)
 \end{aligned}$$

The general topology is as follows,



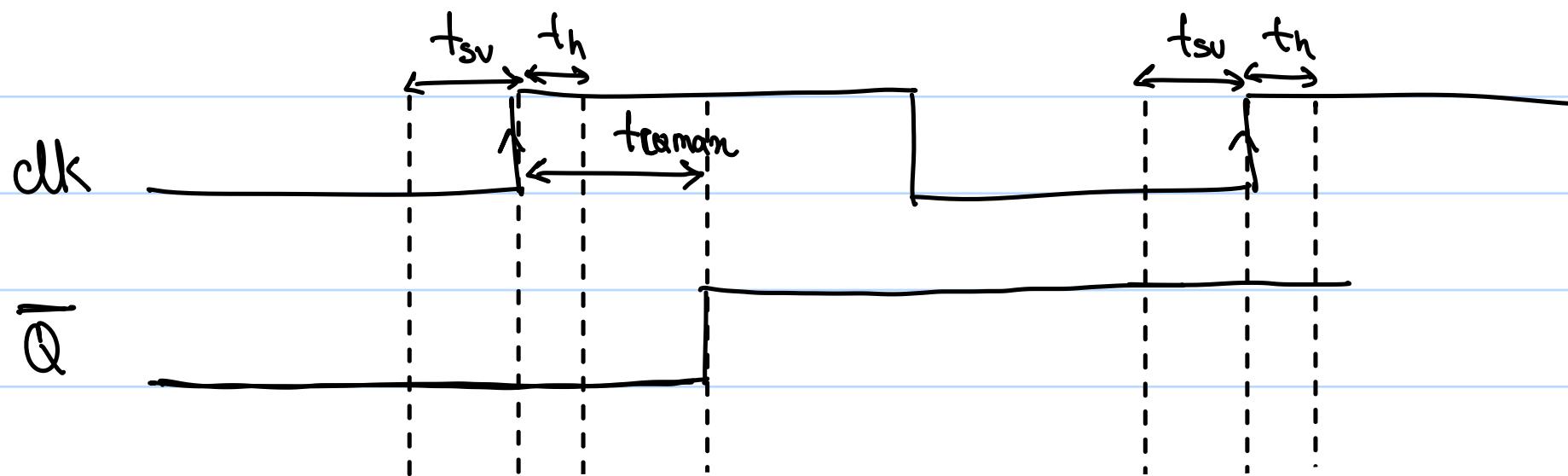
PUN is $f(\bar{A}, \bar{B}, \bar{C}, \dots)$ implemented in PMOS and PDN is $\bar{f}(A, B, C, \dots)$ implemented in NMOS (III Jo MOS design)

Example: Perform Static Timing Analysis on,



Given $t_{su} = 20\text{ns}$, $t_h = 5\text{ns}$, $t_{cqmax} = 40\text{ns}$, $t_{cqmin} = 25\text{ns}$.

Find the minimum clock period for normal functionality.

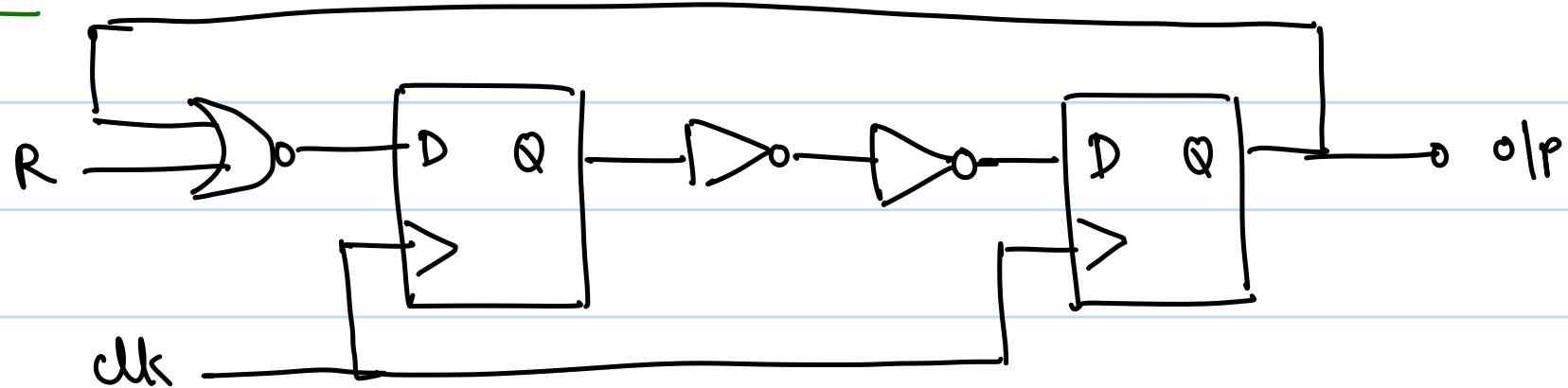


Based on the above obtained timing analysis, we can say that,

$$T_{clk} \geq t_{Q\max} + t_{sv}$$

$$\Rightarrow T_{clk\ min} = 40 + 20 = \underline{\underline{60\ ns}}$$

Example:



Find $T_{clk\ min}$ and verify for any hold time violation.

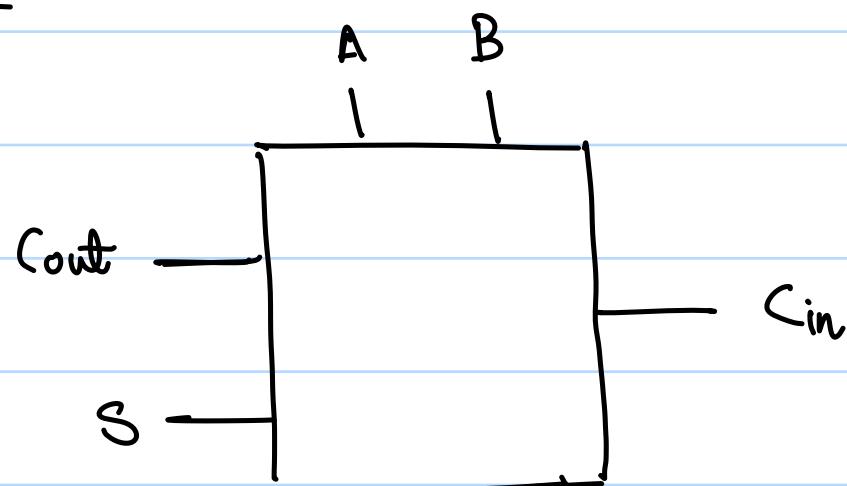
$$t_{sv} = 3n, t_{pd_inv} = 2n, t_{NOR} = 2n, t_{P\bar{Q}} = 2n, t_h = 1n$$

Analyse from 2 paths, FF1 to FF2 and FF2 to FF1

★ Arithmetic Circuits :-

(PPT: DK Sharma, IIT Bombay)

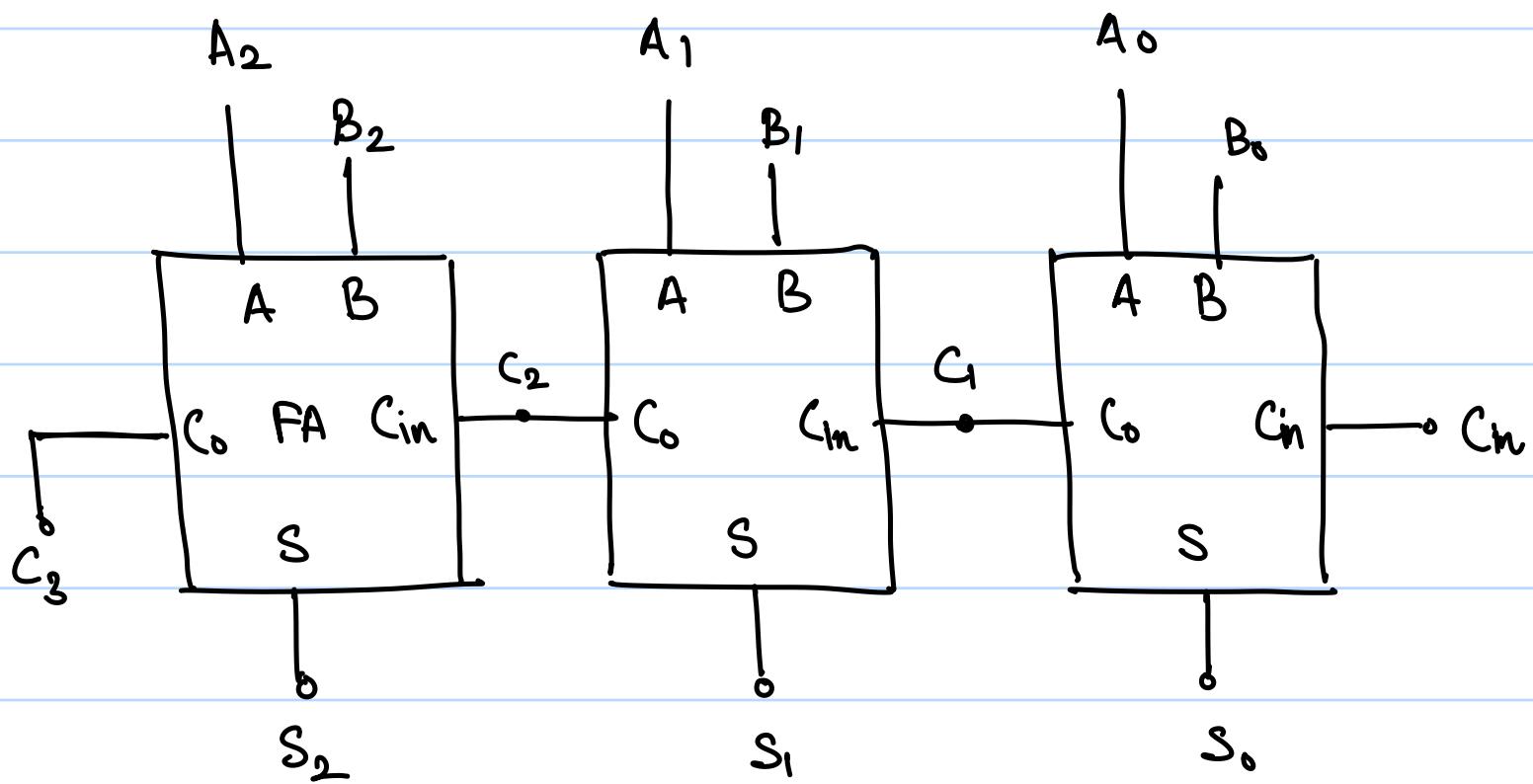
→ Full Adders:-



$$S = A \oplus B \oplus C$$

$$C = AB + BC + AC$$

→ Ripple Carry Adder :-



- Connection of n FAs to perform n -bit addition.

- Since it uses series-connection, propagation delay of the last S will be $n \times (t_{pd-FA})$.

→ Carry Lookahead Adder :-

- Uses the input signals A, B and Cin to generate all the carry signals required.

$$C_1 = \underbrace{A_0 B_0}_{C_0} + C_0 (A_0 + B_0)$$

$$C_2 = A_1 B_1 + C_1 (A_1 + B_1)$$

$$\begin{aligned} &= A_1 B_1 + A_1 A_0 B_0 + A_1 (A_0 + B_0) C_0 + B_1 A_0 B_0 \\ &\quad + B_1 C_0 (A_0 + B_0) \end{aligned}$$

:

• Benefit : Improved circuit speed due to lesser propagation delay.

• Drawback : Increased circuit complexity, input capacitance, etc.

→ Complementation Property :-

$$S = A \oplus B \oplus C$$

$$\bar{S} = \overline{A \oplus B \oplus C} = \bar{A} \oplus \bar{B} \oplus \bar{C}$$

$$C_{out} = AB + BC + AC$$

$$\bar{C}_{out} = \overline{AB + BC + AC} = \bar{A} \cdot \bar{B} + \bar{B} \cdot \bar{C} + \bar{A} \cdot \bar{C}$$

∴ If ilps are $\bar{A}, \bar{B}, \bar{C}$, o/p's are \bar{S}, \bar{C}_{out} .

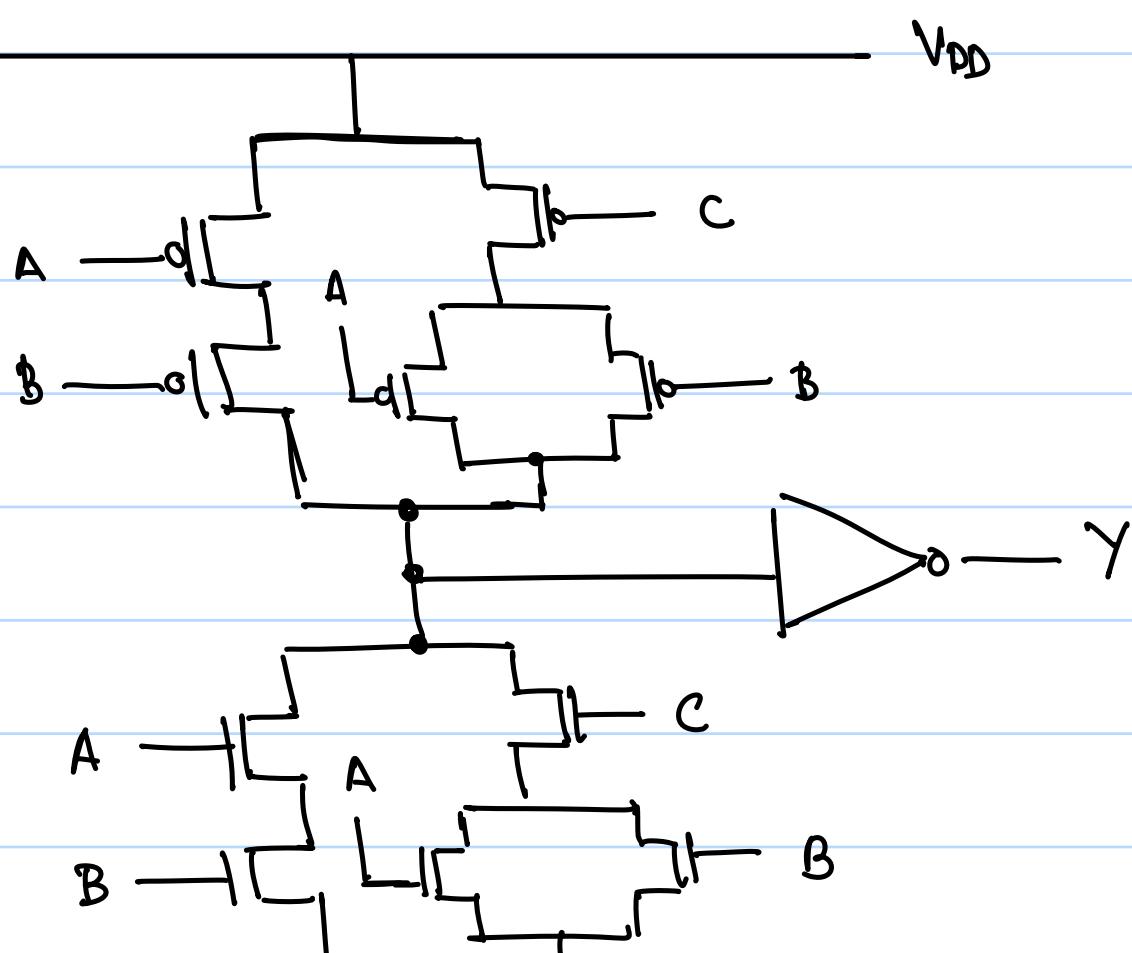
• Since in a CMOS implementation of the logic, we use complementary logic for the PMOS and NMOS networks, we can use the same configuration for both the PMOS and NMOS networks.

$$\rightarrow AB + C(A+B)$$

$$C_{out} = AB + BC + CA \longrightarrow \text{PDN}$$

$$\bar{C}_{out} = \bar{A}\bar{B} + \bar{B}\bar{C} + \bar{C}\bar{A} \longrightarrow \text{PUN}$$

$$\rightarrow \bar{A}\bar{B} + \bar{C}(\bar{A}+\bar{B})$$



This type of logic is termed as mirror gate. Such mirror gate can be used to reduce transistor stacking and maybe no. of transistors (reducing area required)

- The output inverter can be omitted from the carry output to reduce the delay on the critical path of the RCA (C_{in} to $S_n | C_{out}$)

Using the complementation property,

- Even bit adder : A, B, C_{in} as inputs
- Odd bit adder : $\bar{A}, \bar{B}, \bar{C}_{in}$ as inputs, also remove the op inverter of the S mirror gate.

→ Carry Lookahead Adder (2) :-

- CLA generates the carry signals directly from the input A, B, C_{in} signals.
- Carry Independent Terms :-

- Kill : $A_i = 0, B_i = 0$, then $C_{out} = 0$ for any C_{in} . This condition is represented as $\bar{A}_i \cdot \bar{B}_i$
- Generate : $A_i = 1, B_i = 1$, then $C_{out} = 1$ for any C_{in} . This condition is represented as $A_i \cdot B_i$.

3) Propagate: If $A_i = 0, B_i = 1$, or $A_i = 1, B_i = 0$, $C_{out} = 1$ iff $C_{in} = 1$. This condition is represented as $A_i \oplus B_i$. ($C_{out} = C_{in}$)

- Let the above be signals K, G, P respectively.

A	B	Condition
0	0	K
0	1	P
1	0	P
1	1	G

Only one is true at any time

If $K = 1, C_{out} = 0$

$G = 1, C_{out} = 1$

$P = 1, C_{out} = C_{in}$

We can also use an OR gate from P ($P = A + B$) since XOR can be shown, by ensuring that $C_{out} = 1$ irrespective of P when $G = 1$

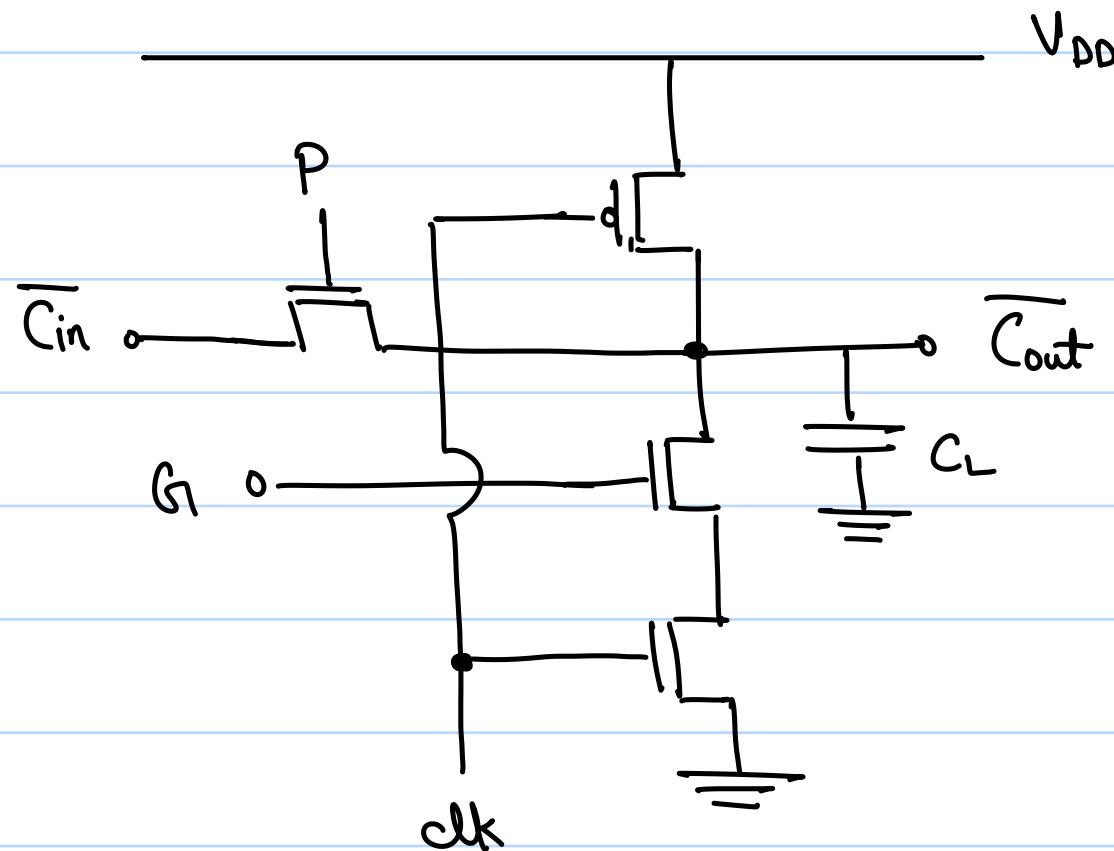
$$\Rightarrow C_{out} = G + P \cdot C_{in}$$

$$C_{i+1} = G_i + P_i C_i = G_i + P_i (G_{i-1} + P_{i-1} C_{i-1}) = \dots$$

$$\Rightarrow C_{i+1} = G_i + P_i G_{i-1} + P_i P_{i-1} G_{i-2} + \dots + P_i P_{i-1} \dots P_0 C_{in}$$

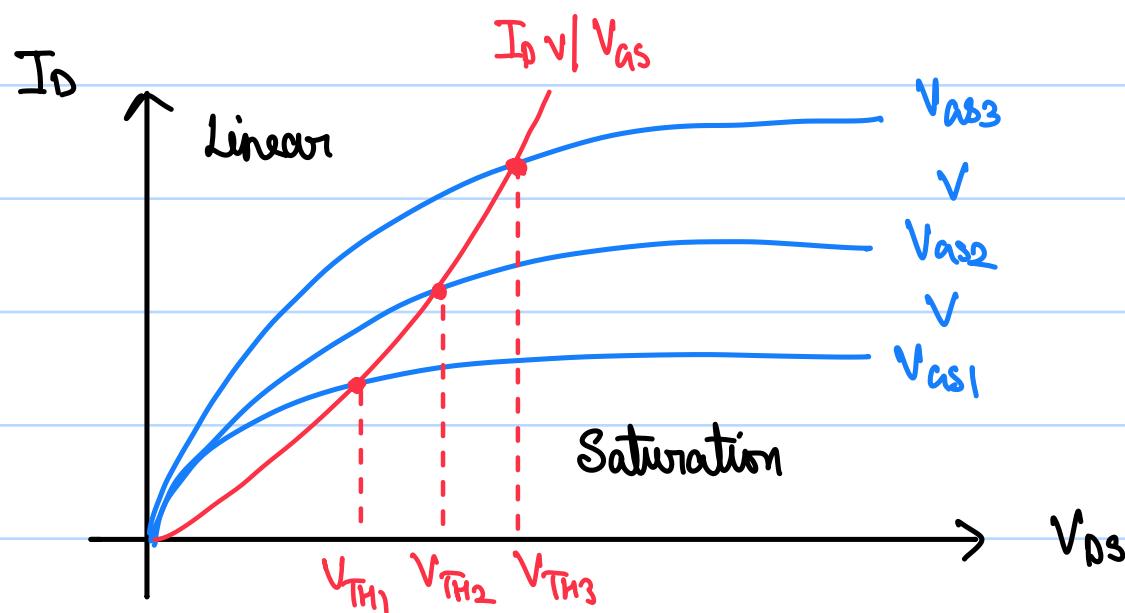
Therefore, without using the C_{out} of the FA, we can generate every carry signal independently, using only the input signals.

- But due to the high complexity of the functions for high-indexed carry signals, the delay saved might not be significant, in the static implementation atleast.
- In the dynamic implementation, the delay saved can be significant by using the Manchester Carry Chain.



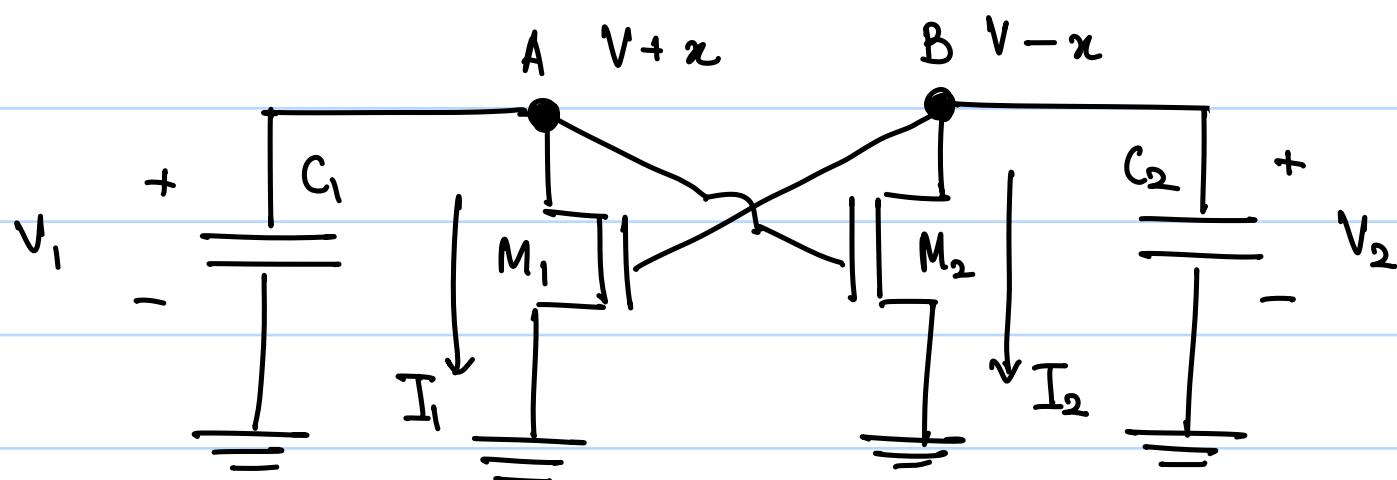
* Differential Circuits :-

- All the previously discussed circuits use the transistor as a switch.
- But we know that the transistor can be used for Analog applications (AEC)
- We know that a MOSFET can act as an Analog amplifier (with small signal approximation) in the saturation mode of operation (voltage-controlled current source)



In saturation, I_D is independent of V_{DS} , so the MOSFET becomes a V_{GS} controlled current source.

- Differential logic uses the amplification property to create digital circuits.



Say V_1, V_2 are the same voltage V such that M_1, M_2 are in saturation.

Because of noise, the voltages at A and B might be different.

$$I_1 = k(V+x - V_{TH})^2$$

$$I_2 = k(V-x - V_{TH})^2$$

Since $I_1 > I_2$, V_A will discharge faster than V_B .

As A and B discharge asymmetrically, the difference b/w V_A and V_B increase, which again increases the asymmetric charging.

$$I_1 = C_1 \frac{dV}{dt}, \quad I_2 = C_2 \frac{dV}{dt}$$

Let $C_1 = C_2$, then

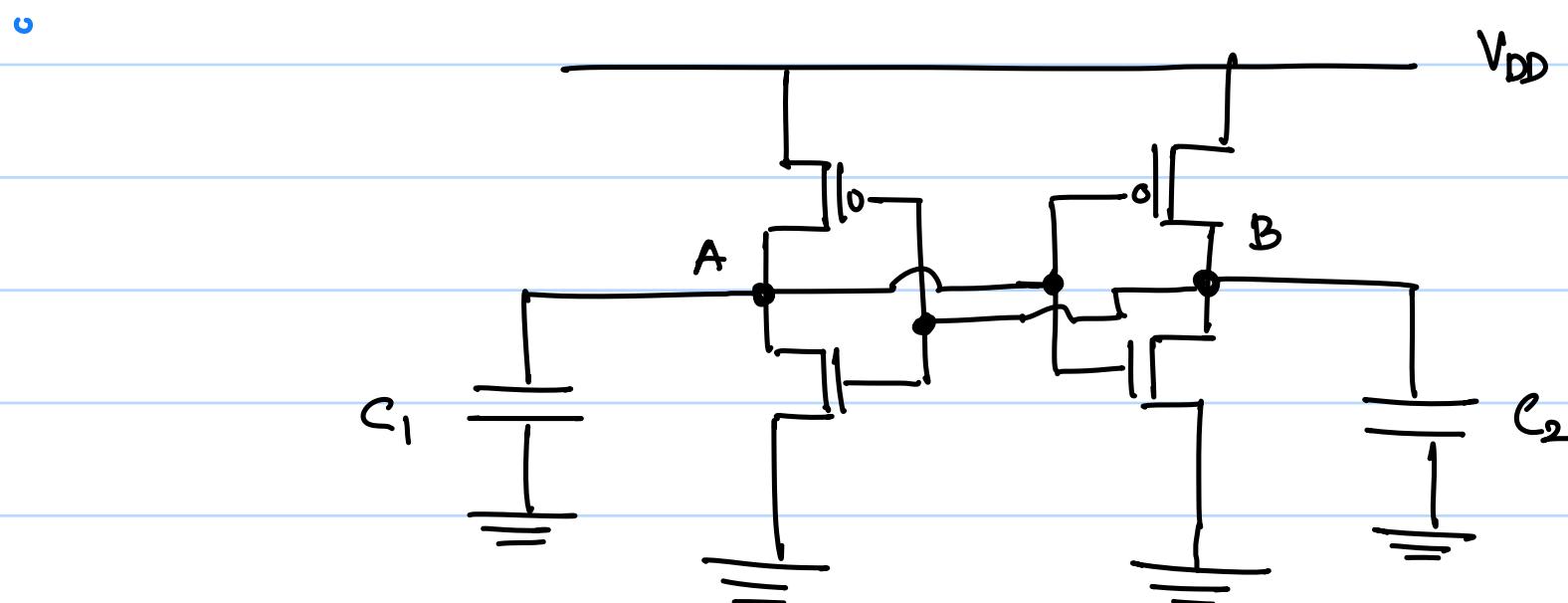
$$I_1 - I_2 = C \frac{d}{dt} (V_{IA} - V_{IB})$$

$$I_1 - I_2 = 2C \frac{dx}{dt}$$

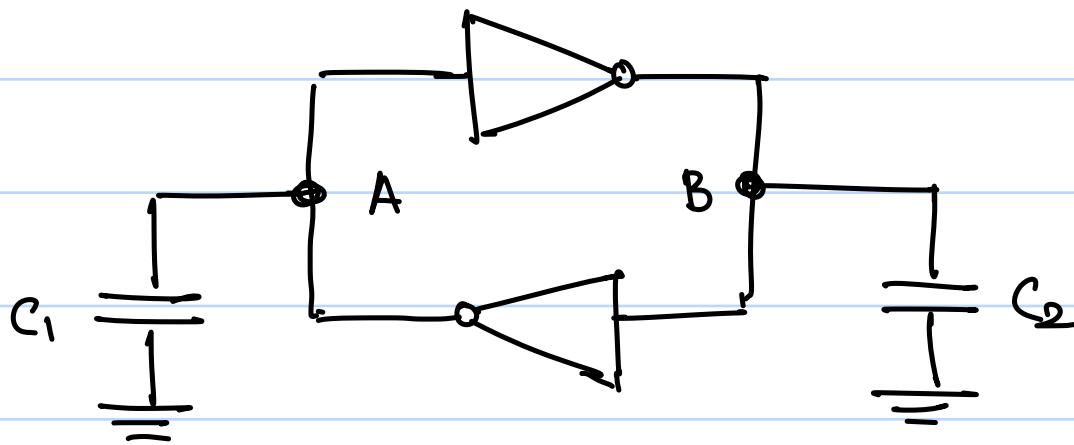
$$\begin{aligned} \Rightarrow k((V+x-V_{TH})^2 - (V-x-V_{TH})^2) &= 2C \frac{dx}{dt} \\ = k(((V-V_{TH})+x)^2 - ((V-V_{TH})-x)^2) &= 2C \frac{dx}{dt} \\ = \frac{1}{2}k(V-V_{TH})x &= 2C \frac{dx}{dt} \end{aligned}$$

$$\Rightarrow \frac{dx}{dt} = \frac{2k(V-V_{TH})}{C} x$$

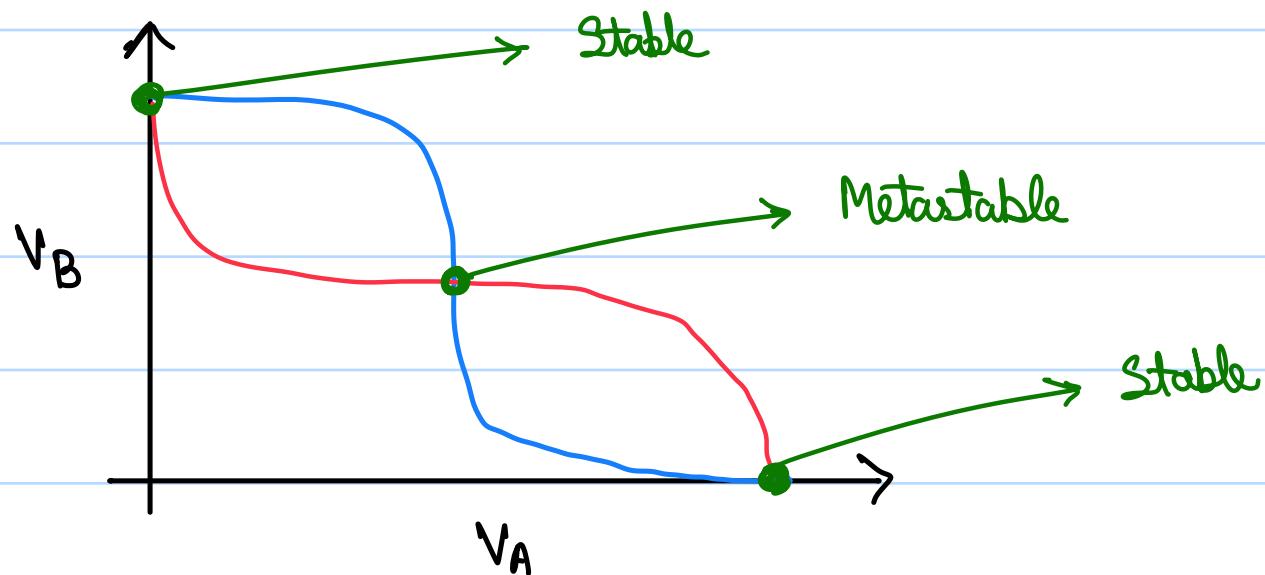
$$\Rightarrow x(t) = x_0 \exp\left(\frac{2k(V-V_{TH})}{C} t\right)$$



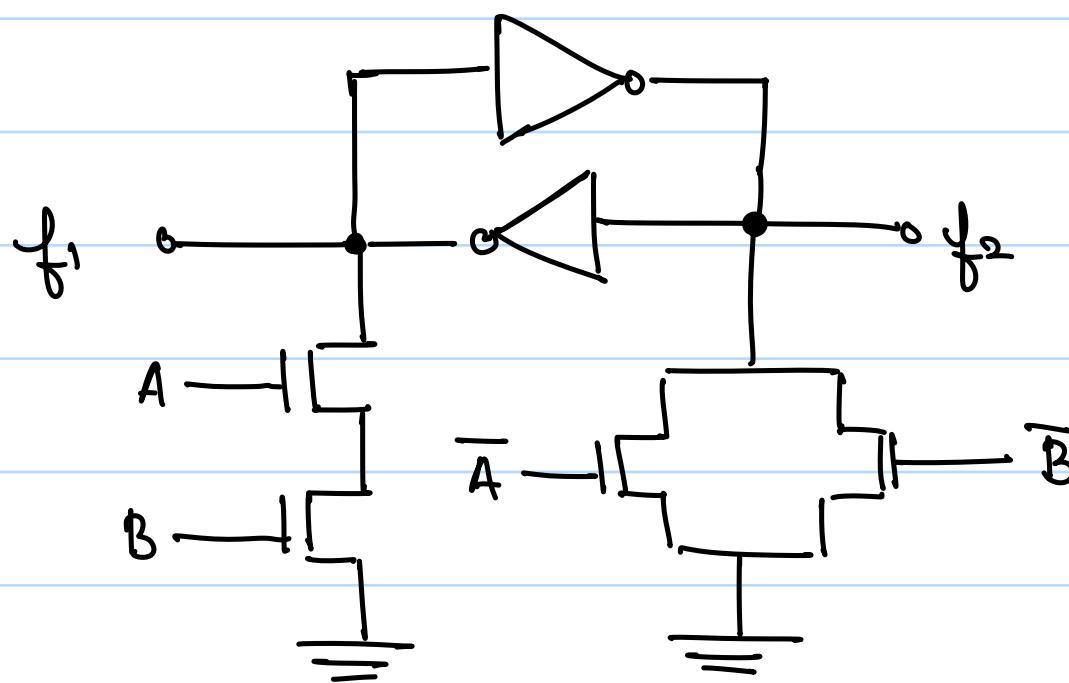
The above circuit is equivalent to connecting 2 inverters back to back



For the above circuit to be stable, either one of A and B should be V_{DD} and the other should be gnd, depending on the asymmetry in the node voltages of A and B.



- Say we have to implement $f = \overline{AB}$ (2ilp NAND)

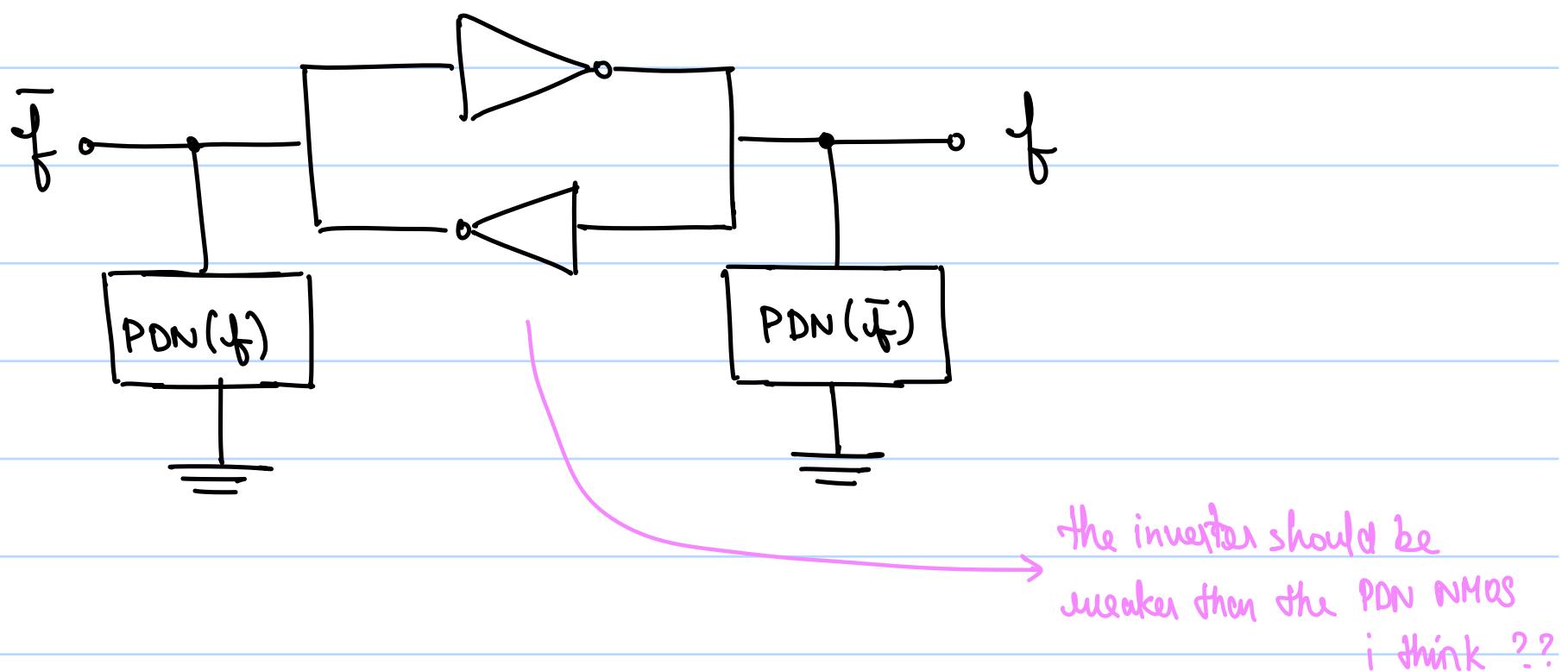


The node f_1 shows $\bar{A}\bar{B}$ and f_2 shows $\bar{A} + \bar{B} = AB$, ie f_1 and f_2 are complementary.

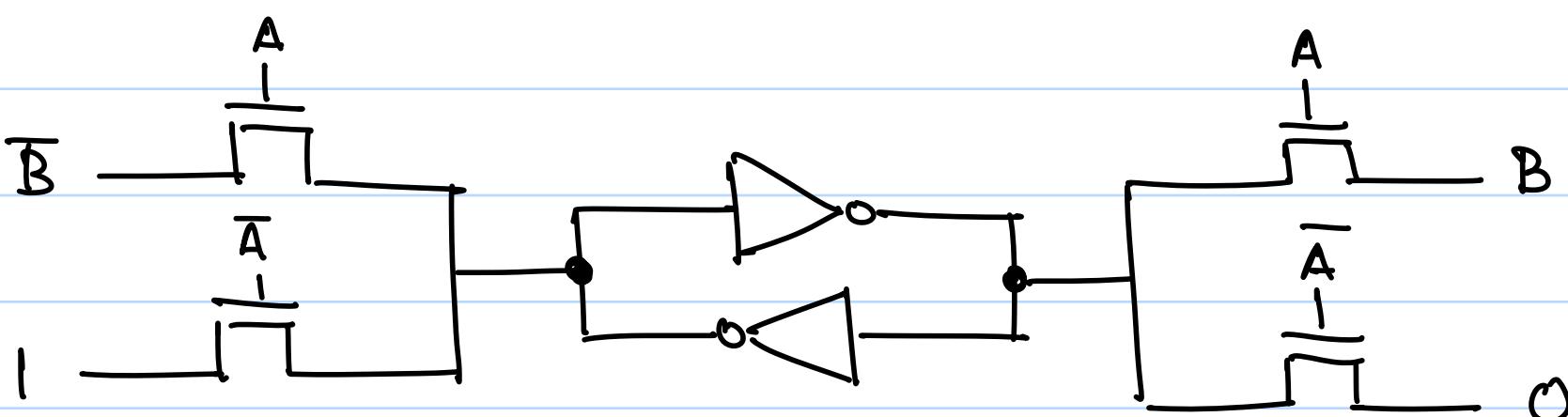
Since the NMOS networks for f_1 and f_2 are pull-down networks, there cannot pull the output node to VDD

But due to the complementary nature, the differential circuit will amplify the op to VDD and 0, giving us rail to rail outputs.

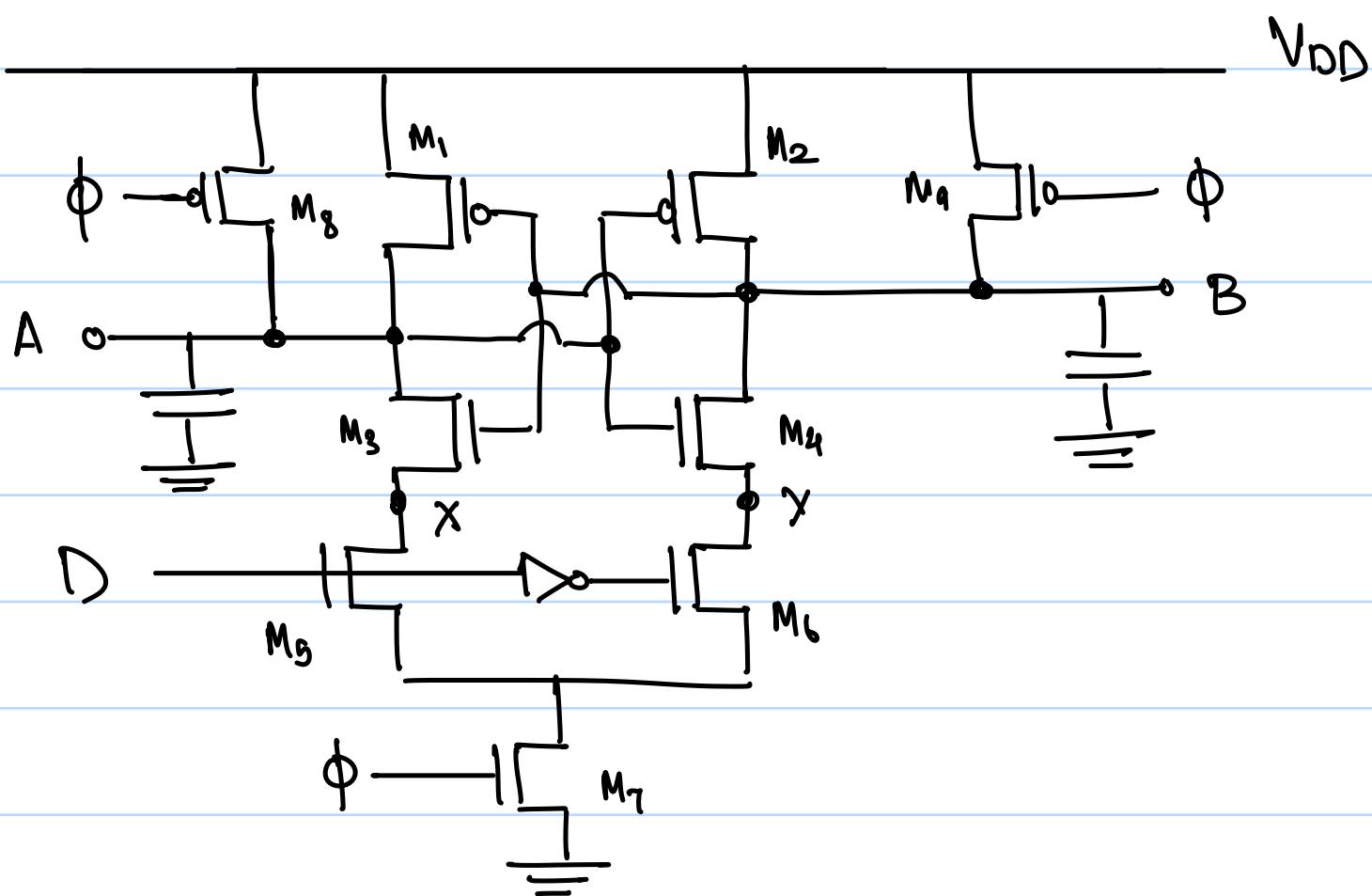
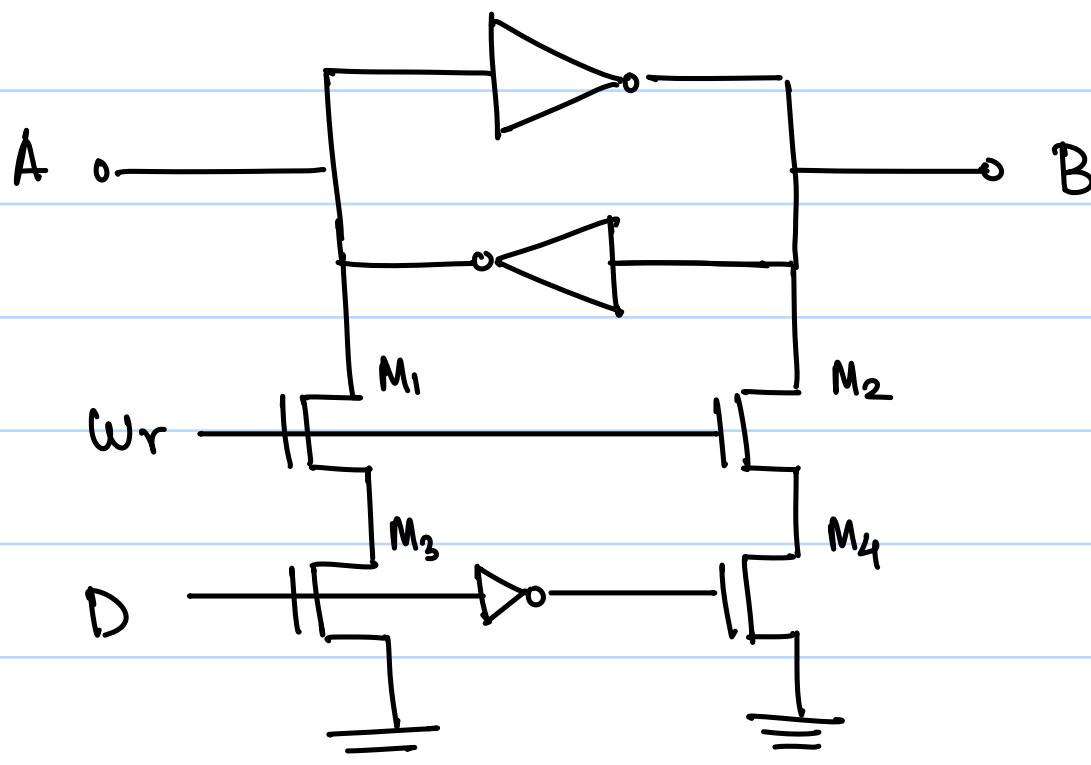
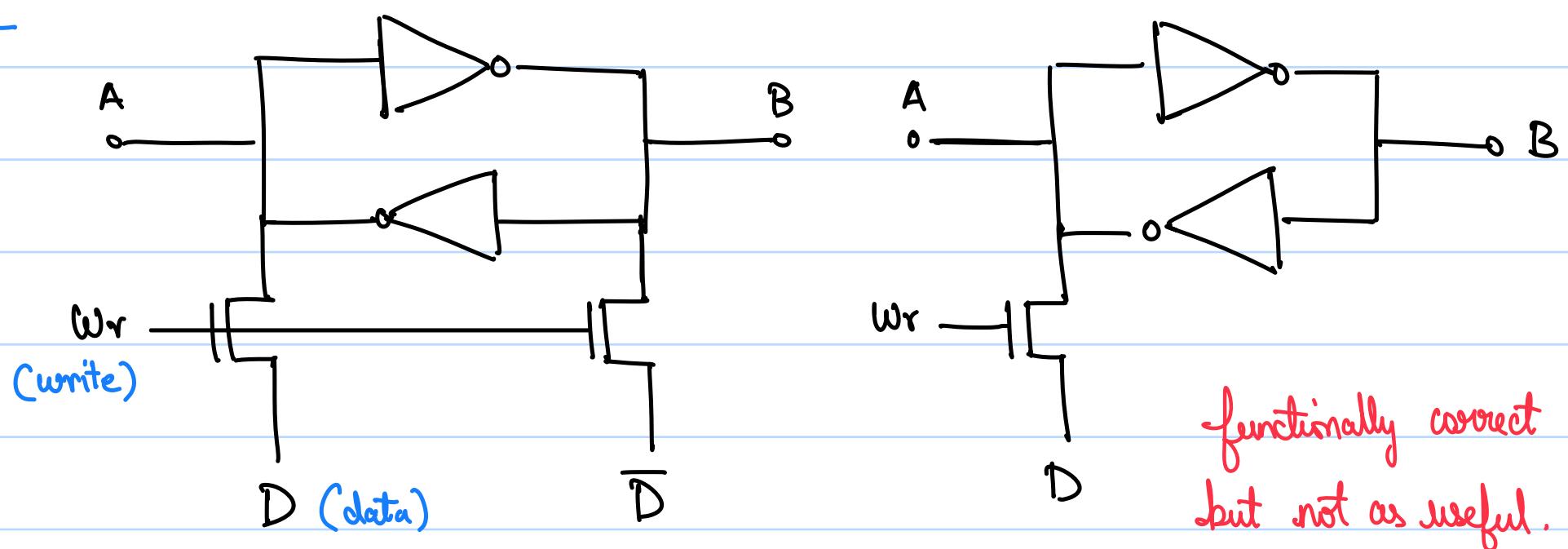
- In a nutshell, differential circuits greatly amplify the difference between 2 node voltages.



For the logic blocks, pass NMOS logic can also be used.



o Memory Element :-



The above is a clocked version of the previous variation.

If $\phi = 0$, $M_8 = M_9 = \text{ON}$
 $A = B = VDD$ (Porecharging)

If $\phi: 0 \rightarrow 1$,

1) $D = 1$,

$X = 0, Y = z$

$\Rightarrow A = 0, B = VDD$

2) $D: 1 \rightarrow 0$,

$X = z, Y = 0$

Right now, $A = 0, B = VDD$

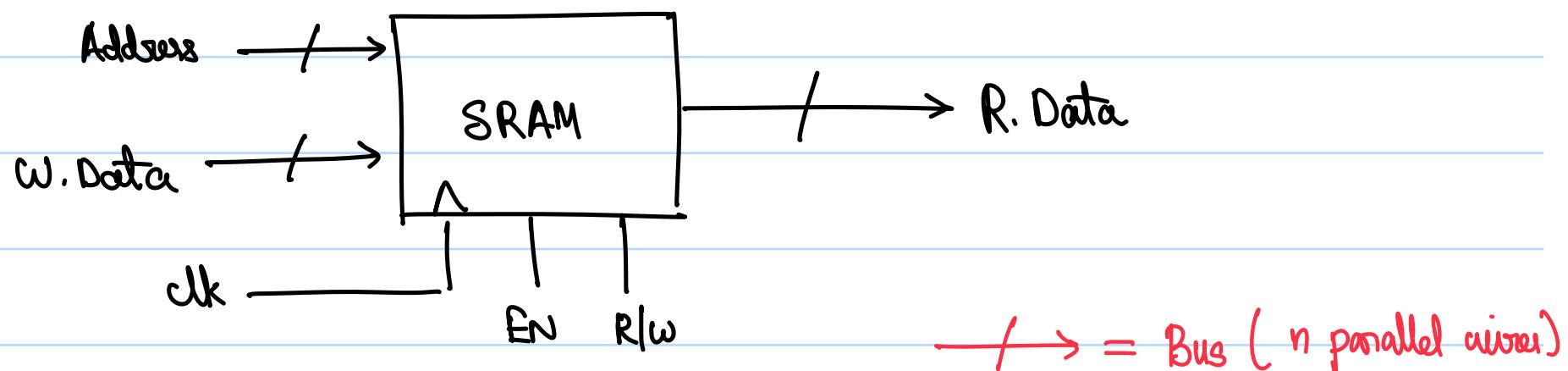
B cannot discharge since M_4 is OFF due to A

$\Rightarrow A = 0, B = VDD$ still

\therefore The device is edge triggered.

The above cell is an important part of SRAM devices.

→ Static Random Access Memory (SRAM) :-



RTL

↓
Register Transfer Logic

- SRAM stores n-bit words in multiple registers.
- Address - Encoded location of register.
- The buses require bus controllers to control the flow of data between the multiple devices connected to it.
- A basic SRAM cell is as follows,

